AUTOMATEC

UNILA
Universidade Federal
da Integração
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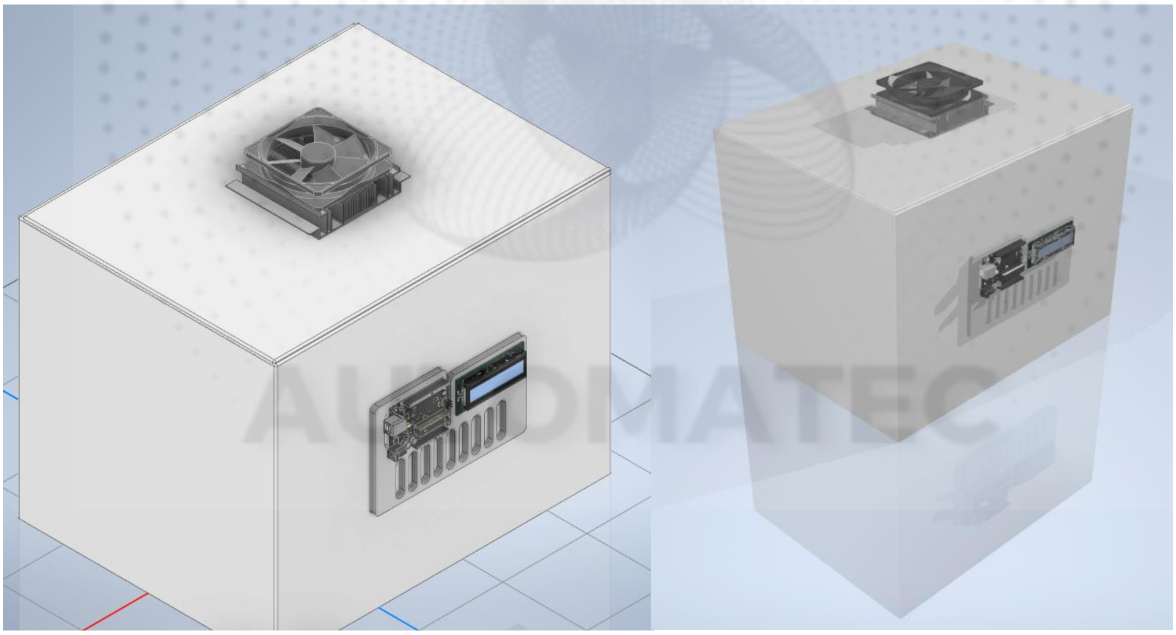
INSTITUTO LATINO-AMERICANO
DE CIÊNCIAS DA VIDA E DA NATUREZA
(ILACVN)
ENGENHARIA FÍSICA

MANUAL DE USO

MINIGELADEIRA PARA AMOSTRAS EM TEMPERATURA CONTROLADA



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Introdução: A mini geladeira para amostras com temperatura controlada é projetada para manter uma temperatura específica e estável, ideal para armazenar amostras sensíveis. Este manual descreve os componentes, o funcionamento e as etapas para configurar e usar a mini geladeira.

Componentes:

1. **LCD de 16 pinos:**
   - Exibe a temperatura interna e externa da mini geladeira.
   - Conectado ao Arduino UNO.
2. **Arduino UNO:**
   - Atua como o sistema de controle principal.
   - Coleta dados dos sensores e executa o código com os sistemas de Histerese e PID.
   - O sistema de Histerese controla o relé.
3. **Relé (duas saídas de 12V):**
   - Controla o tempo ligado e desligado do sistema de resfriamento.
   - O sistema de resfriamento inclui 2 coolers e 2 módulos Peltier.
4. **Cooler Interno com Dissipador de Calor Pequeno:**
   - Remove o calor gerado pelo sistema de resfriamento interno.
5. **Cooler Externo com Dissipador de Calor Grande:**
   - Dissipa o calor gerado pelo sistema de resfriamento externo.
6. **Sensor de Corrente:**
   - Monitora o consumo de corrente pelo sistema de resfriamento.
   - Detecta possíveis picos de corrente.
7. **Sensor de Temperatura LM35DZ:**
   - Mede a temperatura externa da caixa (temperatura ambiente).
8. **Sensor de Temperatura Termistor NPC de 10k:**
   - Mede a temperatura interna da caixa.
   - O usuário pode ajustar a temperatura desejada usando o potenciômetro de controle de temperatura de b50k.
   - O objetivo inicial é manter a temperatura em 6°C, com variação de 0,5°C.
9. **Potenciômetro de b50k para Ajuste de Temperatura:**
   - Permite ao usuário definir a temperatura desejada.
10. **Potenciômetro de b50k para Ajustar a Nitidez do LCD:**
    - Controla a nitidez e o contraste do display LCD.

Instruções de Uso:

1. **Ligando a Minigeladeira:**
   - Conecte a minigeladeira a uma fonte de alimentação adequada, entre 5v a 12v.
   - Ligue o Arduino UNO em uma fonte de 5v.
2. **Configuração Inicial:**

- Ajuste o potenciômetro de controle de temperatura para a temperatura desejada (por exemplo, 6°C).
    - Verifique se o LCD exibe a temperatura correta.
3. **Monitoramento:**
    - O LCD mostrará a temperatura interna e externa.
    - Monitore o consumo de corrente no sensor correspondente.
4. **Manutenção:**
    - Limpe os dissipadores de calor regularmente para garantir a eficiência do resfriamento.
    - Verifique os cabos e conexões para evitar falhas.
5. **Desligando a Minigeladeira:**
    - Desligue o Arduino UNO.
    - Desconecte a fonte de alimentação.

Explicação Detalhada do Código da Minigeladeira para Amostras com Temperatura Controlada

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Aqui está uma análise detalhada do código utilizado na minigeladeira para amostras com temperatura controlada:

1. **Declaração de Bibliotecas:**
    - `Wire.h`: Essa biblioteca é usada para comunicação I2C.
    - `LiquidCrystal_I2C.h`: Permite o controle de um display LCD via I2C.
    - `PID_v1.h`: Implementa o controle PID (Proporcional, Integral e Derivativo).
    - `Thermistor.h`: Facilita a leitura do sensor de temperatura NTC.
    - `EEPROM.h`: Permite o acesso à memória EEPROM do Arduino.
2. **Definições de Pinos:**
    - `ACS712_PIN`: Pino de entrada para o sensor de corrente ACS712.
    - `LM35_PIN`: Pino de entrada para o sensor de temperatura LM35.
    - `NTC_PIN`: Pino de entrada para o termistor NTC.
    - `RELAY_PIN`: Pino de saída para o controle do relé.
3. **Variáveis de Controle de Temperatura:**
    - `setpoint`: Representa a temperatura desejada.
    - `histerese`: Define a histerese de controle.
    - `input`, `output`: Variáveis utilizadas no cálculo do controle PID.
    - `temperature`: Armazena a leitura da temperatura.
4. **Configuração do LCD:**
    - Inicializa um objeto `LiquidCrystal_I2C` com endereço 0x27, 16 colunas e 2 linhas.
5. **Configuração do Termistor NTC:**
    - Define constantes e parâmetros para o cálculo da temperatura do termistor.
6. **Variáveis Globais:**
    - `Constante`: Constante para converter a leitura analógica em temperatura.
    - `Temperatura`: Variável que armazena a temperatura convertida.
    - `ValorAjustadoTemp`: Utilizada para ajustar a temperatura.
7. **Função `setup()`:**

    - Inicializa a comunicação serial e o LCD.
    - Define os pinos como entrada ou saída conforme necessário.
    - Configura o modo de controle PID.
8. **Função `loop()`:**
    - Realiza leituras dos sensores de corrente e temperatura.
    - Atualiza o controle PID com a temperatura lida do termistor NTC.
    - Controla o relé com base na saída do controle PID.
    - Exibe informações no LCD.
    - Envia dados pela porta serial.
    - Aguarda intervalos de tempo definidos.
9. **Funções de Leitura dos Sensores:**
    - `readCurrent()`: Lê a corrente do sensor ACS712.
    - `readTemperatureLM35()`: Obtém a temperatura do sensor LM35.
    - `readTemperatureNTC()`: Mede a temperatura do termistor NTC.
10. **Diagrama de Conexões:**

```
11. ACS712_PIN ---------- Sensor de Corrente ACS712
12. LM35_PIN   ---------- Sensor de Temperatura LM35
13. NTC_PIN    ---------- Termistor NTC de 10k
14. RELAY_PIN  ---------- Relé de Controle de Temperatura
```

Uso do LabVIEW para Armazenar Dados:

Para armazenar os dados coletados pelo sistema de controle de temperatura e corrente, você pode utilizar o LabVIEW, uma poderosa plataforma de programação gráfica amplamente utilizada para aquisição de dados, controle de instrumentos e análise de dados.

1. **Configuração Inicial:**
    - No LabVIEW, crie um novo projeto ou abra um projeto existente.
    - Adicione um novo VI (Virtual Instrument) para aquisição de dados.
2. **Comunicação Serial:**
    - Utilize a função "VISA Configure Serial Port" para configurar a comunicação serial com o Arduino.
    - Defina a taxa de transmissão (baud rate) e outros parâmetros conforme as configurações do Arduino.
3. **Leitura de Dados:**
    - Crie um loop que execute continuamente para ler os dados enviados pela porta serial.
    - Utilize a função "VISA Read" para receber os dados.
4. **Armazenamento em Arquivo:**
    - Crie um arquivo de texto (por exemplo, com extensão .txt) para armazenar os dados.
    - Utilize a função "Write to Text File" para escrever os dados no arquivo.
5. **Visualização e Análise:**
    - Utilize gráficos ou tabelas para visualizar os dados em tempo real.
    - Realize análises estatísticas ou outras operações conforme necessárias.

Código no Arduino para Salvar em TXT:

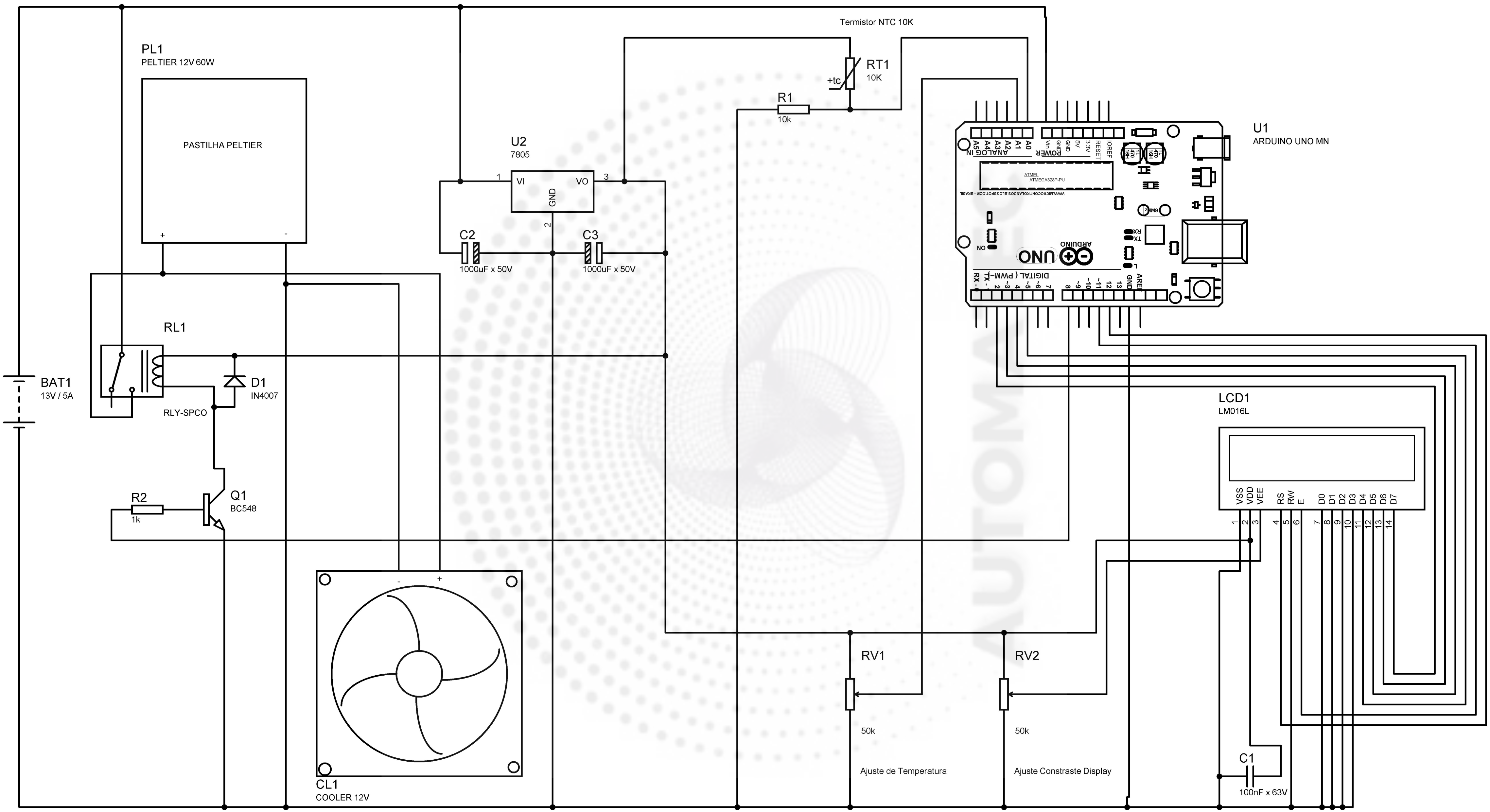
Você pode modificar o código do Arduino para salvar os dados diretamente em um arquivo de texto. Aqui está um exemplo de como fazer isso:

```
#include <SPI.h>
#include <SD.h>

File dataFile;

void setup() {
  // Inicialização do SD Card
  if (!SD.begin(10)) {
    // Falha na inicialização do SD Card
    while (1);
  }

  // Abre o arquivo para escrita
  dataFile = SD.open("dados.txt", FILE_WRITE);
  if (dataFile) {
    dataFile.println("Temp (C)\tCorrente (A)"); // Cabeçalho
    dataFile.close();
  }
}

void loop() {
  // Leitura dos sensores (exemplo)
  float temperatura = readTemperatureNTC();
  float corrente = readCurrent();

  // Abre o arquivo para adicionar dados
  dataFile = SD.open("dados.txt", FILE_WRITE);
  if (dataFile) {
    dataFile.print(temperatura);
    dataFile.print("\t");
    dataFile.println(corrente);
    dataFile.close();
  }

  // Outras operações do loop
  // ...
}
```

DATASHEET, DIAGRAMA DO CIRCUITO E CÓDIGO

O relatório do protótipo da versão atual 22/04/2024 está no link:
https://drive.google.com/file/d/1WfeyqRp_8tzKaITQu9t1O3Fxt2VZYYZq/view?usp=sharing

DIAGRAMA DE CIRCUITO ELÉCTRICO V. 01
AUTOMATEC - MINIGELADEIRA



DRAWN Bruno H. D. Macedo	21/04/2024	Automatec Engenharia Física	
CHECKED Renata Benedet	21/04/2024	TITLE	
QA		Minigeladeira para Amostras em temperatura controlada	
MFG Felipe Camargo	21/04/2024		
APPROVED Bruno Macedo	21/04/2024		
		SIZE D	DWG NO 213131	REV 2544
		SCALE 1 / 2	SHEET 1 OF 1

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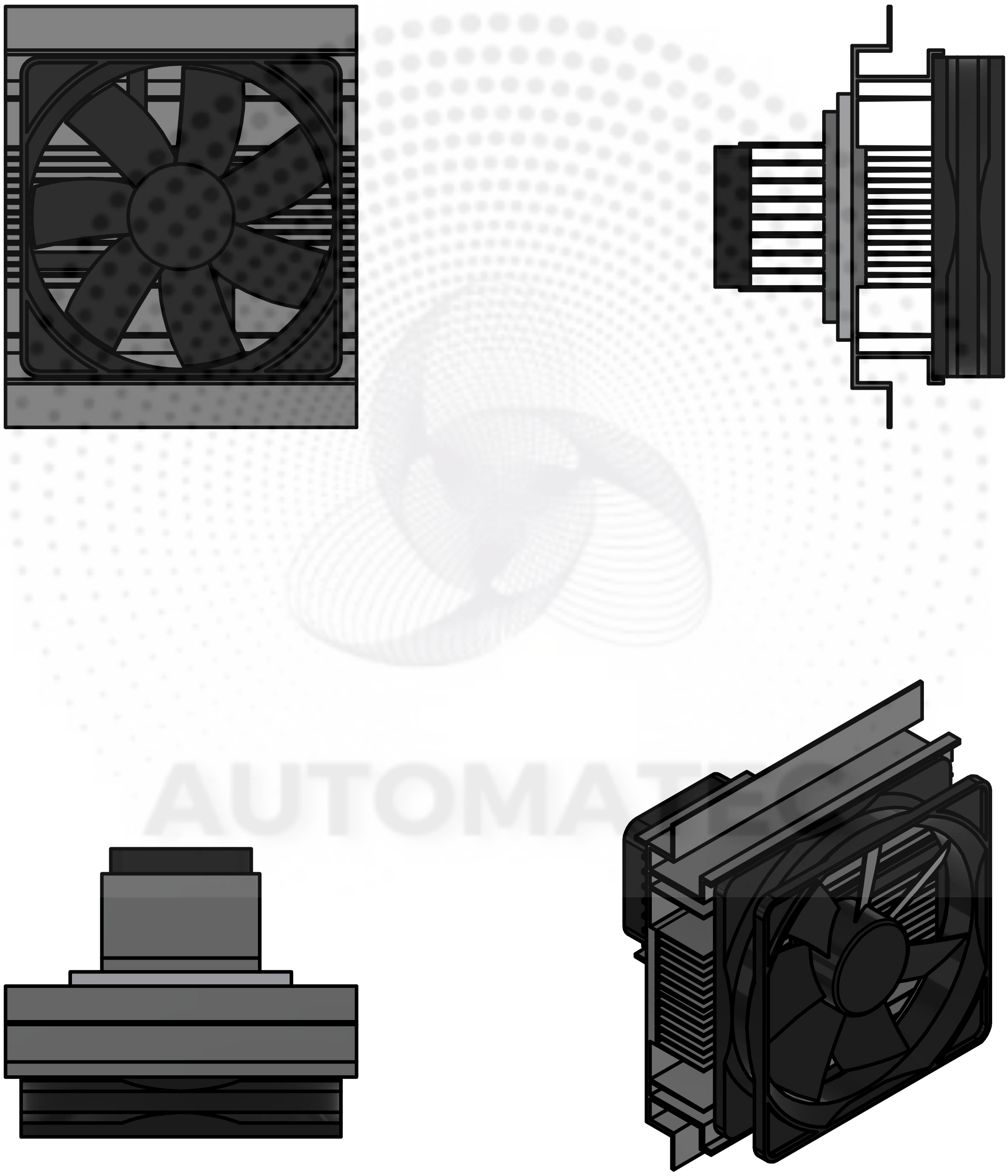
LISTA DE PEÇAS		
ITEM	QTDE	NÚMERO DA PEÇA
1	2	Peltier DE 90W
1	1	Cooler Grande
1	1	Cooler Pequeno



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Projetado por	Verificado por	Aprovado por	Data	Data	
Bruno Macedo	Renata O. B.	Bruno H. D. Macedo		21/04/2024	

		Edição	Folha
BFR	Sistema de Resfriamento	2024.1	1 / 1

```
#include <Wire.h>
#include <LiquidCrystal_I2C.h>
#include <PID_v1.h>
#include <Thermistor.h>
#include <EEPROM.h>

// Definições para o LCD com PCF8574T
#define I2C_ADDR_LCD 0x27 // Endereço do display LCD

// Definições para o sensor de corrente ACS712
#define ACS712_PIN A0

// Definições para o sensor de temperatura LM35
#define LM35_PIN A1

// Definições para o termistor de 10k
#define THERMISTOR_PIN A2

// Definições para o relé
#define RELAY_PIN 4

// Variáveis para o controle de temperatura
double setpoint = 6.0;  // Temperatura desejada
double histerese = 0.5; // Histerese de controle
double input, output, temperature;
PID pid(&input, &output, &setpoint, 1, 1, 1, DIRECT); // Parâmetros do PID
// Configuração do LCD
LiquidCrystal_I2C lcd(0x27, 2, 1, 0, 4, 5, 6, 7, 3, POSITIVE); //ENDEREÇO DO I2C E DEMAIS INFORMAÇÕES

//============================ Declarando Variáveis Globais ==========================//
float Constante = 51.15; // Constante para estabelecer a faixa de temperatura de 0 à 20 Graus / 1023/20 = 51.15.
float Temperatura;        // Variável que recebe o valor convertido para temperatura.
int ValorAjustadoTemp = 0;

//========================= Array que desenha o simbolo de grau ======================//
byte a[8] = {B00110, B01001, B00110, B00000, B00000, B00000, B00000, B00000,};
```

```
//========================= Criando o objeto para o termistor =====================//
Thermistor temp(THERMISTOR_PIN);

void setup() {
  Serial.begin(9600); // Inicializa a comunicação serial

  lcd.begin(16, 2); //SETA A QUANTIDADE DE COLUNAS(16) E O NÚMERO DE LINHAS(2) DO DISPLAY
  lcd.setBacklight(HIGH); //LIGA O BACKLIGHT (LUZ DE FUNDO)

  // Inicialização do sensor de corrente
  pinMode(ACS712_PIN, INPUT);

  // Inicialização do sensor de temperatura LM35
  pinMode(LM35_PIN, INPUT);

  // Inicialização do termistor
  pinMode(THERMISTOR_PIN, INPUT);

  // Inicialização do relé
  pinMode(RELAY_PIN, OUTPUT);

  // Inicialização do PID
  pid.SetMode(AUTOMATIC);
}

void loop() {
  // Leitura dos sensores
  double current = readCurrent();
  double temperatureLM35 = readTemperatureLM35();
  double temperatureThermistor = readTemperatureThermistor();

  // Atualização do PID
  input = temperatureThermistor;
  pid.Compute();
```

```
// Controle do relé
if (output > 0) {
  digitalWrite(RELAY_PIN, HIGH); // Liga o relé
} else {
  digitalWrite(RELAY_PIN, LOW); // Desliga o relé
}

// Exibir informações no LCD
lcd.clear();
lcd.setCursor(0, 0); //SETA A POSIÇÃO DO CURSOR
lcd.print(" BILIVOLTs 2.0 "); //IMPRIME O TEXTO NO DISPLAY LCD
lcd.setCursor(0, 1); //SETA A POSIÇÃO DO CURSOR
lcd.print("----------------"); //SEQUÊNCIA DE ESPAÇOS
delay(2000); //INTERVALO DE 2 SEGUNDOS
lcd.setCursor(0, 0); //SETA A POSIÇÃO DO CURSOR
lcd.print("TEMP IN: "); //IMPRIME O TEXTO NO DISPLAY LCD
lcd.print(temperatureThermistor);
lcd.print(" C");
lcd.setCursor(0, 1);
lcd.print("Corrente: ");
lcd.print(current);
lcd.print(" A");
delay(2000); //INTERVALO DE 2 SEGUNDOS
lcd.setCursor(0, 0); //SETA A POSIÇÃO DO CURSOR
lcd.print("TEMP FORA: "); //IMPRIME O TEXTO NO DISPLAY LCD
lcd.print(temperatureLM35);
lcd.print(" C");
lcd.setCursor(0, 1);
lcd.print("Corrente: ");
lcd.print(current);
lcd.print(" A");
delay(2000); //INTERVALO DE 2 SEGUNDOS
lcd.setCursor(0, 0); //SETA A POSIÇÃO DO CURSOR
lcd.print("                "); //SEQUÊNCIA DE ESPAÇOS
lcd.setCursor(0, 0); //SETA A POSIÇÃO DO CURSOR
lcd.print("   GRUPO BFR!  "); //IMPRIME O TEXTO NO DISPLAY LCD
```

```
  lcd.setCursor(0, 1);
  lcd.print("  2024  "); //IMPRIME O TEXTO NO DISPLAY LCD
  lcd.setCursor(0, 1); //SETA A POSIÇÃO DO CURSOR
  lcd.print("                "); //SEQUÊNCIA DE ESPAÇOS
  delay(3000); // Aguarda 1 segundo antes de atualizar o LCD

  // Envio dos dados pela porta serial
  Serial.print("Temperatura Thermistor: ");
  Serial.print(temperatureThermistor);
  Serial.print(" C, Corrente: ");
  Serial.print(current);
  Serial.print(" A, Temperatura LM35: ");
  Serial.print(temperatureLM35);
  Serial.println(" C");
  delay(2000); // Aguarda 2 segundos antes de enviar o próximo conjunto de dados
}

// Função para ler a corrente do sensor ACS712
double readCurrent() {
  int sensorValue = analogRead(ACS712_PIN);
  double current = (sensorValue - 512) / 102.3; // Ajuste para converter a leitura em amperes
  return current;
}

// Função para ler a temperatura do sensor LM35
double readTemperatureLM35() {
  int sensorValue = analogRead(LM35_PIN);
  double temperature = (sensorValue * 5.0) / 1023.0 * 100.0; // Ajuste para converter a leitura em graus Celsius
  return temperature;
}

// Função para ler a temperatura do termistor de 10k
double readTemperatureThermistor() {
  double temperature = temp.getTemp(); // Utiliza a biblioteca Thermistor.h para obter a temperatura
  return temperature;
}
```

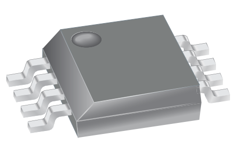
Fully Integrated, Hall Effect-Based Linear Current Sensor with 2.1 kVRMS Voltage Isolation and a Low-Resistance Current Conductor

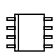
Features and Benefits

- Low-noise analog signal path
- Device bandwidth is set via the new FILTER pin
- 5 µs output rise time in response to step input current
- 80 kHz bandwidth
- Total output error 1.5% at T_A= 25°C
- Small footprint, low-profile SOIC8 package
- 1.2 mΩ internal conductor resistance
- 2.1 kV_{RMS} minimum isolation voltage from pins 1-4 to pins 5-8
- 5.0 V, single supply operation
- 66 to 185 mV/A output sensitivity
- Output voltage proportional to AC or DC currents
- Factory-trimmed for accuracy
- Extremely stable output offset voltage
- Nearly zero magnetic hysteresis
- Ratiometric output from supply voltage

TÜV America
Certificate Number:
U8V 06 05 54214 010

Package: 8 Lead SOIC (suffix LC)



Approximate Scale 1:1 

Description

The Allegro® ACS712 provides economical and precise solutions for AC or DC current sensing in industrial, commercial, and communications systems. The device package allows for easy implementation by the customer. Typical applications include motor control, load detection and management, switched-mode power supplies, and overcurrent fault protection.

The device consists of a precise, low-offset, linear Hall sensor circuit with a copper conduction path located near the surface of the die. Applied current flowing through this copper conduction path generates a magnetic field which is sensed by the integrated Hall IC and converted into a proportional voltage. Device accuracy is optimized through the close proximity of the magnetic signal to the Hall transducer. A precise, proportional voltage is provided by the low-offset, chopper-stabilized BiCMOS Hall IC, which is programmed for accuracy after packaging.

The output of the device has a positive slope (>$V_{IOUT(Q)}$) when an increasing current flows through the primary copper conduction path (from pins 1 and 2, to pins 3 and 4), which is the path used for current sensing. The internal resistance of this conductive path is 1.2 mΩ typical, providing low power

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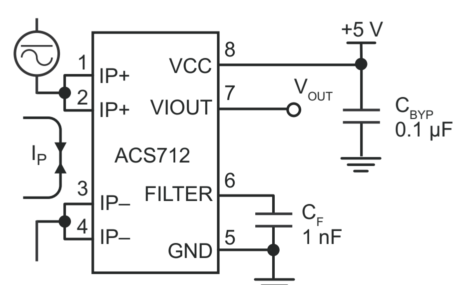
Typical Application



Application 1. The ACS712 outputs an analog signal, V_{OUT}. that varies linearly with the uni- or bi-directional AC or DC primary sensed current, I_P, within the range specified. C_F is recommended for noise management, with values that depend on the application.

Description (continued)

loss. The thickness of the copper conductor allows survival of the device at up to 5× overcurrent conditions. The terminals of the conductive path are electrically isolated from the sensor leads (pins 5 through 8). This allows the ACS712 current sensor to be used in applications requiring electrical isolation without the use of opto-isolators or other costly isolation techniques.

The ACS712 is provided in a small, surface mount SOIC8 package. The leadframe is plated with 100% matte tin, which is compatible with standard lead (Pb) free printed circuit board assembly processes. Internally, the device is Pb-free, except for flip-chip high-temperature Pb-based solder balls, currently exempt from RoHS. The device is fully calibrated prior to shipment from the factory.

Selection Guide

Part Number	Packing*	T_A (°C)	Optimized Range, I_P (A)	Sensitivity, Sens (Typ) (mV/A)
ACS712ELCTR-05B-T	Tape and reel, 3000 pieces/reel	–40 to 85	±5	185
ACS712ELCTR-20A-T	Tape and reel, 3000 pieces/reel	–40 to 85	±20	100
ACS712ELCTR-30A-T	Tape and reel, 3000 pieces/reel	–40 to 85	±30	66

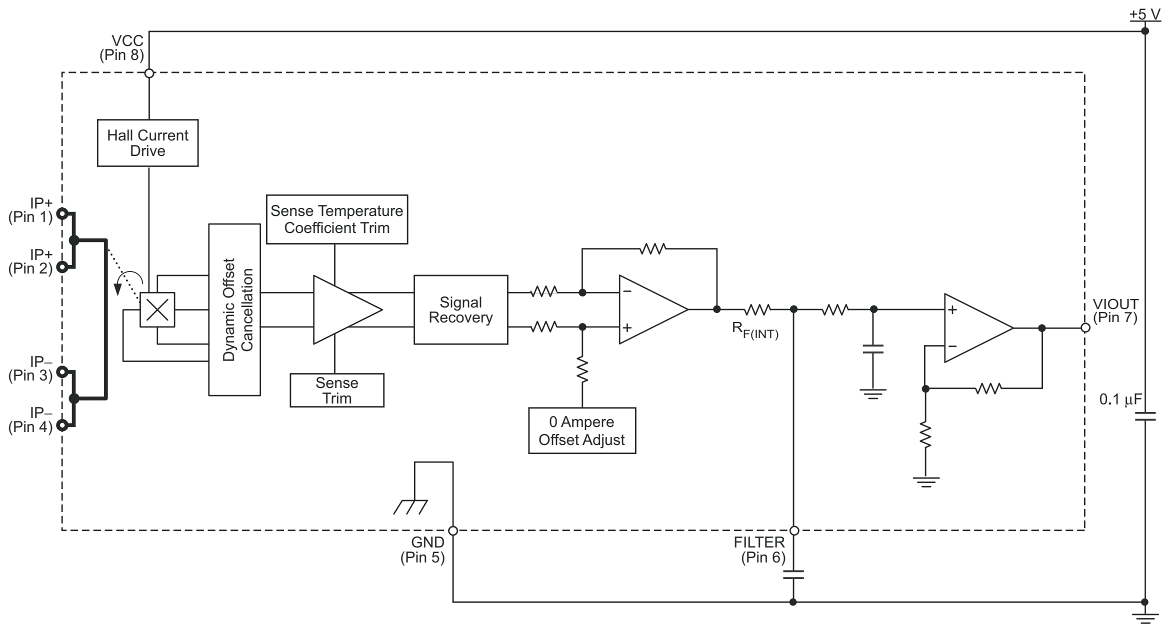
*Contact Allegro for additional packing options.

Absolute Maximum Ratings

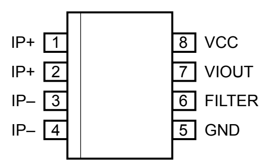
Characteristic	Symbol	Notes	Rating	Units
Supply Voltage	V_{CC}		8	V
Reverse Supply Voltage	V_{RCC}		–0.1	V
Output Voltage	V_{IOUT}		8	V
Reverse Output Voltage	V_{RIOUT}		–0.1	V
Reinforced Isolation Voltage	V_{ISO}	Pins 1-4 and 5-8; 60 Hz, 1 minute, T_A=25°C	2100	V
		Voltage applied to leadframe (Ip+ pins), based on IEC 60950	184	V_{peak}
Basic Isolation Voltage	$V_{ISO(bsc)}$	Pins 1-4 and 5-8; 60 Hz, 1 minute, T_A=25°C	1500	V
		Voltage applied to leadframe (Ip+ pins), based on IEC 60950	354	V_{peak}
Output Current Source	$I_{IOUT(Source)}$		3	mA
Output Current Sink	$I_{IOUT(Sink)}$		10	mA
Overcurrent Transient Tolerance	I_P	1 pulse, 100 ms	100	A
Nominal Operating Ambient Temperature	T_A	Range E	–40 to 85	ºC
Maximum Junction Temperature	T_J(max)		165	ºC
Storage Temperature	T_{stg}		–65 to 170	ºC

Parameter	Specification
Fire and Electric Shock	CAN/CSA-C22.2 No. 60950-1-03 UL 60950-1:2003 EN 60950-1:2001

Functional Block Diagram



Pin-out Diagram



Terminal List Table

Number	Name	Description
1 and 2	IP+	Terminals for current being sensed; fused internally
3 and 4	IP–	Terminals for current being sensed; fused internally
5	GND	Signal ground terminal
6	FILTER	Terminal for external capacitor that sets bandwidth
7	VIOUT	Analog output signal
8	VCC	Device power supply terminal

COMMON OPERATING CHARACTERISTICS[1] over full range of T_A, C_F = 1 nF, and V_{CC} = 5 V, unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Typ.	Max.	Units
ELECTRICAL CHARACTERISTICS						
Supply Voltage	V_{CC}		4.5	5.0	5.5	V
Supply Current	I_{CC}	V_{CC} = 5.0 V, output open	–	10	13	mA
Output Capacitance Load	C_{LOAD}	VIOUT to GND	–	–	10	nF
Output Resistive Load	R_{LOAD}	VIOUT to GND	4.7	–	–	kΩ
Primary Conductor Resistance	$R_{PRIMARY}$	T_A = 25°C	–	1.2	–	mΩ
Rise Time	t_r	$I_P = I_P(max)$, T_A = 25°C, C_{OUT} = open	–	5	–	μs
Frequency Bandwidth	f	–3 dB, T_A = 25°C; I_P is 10 A peak-to-peak	–	80	–	kHz
Nonlinearity	E_{LIN}	Over full range of I_P	–	1.5	–	%
Symmetry	E_{SYM}	Over full range of I_P	98	100	102	%
Zero Current Output Voltage	$V_{IOUT(Q)}$	Bidirectional; I_P = 0 A, T_A = 25°C	–	V_{CC} × 0.5	–	V
Power-On Time	t_{PO}	Output reaches 90% of steady-state level, T_J = 25°C, 20 A present on leadframe	–	35	–	μs
Magnetic Coupling[2]			–	12	–	G/A
Internal Filter Resistance[3]	$R_{F(INT)}$			1.7		kΩ

[1]Device may be operated at higher primary current levels, I_P, and ambient, T_A, and internal leadframe temperatures, T_A, provided that the Maximum Junction Temperature, T_J(max), is not exceeded.

[2]1G = 0.1 mT.

[3]$R_{F(INT)}$ forms an RC circuit via the FILTER pin.

COMMON THERMAL CHARACTERISTICS[1]

			Min.	Typ.	Max.	Units
Operating Internal Leadframe Temperature	T_A	E range	–40	–	85	°C
					Value	Units
Junction-to-Lead Thermal Resistance[2]	$R_{\theta JL}$	Mounted on the Allegro ASEK 712 evaluation board			5	°C/W
Junction-to-Ambient Thermal Resistance	$R_{\theta JA}$	Mounted on the Allegro 85-0322 evaluation board, includes the power consumed by the board			23	°C/W

[1]Additional thermal information is available on the Allegro website.

[2]The Allegro evaluation board has 1500 mm^2 of 2 oz. copper on each side, connected to pins 1 and 2, and to pins 3 and 4, with thermal vias connecting the layers. Performance values include the power consumed by the PCB. Further details on the board are available from the Frequently Asked Questions document on our website. Further information about board design and thermal performance also can be found in the Applications Information section of this datasheet.

x05B PERFORMANCE CHARACTERISTICS T_A = –40°C to 85°C[1], C_F = 1 nF, and V_{CC} = 5 V, unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Optimized Accuracy Range	I_P		–5	–	5	A
Sensitivity	Sens	Over full range of I_P, T_A = 25°C	180	185	190	mV/A
Noise	$V_{NOISE(PP)}$	Peak-to-peak, T_A = 25°C, 185 mV/A programmed Sensitivity, C_F = 47 nF, C_{OUT} = open, 2 kHz bandwidth	–	21	–	mV
Zero Current Output Slope	$\Delta I_{OUT(Q)}$	T_A = –40°C to 25°C	–	–0.26	–	mV/°C
		T_A = 25°C to 150°C	–	–0.08	–	mV/°C
Sensitivity Slope	ΔSens	T_A = –40°C to 25°C	–	0.054	–	mV/A/°C
		T_A = 25°C to 150°C	–	–0.008	–	mV/A/°C
Total Output Error[2]	E_{TOT}	I_P =±5 A, T_A = 25°C	–	±1.5	–	%

[1]Device may be operated at higher primary current levels, I_P, and ambient temperatures, T_A, provided that the Maximum Junction Temperature, $T_{J(max)}$, is not exceeded.

[2]Percentage of I_P, with I_P = 5 A. Output filtered.

x20A PERFORMANCE CHARACTERISTICS T_A = –40°C to 85°C[1], C_F = 1 nF, and V_{CC} = 5 V, unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Optimized Accuracy Range	I_P		–20	–	20	A
Sensitivity	Sens	Over full range of I_P, T_A = 25°C	96	100	104	mV/A
Noise	$V_{NOISE(PP)}$	Peak-to-peak, T_A = 25°C, 100 mV/A programmed Sensitivity, C_F = 47 nF, C_{OUT} = open, 2 kHz bandwidth	–	11	–	mV
Zero Current Output Slope	$\Delta I_{OUT(Q)}$	T_A = –40°C to 25°C	–	–0.34	–	mV/°C
		T_A = 25°C to 150°C	–	–0.07	–	mV/°C
Sensitivity Slope	ΔSens	T_A = –40°C to 25°C	–	0.017	–	mV/A/°C
		T_A = 25°C to 150°C	–	–0.004	–	mV/A/°C
Total Output Error[2]	E_{TOT}	I_P =±20 A, T_A = 25°C	–	±1.5	–	%

[1]Device may be operated at higher primary current levels, I_P, and ambient temperatures, T_A, provided that the Maximum Junction Temperature, T_J(max), is not exceeded.

[2]Percentage of I_P, with I_P = 20 A. Output filtered.

x30A PERFORMANCE CHARACTERISTICS T_A = –40°C to 85°C[1], C_F = 1 nF, and V_{CC} = 5 V, unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Optimized Accuracy Range	I_P		–30	–	30	A
Sensitivity	Sens	Over full range of I_P, T_A = 25°C	64	66	68	mV/A
Noise	$V_{NOISE(PP)}$	Peak-to-peak, T_A = 25°C, 66 mV/A programmed Sensitivity, C_F = 47 nF, C_{OUT} = open, 2 kHz bandwidth	–	7	–	mV
Zero Current Output Slope	$\Delta I_{OUT(Q)}$	T_A = –40°C to 25°C	–	–0.35	–	mV/°C
		T_A = 25°C to 150°C	–	–0.08	–	mV/°C
Sensitivity Slope	ΔSens	T_A = –40°C to 25°C	–	0.007	–	mV/A/°C
		T_A = 25°C to 150°C	–	–0.002	–	mV/A/°C
Total Output Error[2]	E_{TOT}	I_P = ±30 A, T_A = 25°C	–	±1.5	–	%

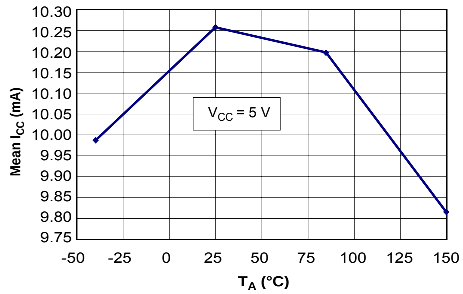
[1]Device may be operated at higher primary current levels, I_P, and ambient temperatures, T_A, provided that the Maximum Junction Temperature, T_J(max), is not exceeded.

[2]Percentage of I_P, with I_P = 30 A. Output filtered.

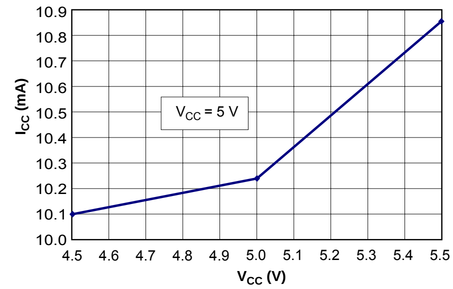
Characteristic Performance

I_P = 5 A, unless otherwise specified

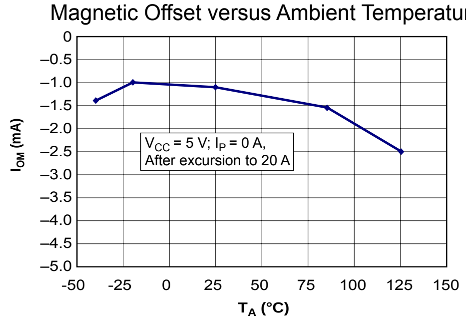
Mean Supply Current versus Ambient Temperature



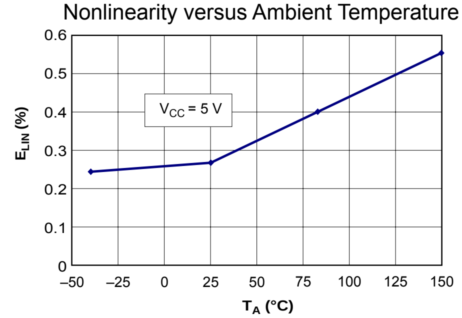
Supply Current versus Supply Voltage



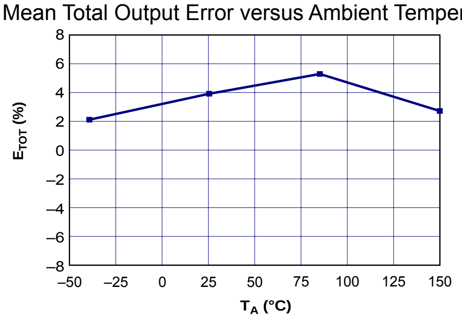
Magnetic Offset versus Ambient Temperature



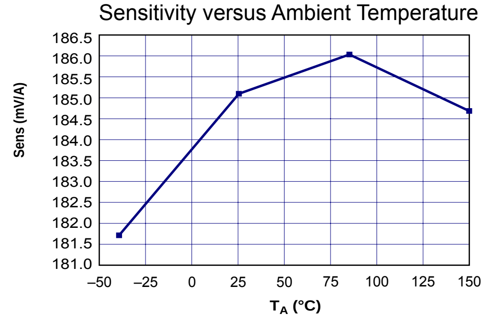
Nonlinearity versus Ambient Temperature



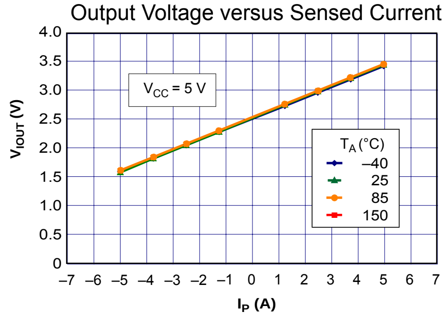
Mean Total Output Error versus Ambient Temperature



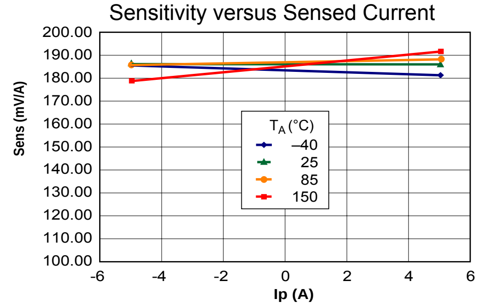
Sensitivity versus Ambient Temperature



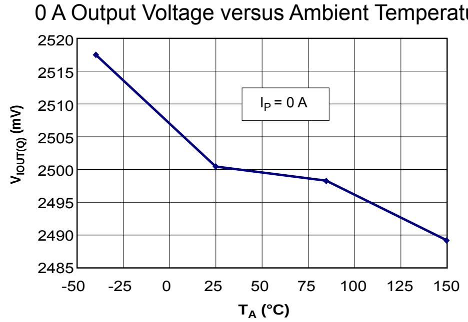
Output Voltage versus Sensed Current



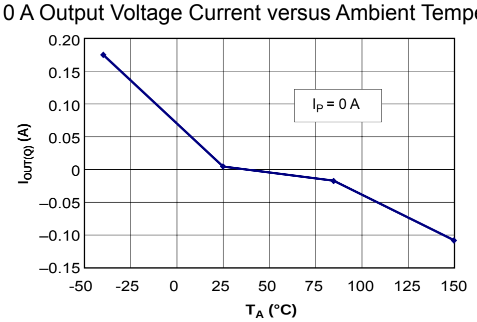
Sensitivity versus Sensed Current



0 A Output Voltage versus Ambient Temperature



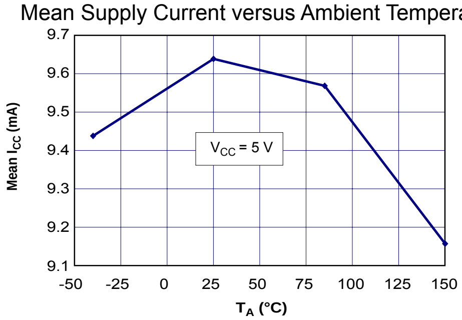
0 A Output Voltage Current versus Ambient Temperature



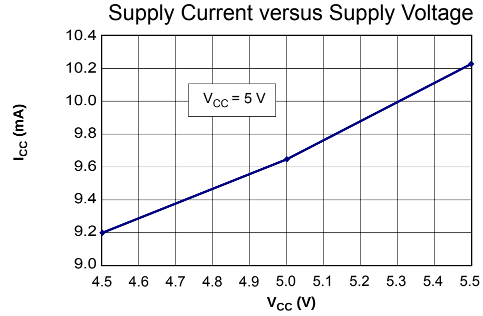
Characteristic Performance

I_P = 20 A, unless otherwise specified

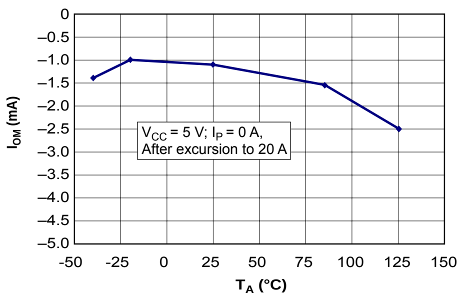
Mean Supply Current versus Ambient Temperature



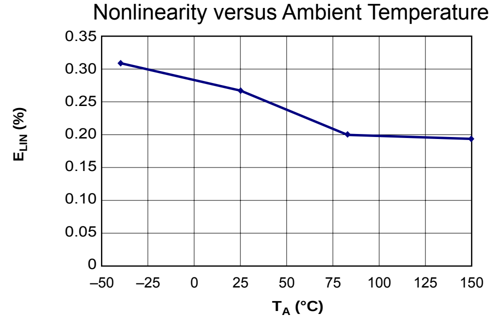
Supply Current versus Supply Voltage



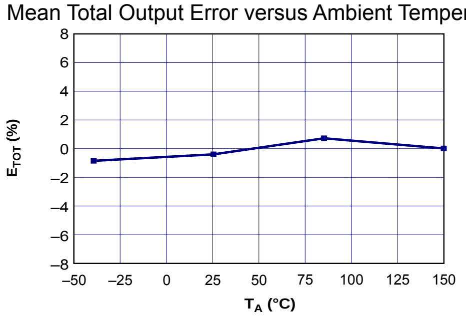
Magnetic Offset versus Ambient Temperature



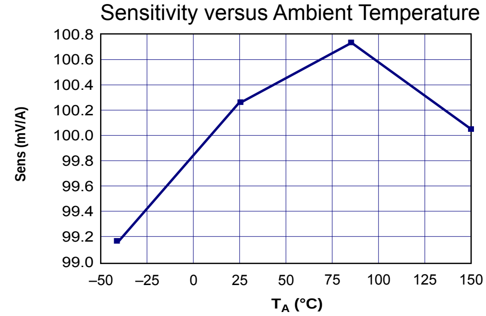
Nonlinearity versus Ambient Temperature



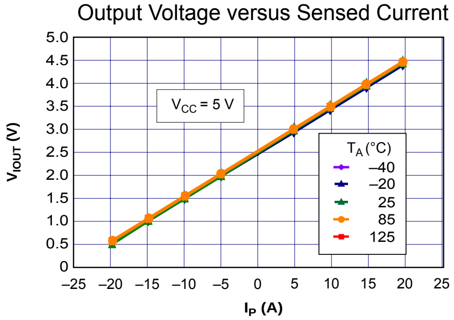
Mean Total Output Error versus Ambient Temperature



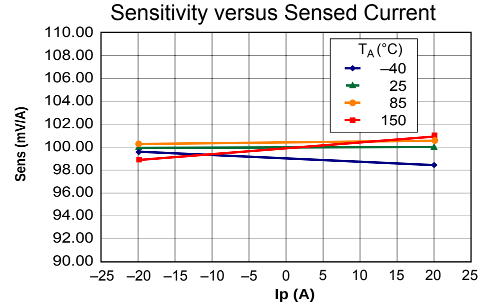
Sensitivity versus Ambient Temperature



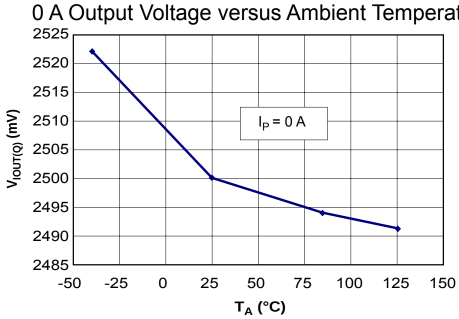
Output Voltage versus Sensed Current



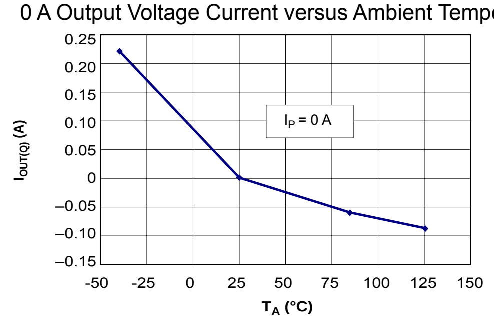
Sensitivity versus Sensed Current



0 A Output Voltage versus Ambient Temperature



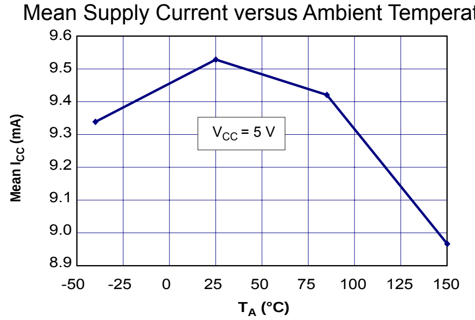
0 A Output Voltage Current versus Ambient Temperature



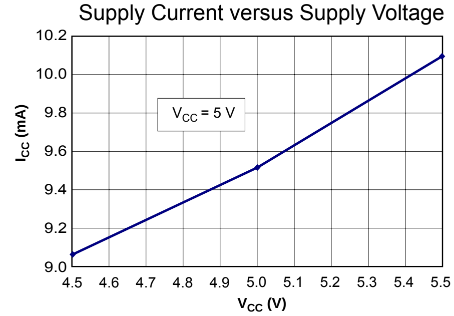
Characteristic Performance

I_P = 30 A, unless otherwise specified

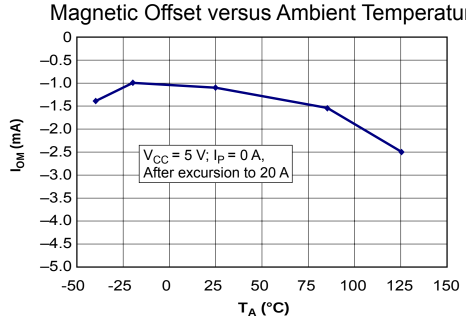
Mean Supply Current versus Ambient Temperature



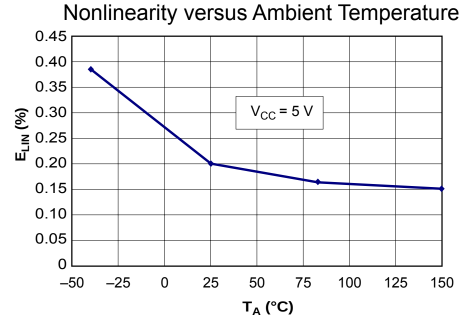
Supply Current versus Supply Voltage



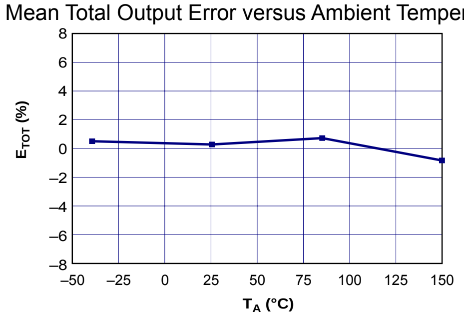
Magnetic Offset versus Ambient Temperature



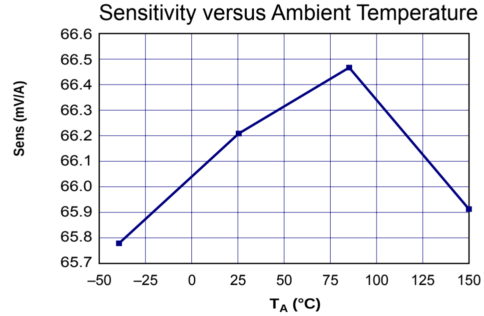
Nonlinearity versus Ambient Temperature



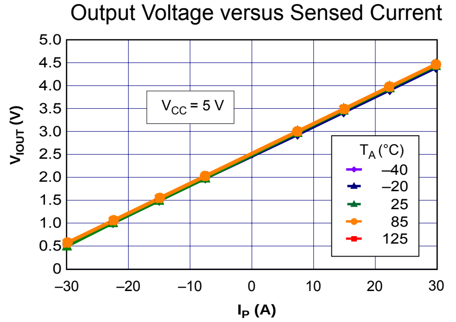
Mean Total Output Error versus Ambient Temperature



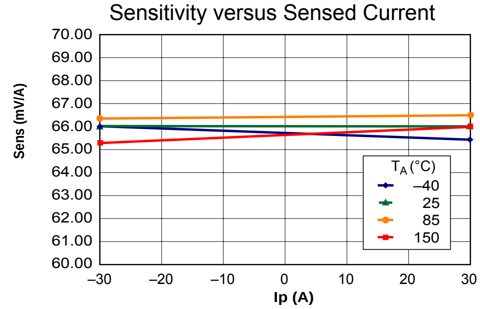
Sensitivity versus Ambient Temperature



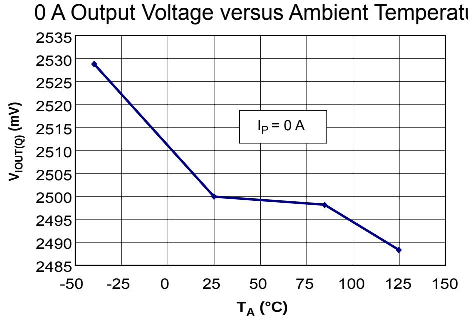
Output Voltage versus Sensed Current



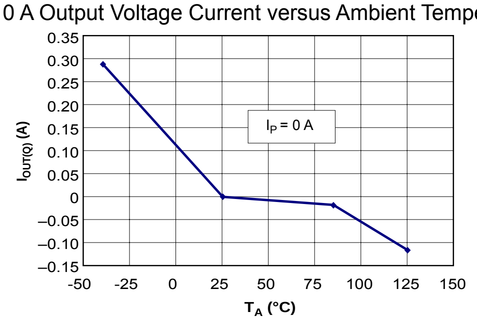
Sensitivity versus Sensed Current



0 A Output Voltage versus Ambient Temperature



0 A Output Voltage Current versus Ambient Temperature



Definitions of Accuracy Characteristics

Sensitivity (Sens). The change in sensor output in response to a 1 A change through the primary conductor. The sensitivity is the product of the magnetic circuit sensitivity (G/A) and the linear IC amplifier gain (mV/G). The linear IC amplifier gain is programmed at the factory to optimize the sensitivity (mV/A) for the full-scale current of the device.

Noise (V_{NOISE}). The product of the linear IC amplifier gain (mV/G) and the noise floor for the Allegro Hall effect linear IC (≈1 G). The noise floor is derived from the thermal and shot noise observed in Hall elements. Dividing the noise (mV) by the sensitivity (mV/A) provides the smallest current that the device is able to resolve.

Linearity (E_{LIN}). The degree to which the voltage output from the sensor varies in direct proportion to the primary current through its full-scale amplitude. Nonlinearity in the output can be attributed to the saturation of the flux concentrator approaching the full-scale current. The following equation is used to derive the linearity:

$$100\left\{1-\left[\frac{\Delta\text{ gain}\times\%\text{ sat }(V_{IOUT\_full\text{-}scale\ amperes}-V_{IOUT(Q)})}{2\,(V_{IOUT\_half\text{-}scale\ amperes}-V_{IOUT(Q)})}\right]\right\}$$

where $V_{IOUT\_full\text{-}scale\ amperes}$ = the output voltage (V) when the sensed current approximates full-scale $\pm I_P$.

Symmetry (E_{SYM}). The degree to which the absolute voltage output from the sensor varies in proportion to either a positive or negative full-scale primary current. The following formula is used to derive symmetry:

$$100\left(\frac{V_{IOUT\_+\ full\text{-}scale\ amperes}-V_{IOUT(Q)}}{V_{IOUT(Q)}-V_{IOUT\_-full\text{-}scale\ amperes}}\right)$$

Quiescent output voltage ($V_{IOUT(Q)}$). The output of the sensor when the primary current is zero. For a unipolar supply voltage, it nominally remains at $V_{CC}/2$. Thus, V_{CC} = 5 V translates into $V_{IOUT(Q)}$ = 2.5 V. Variation in $V_{IOUT(Q)}$ can be attributed to the resolution of the Allegro linear IC quiescent voltage trim and thermal drift.

Electrical offset voltage (V_{OE}). The deviation of the device output from its ideal quiescent value of $V_{CC}/2$ due to nonmagnetic causes. To convert this voltage to amperes, divide by the device sensitivity, Sens.

Accuracy (E_{TOT}). The accuracy represents the maximum deviation of the actual output from its ideal value. This is also known as the total ouput error. The accuracy is illustrated graphically in the output voltage versus current chart at right.

Accuracy is divided into four areas:

- **0 A at 25°C.** Accuracy of sensing zero current flow at 25°C, without the effects of temperature.
- **0 A over Δ temperature.** Accuracy of sensing zero current flow including temperature effects.
- **Full-scale current at 25°C.** Accuracy of sensing the full-scale current at 25°C, without the effects of temperature.
- **Full-scale current over Δ temperature.** Accuracy of sensing full-scale current flow including temperature effects.

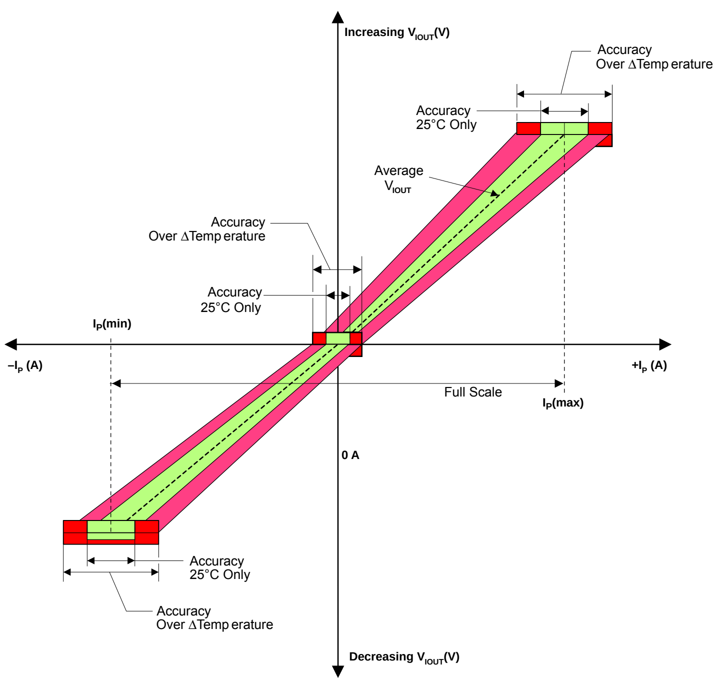
Ratiometry. The ratiometric feature means that its 0 A output, $V_{IOUT(Q)}$, (nominally equal to $V_{CC}/2$) and sensitivity, Sens, are proportional to its supply voltage, V_{CC}. The following formula is used to derive the ratiometric change in 0 A output voltage, $\Delta V_{IOUT(Q)RAT}$ (%).

$$100\left(\frac{V_{IOUT(Q)VCC}\,/\,V_{IOUT(Q)5V}}{V_{CC}\,/\,5\text{ V}}\right)$$

The ratiometric change in sensitivity, $\Delta Sens_{RAT}$ (%), is defined as:

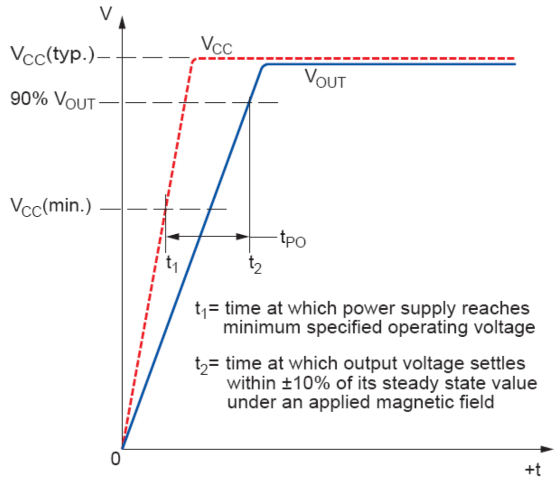
$$100\left(\frac{Sens_{VCC}\,/\,Sens_{5V}}{V_{CC}\,/\,5\text{ V}}\right)$$

Output Voltage versus Sensed Current
Accuracy at 0 A and at Full-Scale Current

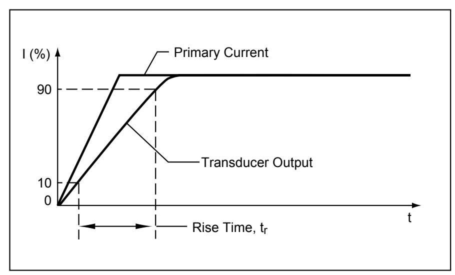


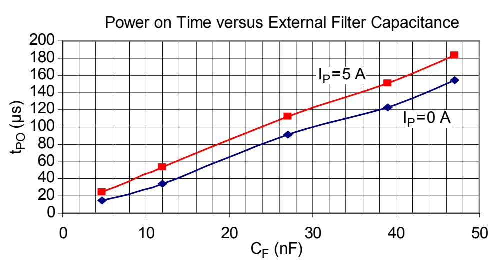
Definitions of Dynamic Response Characteristics

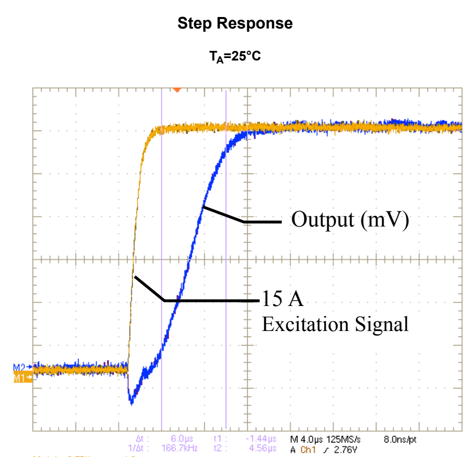
Power-On Time (t_{PO}). When the supply is ramped to its operating voltage, the device requires a finite time to power its internal components before responding to an input magnetic field. Power-On Time, t_{PO} , is defined as the time it takes for the output voltage to settle within ±10% of its steady state value under an applied magnetic field, after the power supply has reached its minimum specified operating voltage, V_{CC}(min), as shown in the chart at right.



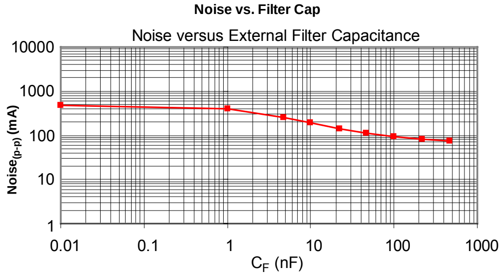
Rise time (t_r). The time interval between a) when the sensor reaches 10% of its full scale value, and b) when it reaches 90% of its full scale value. The rise time to a step response is used to derive the bandwidth of the current sensor, in which $f(–3\text{ dB}) = 0.35 / t_r$. Both t_r and $t_{RESPONSE}$ are detrimentally affected by eddy current losses observed in the conductive IC ground plane.

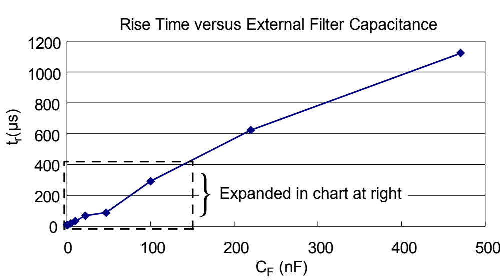




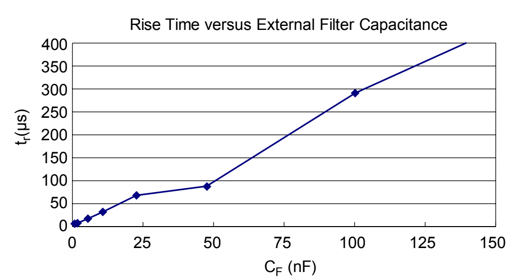


Noise vs. Filter Cap





C_F (nF)	t_r (µs)
0	6.6
1	7.7
4.7	17.4
10	32.1
22	68.2
47	88.2
100	291.3
220	623.0
470	1120.0

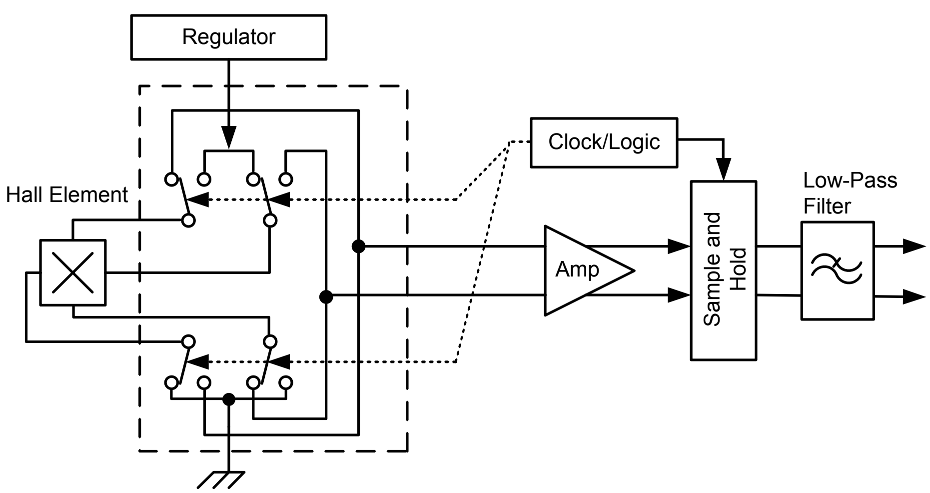


Chopper Stabilization Technique

Chopper Stabilization is an innovative circuit technique that is used to minimize the offset voltage of a Hall element and an associated on-chip amplifier. Allegro patented a Chopper Stabilization technique that nearly eliminates Hall IC output drift induced by temperature or package stress effects. This offset reduction technique is based on a signal modulation-demodulation process. Modulation is used to separate the undesired dc offset signal from the magnetically induced signal in the frequency domain. Then, using a low-pass filter, the modulated dc offset is suppressed while the magnetically induced signal passes through the filter.

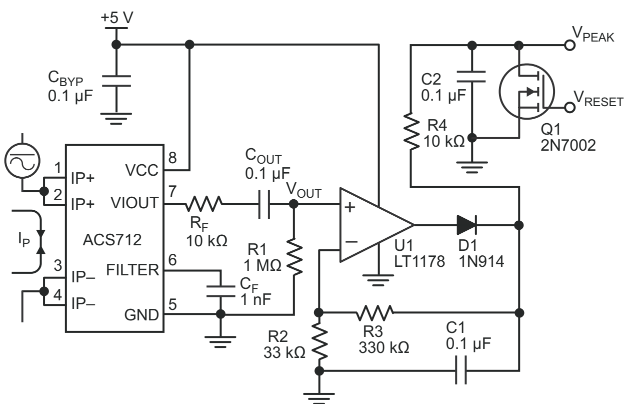
As a result of this chopper stabilization approach, the output voltage from the Hall IC is desensitized to the effects of temperature and mechanical stress. This technique produces devices that have an extremely stable Electrical Offset Voltage, are immune to thermal stress, and have precise recoverability after temperature cycling.

This technique is made possible through the use of a BiCMOS process that allows the use of low-offset and low-noise amplifiers in combination with high-density logic integration and sample and hold circuits.

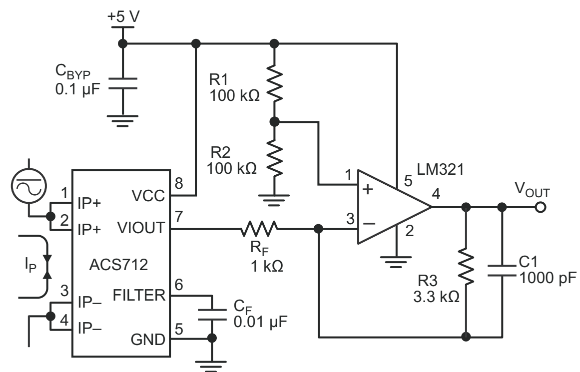


Concept of Chopper Stabilization Technique

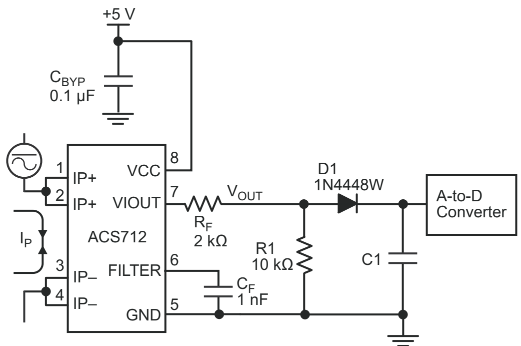
Typical Applications



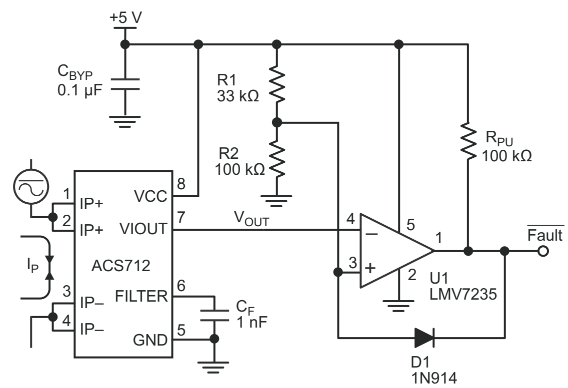
Application 2. Peak Detecting Circuit



Application 3. This configuration increases gain to 610 mV/A (tested using the ACS712ELC-05A).



Application 4. Rectified Output. 3.3 V scaling and rectification application for A-to-D converters. Replaces current transformer solutions with simpler ACS circuit. C1 is a function of the load resistance and filtering desired. R1 can be omitted if the full range is desired.



Application 5. 10 A Overcurrent Fault Latch. Fault threshold set by R1 and R2. This circuit latches an overcurrent fault and holds it until the 5 V rail is powered down.

Improving Sensing System Accuracy Using the FILTER Pin

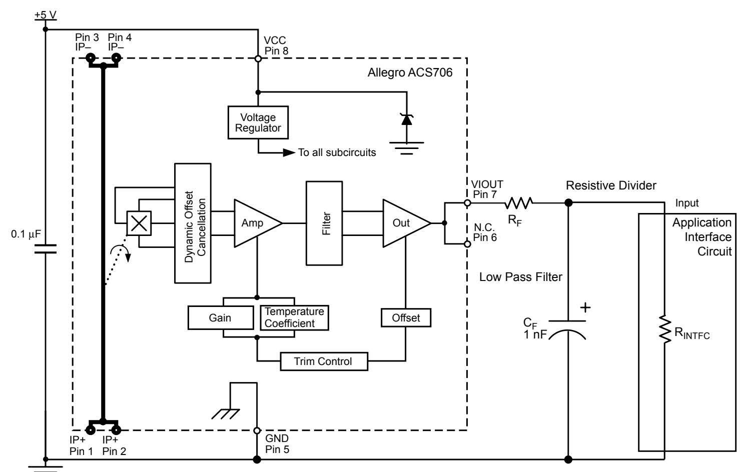
In low-frequency sensing applications, it is often advantageous to add a simple RC filter to the output of the sensor. Such a low-pass filter improves the signal-to-noise ratio, and therefore the resolution, of the sensor output signal. However, the addition of an RC filter to the output of a sensor IC can result in undesirable sensor output attenuation — even for dc signals.

Signal attenuation, ΔV_{ATT}, is a result of the resistive divider effect between the resistance of the external filter, R_F (see Application 6), and the input impedance and resistance of the customer interface circuit, R_{INTFC}. The transfer function of this resistive divider is given by:

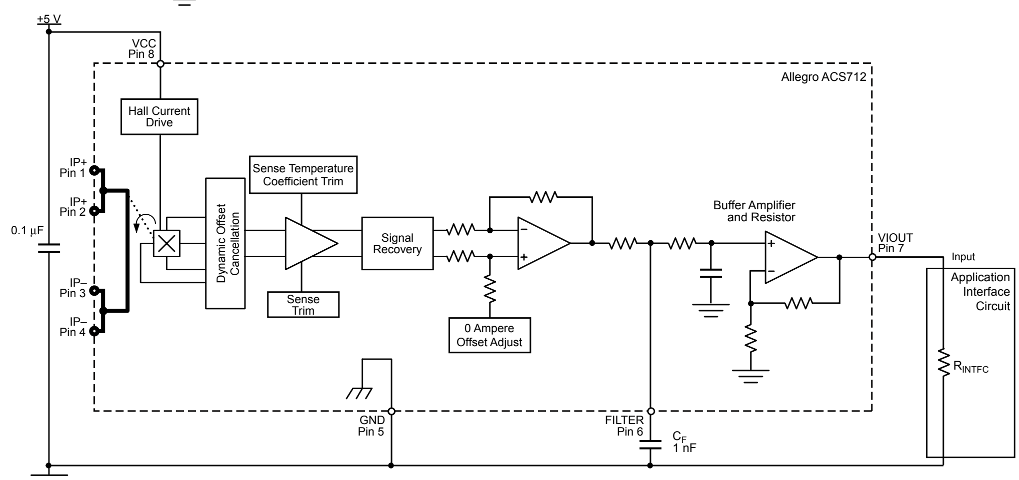
$$\Delta V_{\mathrm{ATT}} = V_{\mathrm{IOUT}}\left(\frac{R_{\mathrm{INTFC}}}{R_{\mathrm{F}} + R_{\mathrm{INTFC}}}\right) .$$

Even if R_F and R_{INTFC} are designed to match, the two individual resistance values will most likely drift by different amounts over temperature. Therefore, signal attenuation will vary as a function of temperature. Note that, in many cases, the input impedance, R_{INTFC}, of a typical analog-to-digital converter (ADC) can be as low as 10 kΩ.

The ACS712 contains an internal resistor, a FILTER pin connection to the printed circuit board, and an internal buffer amplifier. With this circuit architecture, users can implement a simple RC filter via the addition of a capacitor, C_F (see Application 7) from the FILTER pin to ground. The buffer amplifier inside of the ACS712 (located after the internal resistor and FILTER pin connection) eliminates the attenuation caused by the resistive divider effect described in the equation for ΔV_{ATT}. Therefore, the ACS712 device is ideal for use in high-accuracy applications that cannot afford the signal attenuation associated with the use of an external RC low-pass filter.

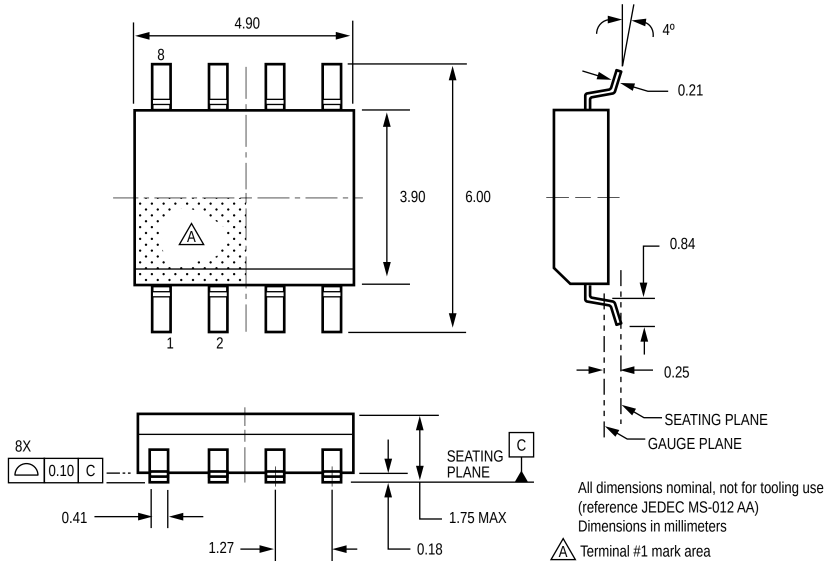


Application 6. When a low pass filter is constructed externally to a standard Hall effect device, a resistive divider may exist between the filter resistor, R_F, and the resistance of the customer interface circuit, R_{INTFC}. This resistive divider will cause excessive attenuation, as given by the transfer function for ΔV_{ATT}.



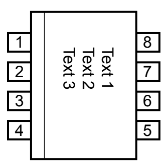
Application 7. Using the FILTER pin provided on the ACS712 eliminates the attenuation effects of the resistor divider between R_F and R_{INTFC}, shown in Application 6.

Package LC, 8-pin SOIC



Package Branding

Two alternative patterns are used



ACS712T *RLCPPP* *YYWWA*	ACS	Allegro Current Sensor
	712	Device family number
	T	Indicator of 100% matte tin leadframe plating
	R	Operating ambient temperature range code
	LC	Package type designator
	PPP	Primary sensed current
	YY	Date code: Calendar year (last two digits)
	WW	Date code: Calendar week
	A	Date code: Shift code

ACS712T *RLCPPP* *L...L* *YYWW*	ACS	Allegro Current Sensor
	712	Device family number
	T	Indicator of 100% matte tin leadframe plating
	R	Operating ambient temperature range code
	LC	Package type designator
	PPP	Primary sensed current
	L...L	Lot code
	YY	Date code: Calendar year (last two digits)
	WW	Date code: Calendar week

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The products described herein are manufactured under one or more of the following U.S. patents: 5,045,920; 5,264,783; 5,442,283; 5,389,889; 5,581,179; 5,517,112; 5,619,137; 5,621,319; 5,650,719; 5,686,894; 5,694,038; 5,729,130; 5,917,320; and other patents pending.

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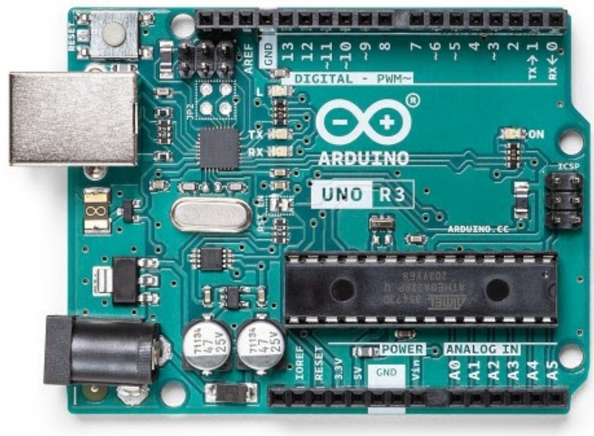
Product Reference Manual
SKU: A000066



Description

The Arduino UNO R3 is the perfect board to get familiar with electronics and coding. This versatile development board is equipped with the well-known ATmega328P and the ATMega 16U2 Processor.
This board will give you a great first experience within the world of Arduino.

Target areas:

Maker, introduction, industries

Features

- **ATMega328P** Processor
  - **Memory**
    - AVR CPU at up to 16 MHz
    - 32KB Flash
    - 2KB SRAM
    - 1KB EEPROM
  - **Security**
    - Power On Reset (POR)
    - Brown Out Detection (BOD)
  - **Peripherals**
    - 2x 8-bit Timer/Counter with a dedicated period register and compare channels
    - 1x 16-bit Timer/Counter with a dedicated period register, input capture and compare channels
    - 1x USART with fractional baud rate generator and start-of-frame detection
    - 1x controller/peripheral Serial Peripheral Interface (SPI)
    - 1x Dual mode controller/peripheral I2C
    - 1x Analog Comparator (AC) with a scalable reference input
    - Watchdog Timer with separate on-chip oscillator
    - Six PWM channels
    - Interrupt and wake-up on pin change
  - **ATMega16U2 Processor**
    - 8-bit AVR® RISC-based microcontroller
  - **Memory**
    - 16 KB ISP Flash
    - 512B EEPROM
    - 512B SRAM
    - debugWIRE interface for on-chip debugging and programming
  - **Power**
    - 2.7-5.5 volts

CONTENTS

1 The Board

1.1 Application Examples

The UNO board is the flagship product of Arduino. Regardless if you are new to the world of electronics or will use the UNO as a tool for education purposes or industry-related tasks, the UNO is likely to meet your needs.

First entry to electronics: If this is your first project within coding and electronics, get started with our most used and documented board; Arduino UNO. It is equipped with the well-known ATmega328P processor, 14 digital input/output pins, 6 analog inputs, USB connections, ICSP header and reset button. This board includes everything you will need for a great first experience with Arduino.

Industry-standard development board: Using the Arduino UNO R3 board in industries, there are a range of companies using the UNO board as the brain for their PLC's.

Education purposes: Although the UNO R3 board has been with us for about ten years, it is still widely used for various education purposes and scientific projects. The board's high standard and top quality performance makes it a great resource to capture real time from sensors and to trigger complex laboratory equipment to mention a few examples.

1.2 Related Products

- Starter Kit
- Arduino UNO R4 Minima
- Arduino UNO R4 WiFi
- Tinkerkit Braccio Robot

2 Ratings

2.1 Recommended Operating Conditions

Symbol	Description	Min	Max
	Conservative thermal limits for the whole board:	-40 °C (-40°F)	85 °C (185°F)

NOTE: In extreme temperatures, EEPROM, voltage regulator, and the crystal oscillator, might not work as expected.

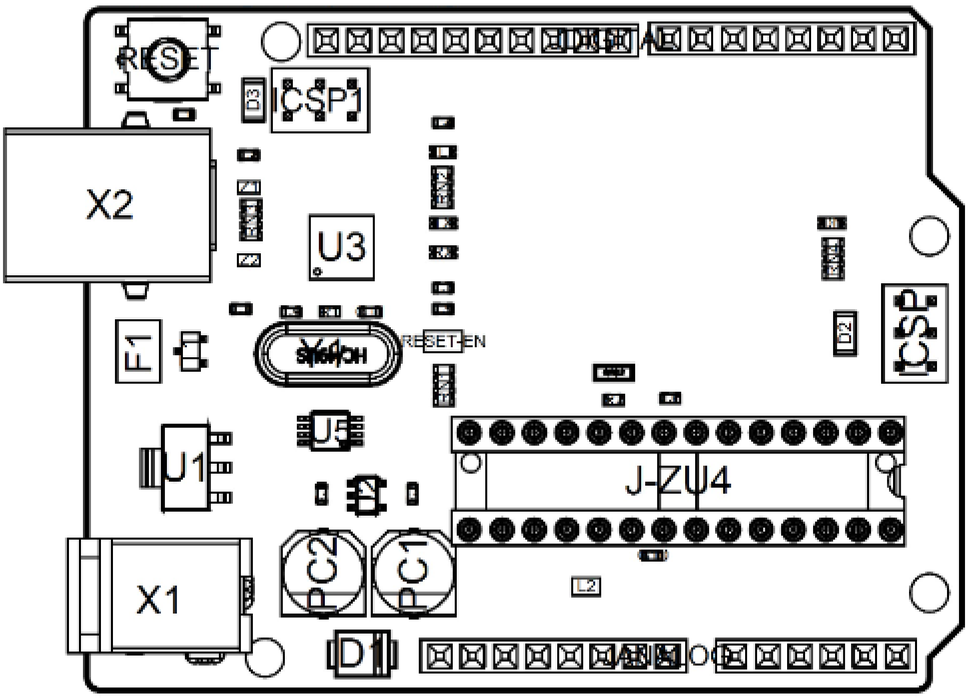
2.2 Power Consumption

Symbol	Description	Min	Typ	Max	Unit
VINMax	Maximum input voltage from VIN pad	6	-	20	V
VUSBMax	Maximum input voltage from USB connector		-	5.5	V
PMax	Maximum Power Consumption	-	-	xx	mA

3 Functional Overview

3.1 Board Topology

Top view



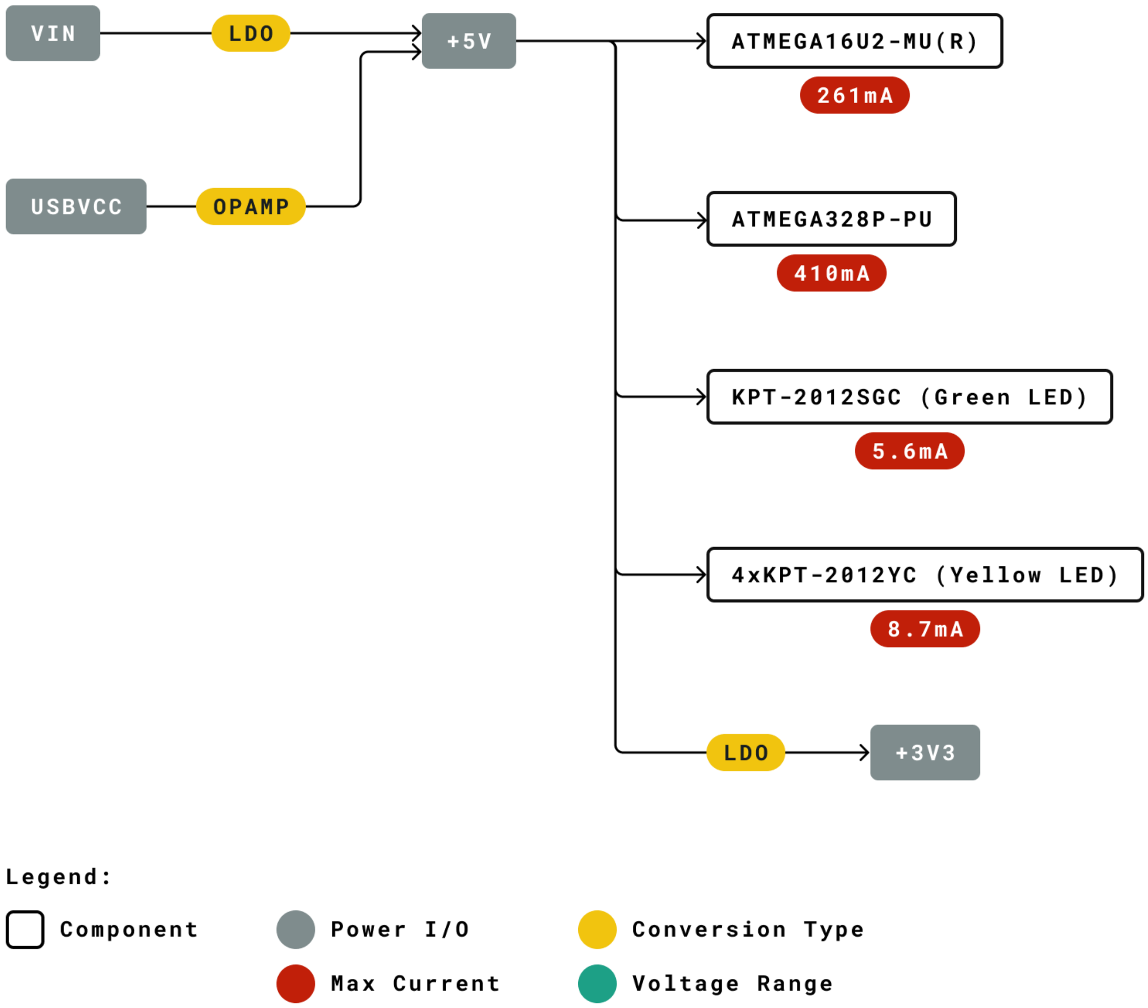
Board topology

Ref.	Description	Ref.	Description
X1	Power jack 2.1x5.5mm	U1	SPX1117M3-L-5 Regulator
X2	USB B Connector	U3	ATMEGA16U2 Module
PC1	EEE-1EA470WP 25V SMD Capacitor	U5	LMV358LIST-A.9 IC
PC2	EEE-1EA470WP 25V SMD Capacitor	F1	Chip Capacitor, High Density
D1	CGRA4007-G Rectifier	ICSP	Pin header connector (through hole 6)
J-ZU4	ATMEGA328P Module	ICSP1	Pin header connector (through hole 6)
Y1	ECS-160-20-4X-DU Oscillator		

3.2 Processor

The Main Processor is a ATmega328P running at up to 20 MHz. Most of its pins are connected to the external headers, however some are reserved for internal communication with the USB Bridge coprocessor.

3.3 Power Tree



Power tree

4 Board Operation

4.1 Getting Started - IDE

If you want to program your Arduino UNO R3 while offline you need to install the Arduino Desktop IDE [1] To connect the Arduino UNO to your computer, you'll need a USB-B cable. This also provides power to the board, as indicated by the LED.

4.2 Getting Started - Arduino Web Editor

All Arduino boards, including this one, work out-of-the-box on the Arduino Web Editor [2], by just installing a simple plugin.

The Arduino Web Editor is hosted online, therefore it will always be up-to-date with the latest features and support for all boards. Follow **[3]** to start coding on the browser and upload your sketches onto your board.

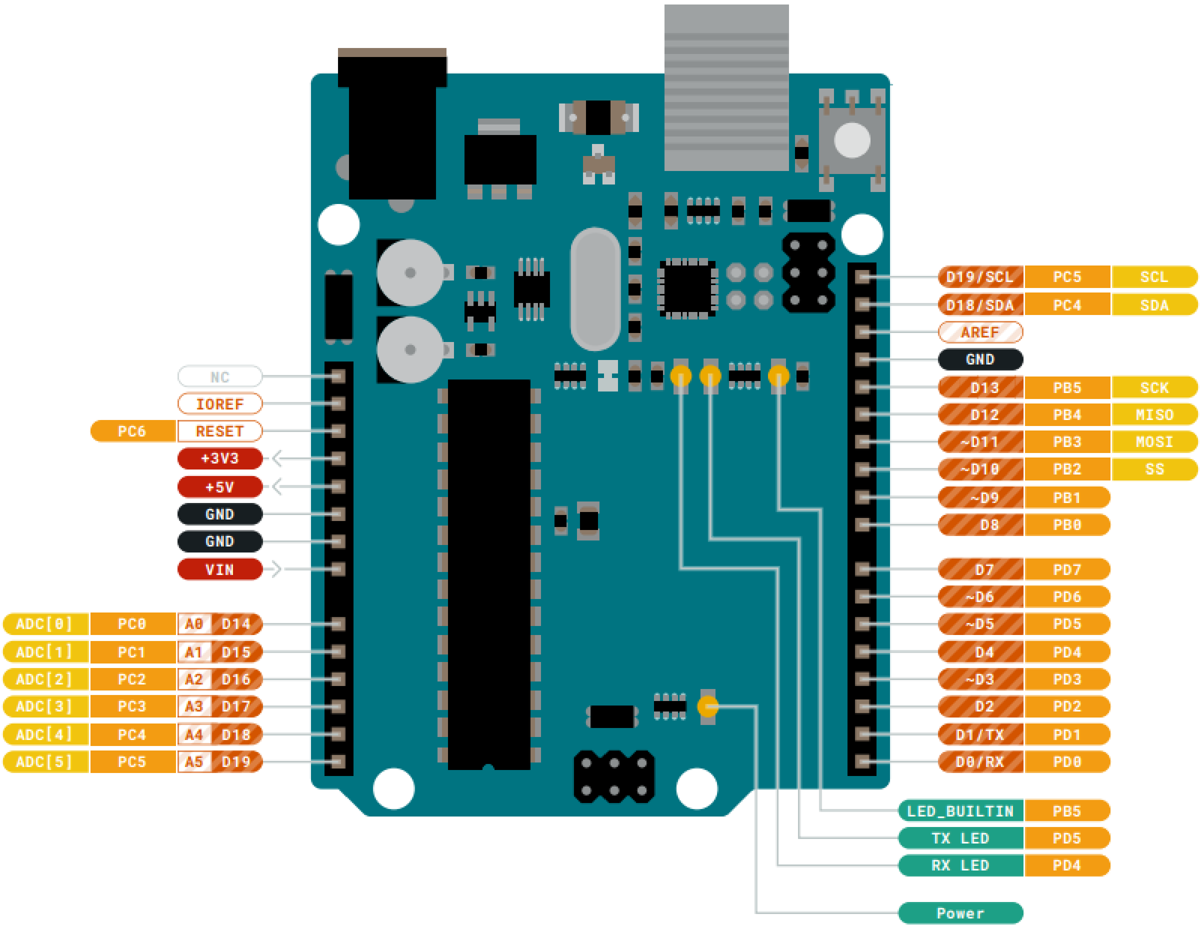
4.3 Sample Sketches

Sample sketches for the Arduino UNO R3 can be found either in the "Examples" menu in the Arduino IDE or in the "Documentation" section of the Arduino website [4]

4.4 Online Resources

Now that you have gone through the basics of what you can do with the board you can explore the endless possibilities it provides by checking exciting projects on Arduino Project Hub **[5]**, the Arduino Library Reference **[6]** and the online Arduino store **[7]** where you will be able to complement your board with sensors, actuators and more.

5 Connector Pinouts



Pinout

5.1 JANALOG

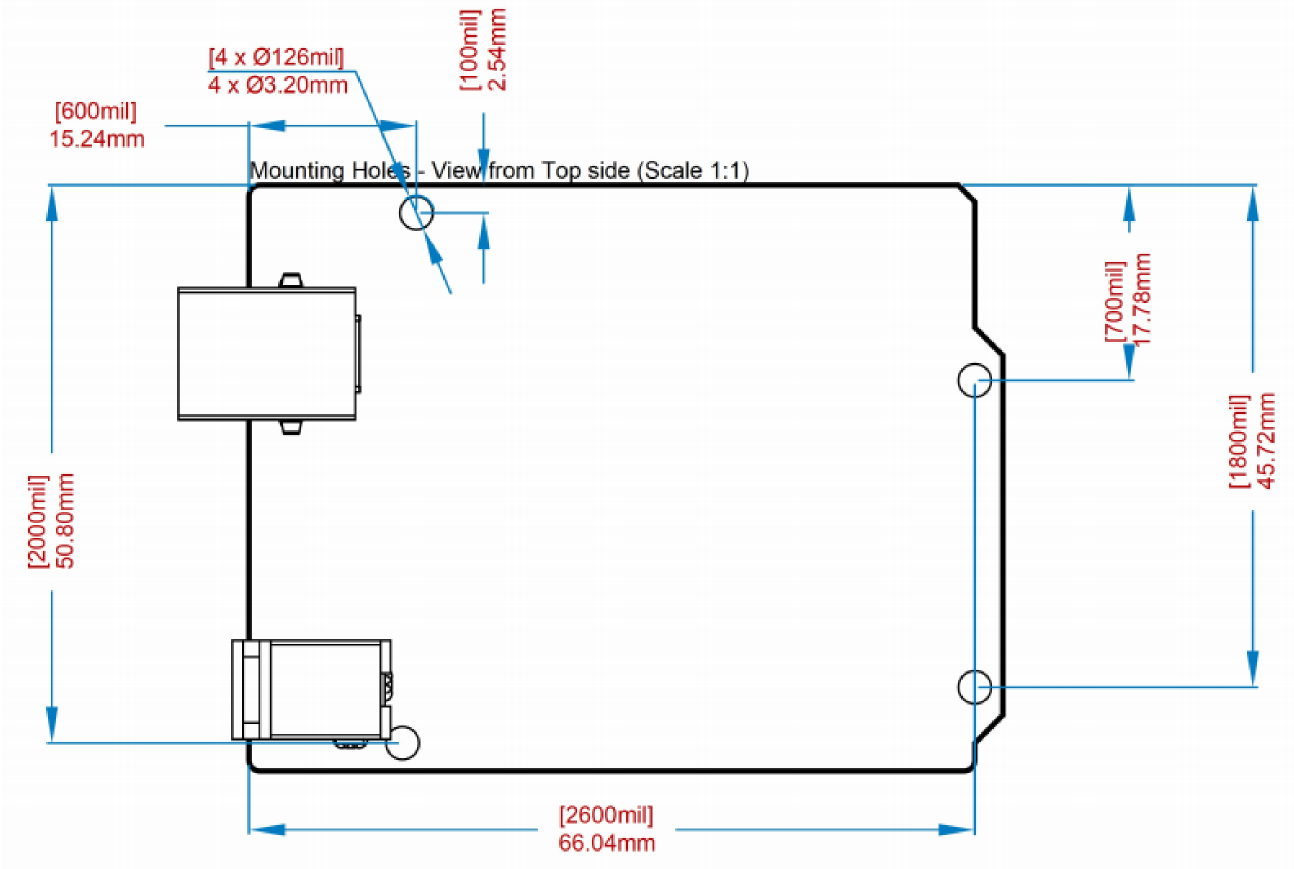
Pin	Function	Type	Description
1	NC	NC	Not connected
2	IOREF	IOREF	Reference for digital logic V - connected to 5V
3	Reset	Reset	Reset
4	+3V3	Power	+3V3 Power Rail
5	+5V	Power	+5V Power Rail
6	GND	Power	Ground
7	GND	Power	Ground
8	VIN	Power	Voltage Input
9	A0	Analog/GPIO	Analog input 0 /GPIO
10	A1	Analog/GPIO	Analog input 1 /GPIO
11	A2	Analog/GPIO	Analog input 2 /GPIO
12	A3	Analog/GPIO	Analog input 3 /GPIO
13	A4/SDA	Analog input/I2C	Analog input 4/I2C Data line
14	A5/SCL	Analog input/I2C	Analog input 5/I2C Clock line

5.2 JDIGITAL

Pin	Function	Type	Description
1	D0	Digital/GPIO	Digital pin 0/GPIO
2	D1	Digital/GPIO	Digital pin 1/GPIO
3	D2	Digital/GPIO	Digital pin 2/GPIO
4	D3	Digital/GPIO	Digital pin 3/GPIO
5	D4	Digital/GPIO	Digital pin 4/GPIO
6	D5	Digital/GPIO	Digital pin 5/GPIO
7	D6	Digital/GPIO	Digital pin 6/GPIO
8	D7	Digital/GPIO	Digital pin 7/GPIO
9	D8	Digital/GPIO	Digital pin 8/GPIO
10	D9	Digital/GPIO	Digital pin 9/GPIO
11	SS	Digital	SPI Chip Select
12	MOSI	Digital	SPI1 Main Out Secondary In
13	MISO	Digital	SPI Main In Secondary Out
14	SCK	Digital	SPI serial clock output
15	GND	Power	Ground
16	AREF	Digital	Analog reference voltage
17	A4/SD4	Digital	Analog input 4/I2C Data line (duplicated)
18	A5/SD5	Digital	Analog input 5/I2C Clock line (duplicated)

5.3 Mechanical Information

5.4 Board Outline & Mounting Holes



Board outline

6 Certifications

6.1 Declaration of Conformity CE DoC (EU)

We declare under our sole responsibility that the products above are in conformity with the essential requirements of the following EU Directives and therefore qualify for free movement within markets comprising the European Union (EU) and European Economic Area (EEA).

ROHS 2 Directive 2011/65/EU	
Conforms to:	EN50581:2012
Directive 2014/35/EU. (LVD)	
Conforms to:	EN 60950-1:2006/A11:2009/A1:2010/A12:2011/AC:2011
Directive 2004/40/EC & 2008/46/EC & 2013/35/EU, EMF	
Conforms to:	EN 62311:2008

6.2 Declaration of Conformity to EU RoHS & REACH 211 01/19/2021

Arduino boards are in compliance with RoHS 2 Directive 2011/65/EU of the European Parliament and RoHS 3 Directive 2015/863/EU of the Council of 4 June 2015 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Substance	Maximum limit (ppm)
Lead (Pb)	1000
Cadmium (Cd)	100
Mercury (Hg)	1000
Hexavalent Chromium (Cr6+)	1000
Poly Brominated Biphenyls (PBB)	1000
Poly Brominated Diphenyl ethers (PBDE)	1000
Bis(2-Ethylhexyl} phthalate (DEHP)	1000
Benzyl butyl phthalate (BBP)	1000
Dibutyl phthalate (DBP)	1000
Diisobutyl phthalate (DIBP)	1000

Exemptions: No exemptions are claimed.

Arduino Boards are fully compliant with the related requirements of European Union Regulation (EC) 1907 /2006 concerning the Registration, Evaluation, Authorization and Restriction of Chemicals (REACH). We declare none of the SVHCs (https://echa.europa.eu/web/guest/candidate-list-table), the Candidate List of Substances of Very High Concern for authorization currently released by ECHA, is present in all products (and also package) in quantities totaling in a concentration equal or above 0.1%. To the best of our knowledge, we also declare that our products do not contain any of the substances listed on the "Authorization List" (Annex XIV of the REACH regulations) and Substances of Very High Concern (SVHC) in any significant amounts as specified by the Annex XVII of Candidate list published by ECHA (European Chemical Agency) 1907 /2006/EC.

6.3 Conflict Minerals Declaration

As a global supplier of electronic and electrical components, Arduino is aware of our obligations with regards to laws and regulations regarding Conflict Minerals, specifically the Dodd-Frank Wall Street Reform and Consumer Protection Act, Section 1502. Arduino does not directly source or process conflict minerals such as Tin, Tantalum, Tungsten, or Gold. Conflict minerals are contained in our products in the form of solder, or as a component in metal alloys. As part of our reasonable due diligence Arduino has contacted component suppliers within our supply chain to verify their continued compliance with the regulations. Based on the information received thus far we declare that our products contain Conflict Minerals sourced from conflict-free areas.

7 FCC Caution

Any Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:

(1) This device may not cause harmful interference

(2) this device must accept any interference received, including interference that may cause undesired operation.

FCC RF Radiation Exposure Statement:

1. This Transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.
2. This equipment complies with RF radiation exposure limits set forth for an uncontrolled environment.
3. This equipment should be installed and operated with minimum distance 20cm between the radiator & your body.

English: User manuals for license-exempt radio apparatus shall contain the following or equivalent notice in a conspicuous location in the user manual or alternatively on the device or both. This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions:

(1) this device may not cause interference

(2) this device must accept any interference, including interference that may cause undesired operation of the device.

French: Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes :

(1) l' appareil nedoit pas produire de brouillage

(2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

IC SAR Warning:

English This equipment should be installed and operated with minimum distance 20 cm between the radiator and your body.

French: Lors de l' installation et de l' exploitation de ce dispositif, la distance entre le radiateur et le corps est d 'au moins 20 cm.

Important: The operating temperature of the EUT can't exceed 85℃ and shouldn't be lower than -40℃.

Hereby, Arduino S.r.l. declares that this product is in compliance with essential requirements and other relevant provisions of Directive 2014/53/EU. This product is allowed to be used in all EU member states.

8 Company Information

Company name	Arduino S.r.l
Company Address	Via Andrea Appiani 25 20900 MONZA Italy

9 Reference Documentation

Reference	Link
Arduino IDE (Desktop)	https://www.arduino.cc/en/Main/Software
Arduino IDE (Cloud)	https://create.arduino.cc/editor
Cloud IDE Getting Started	https://create.arduino.cc/projecthub/Arduino_Genuino/getting-started-with-arduino-web-editor-4b3e4a
Arduino Website	https://www.arduino.cc/
Project Hub	https://create.arduino.cc/projecthub?by=part&part_id=11332&sort=trending
Library Reference	https://www.arduino.cc/reference/en/
Online Store	https://store.arduino.cc/

10 Revision History

Date	Revision	Changes
26/07/2023	2	General Update
06/2021	1	Datasheet release

HD44780U (LCD-II)

(Dot Matrix Liquid Crystal Display Controller/Driver)

HITACHI

ADE-207-272(Z)
'99.9
Rev. 0.0

Description

The HD44780U dot-matrix liquid crystal display controller and driver LSI displays alphanumerics, Japanese kana characters, and symbols. It can be configured to drive a dot-matrix liquid crystal display under the control of a 4- or 8-bit microprocessor. Since all the functions such as display RAM, character generator, and liquid crystal driver, required for driving a dot-matrix liquid crystal display are internally provided on one chip, a minimal system can be interfaced with this controller/driver.

A single HD44780U can display up to one 8-character line or two 8-character lines.

The HD44780U has pin function compatibility with the HD44780S which allows the user to easily replace an LCD-II with an HD44780U. The HD44780U character generator ROM is extended to generate 208 5×8 dot character fonts and 32 5×10 dot character fonts for a total of 240 different character fonts.

The low power supply (2.7V to 5.5V) of the HD44780U is suitable for any portable battery-driven product requiring low power dissipation.

Features

- 5×8 and 5×10 dot matrix possible
- Low power operation support:
  — 2.7 to 5.5V
- Wide range of liquid crystal display driver power
  — 3.0 to 11V
- Liquid crystal drive waveform
  — A (One line frequency AC waveform)
- Correspond to high speed MPU bus interface
  — 2 MHz (when V_{CC} = 5V)
- 4-bit or 8-bit MPU interface enabled
- 80×8-bit display RAM (80 characters max.)
- 9,920-bit character generator ROM for a total of 240 character fonts
  — 208 character fonts (5×8 dot)
  — 32 character fonts (5×10 dot)

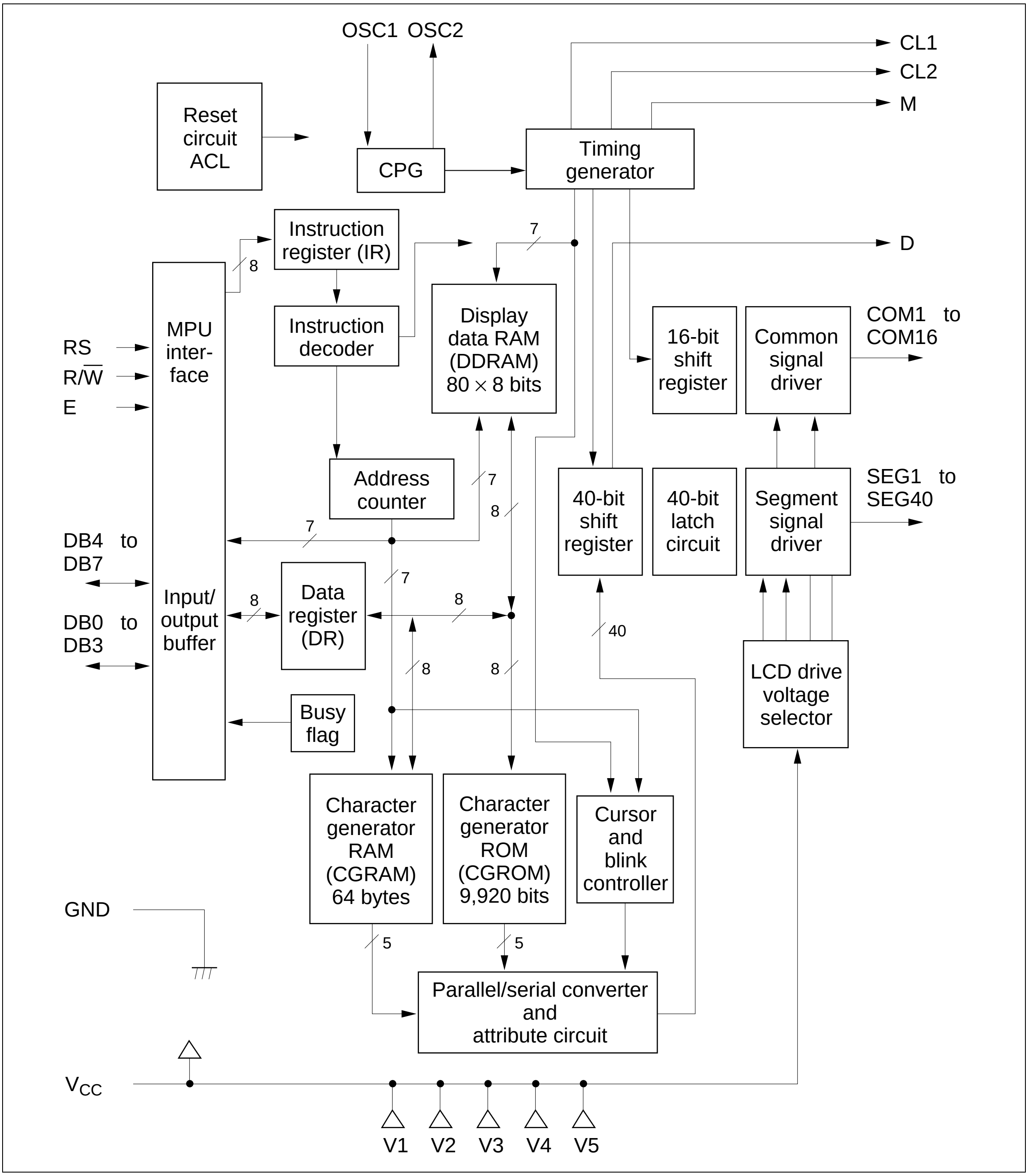
- 64 × 8-bit character generator RAM
  - 8 character fonts (5 × 8 dot)
  - 4 character fonts (5 × 10 dot)
- 16-common × 40-segment liquid crystal display driver
- Programmable duty cycles
  - 1/8 for one line of 5 × 8 dots with cursor
  - 1/11 for one line of 5 × 10 dots with cursor
  - 1/16 for two lines of 5 × 8 dots with cursor
- Wide range of instruction functions:
  - Display clear, cursor home, display on/off, cursor on/off, display character blink, cursor shift, display shift
- Pin function compatibility with HD44780S
- Automatic reset circuit that initializes the controller/driver after power on
- Internal oscillator with external resistors
- Low power consumption

Ordering Information

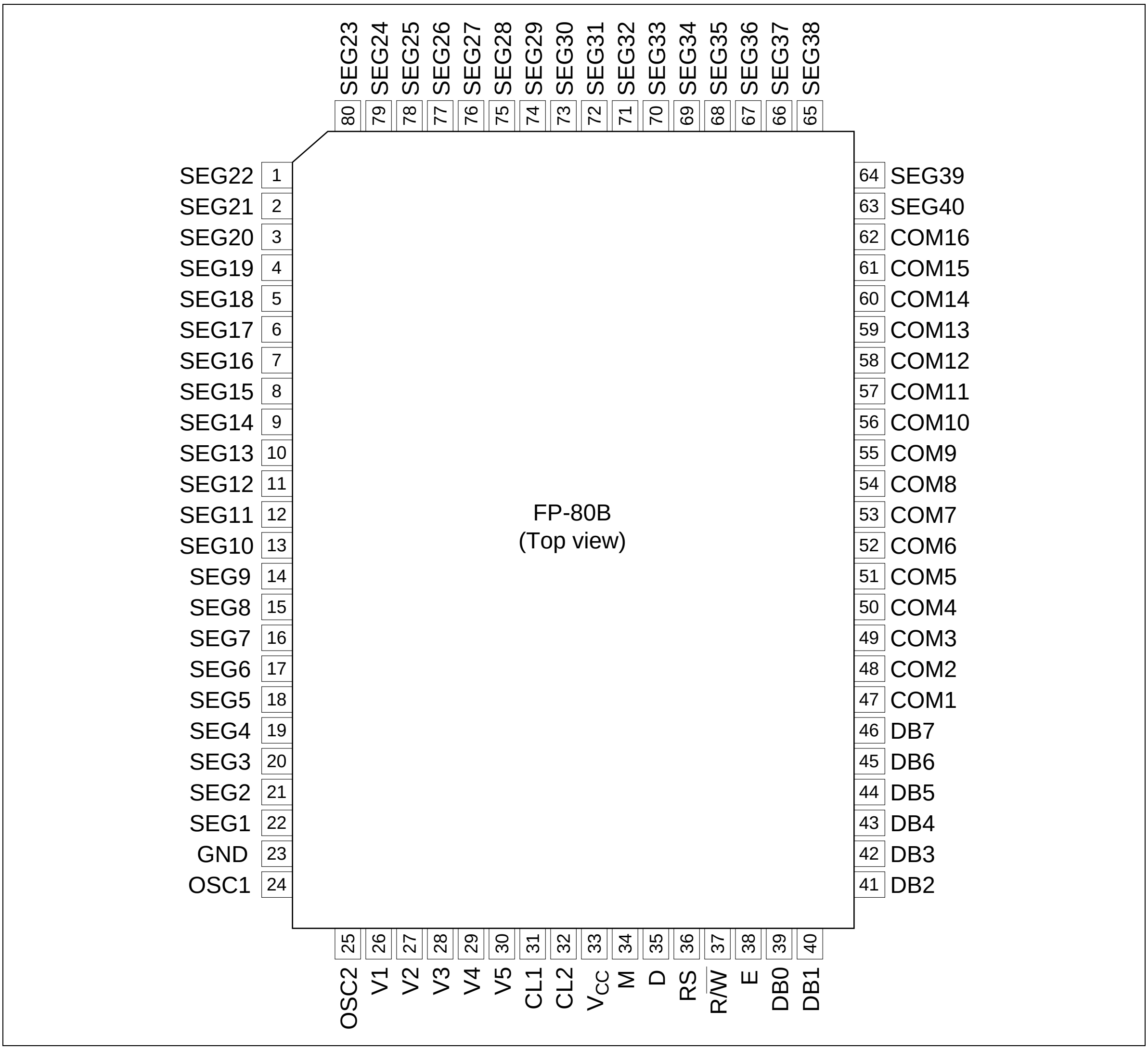
Type No.	Package	CGROM
HD44780UA00FS	FP-80B	Japanese standard font
HCD44780UA00	Chip	
HD44780UA00TF	TFP-80F	
HD44780UA02FS	FP-80B	European standard font
HCD44780UA02	Chip	
HD44780UA02TF	TFP-80F	
HD44780UBxxFS	FP-80B	Custom font
HCD44780UBxx	Chip	
HD44780UBxxTF	TFP-80F	

Note: xx: ROM code No.

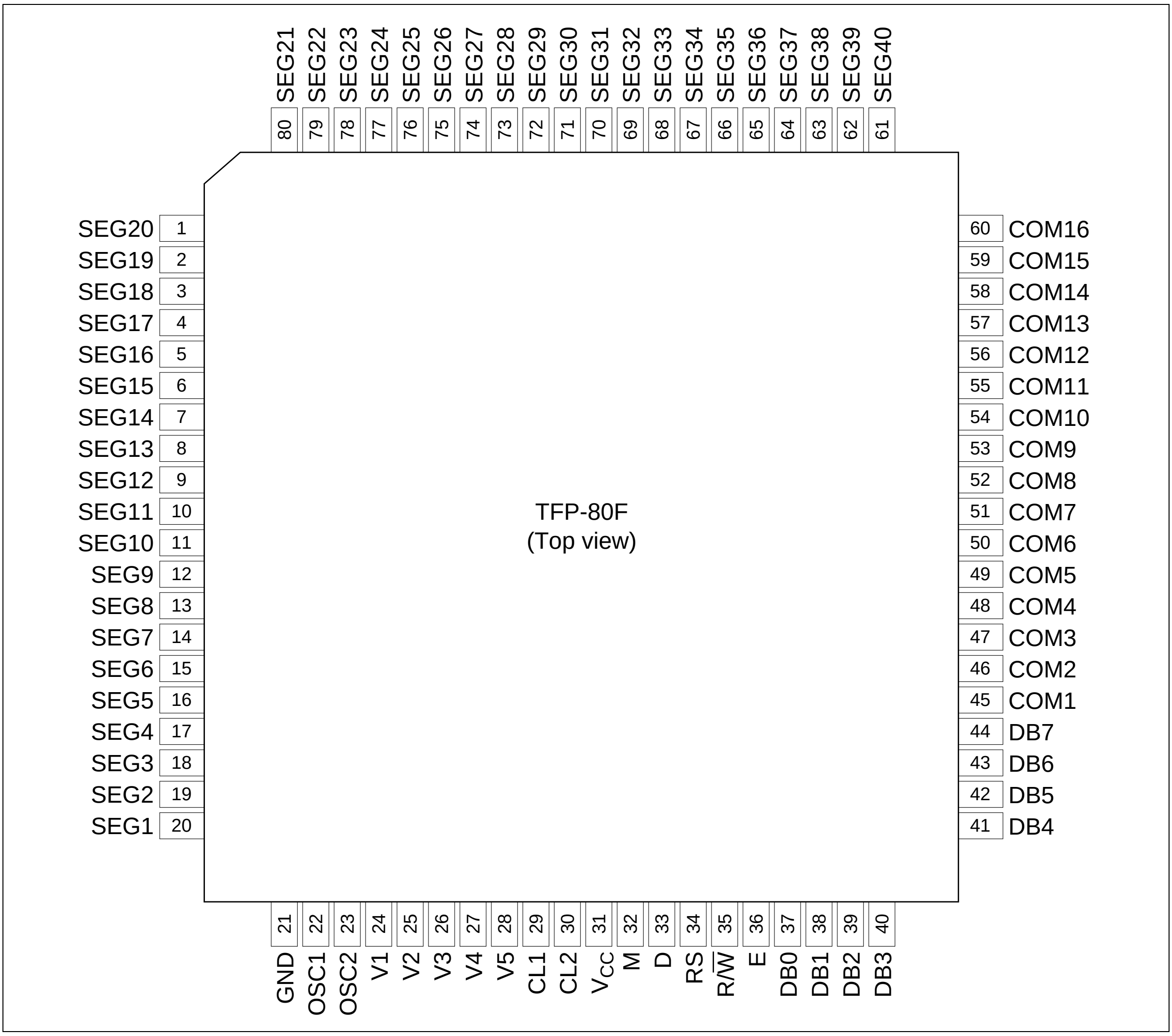
HD44780U Block Diagram



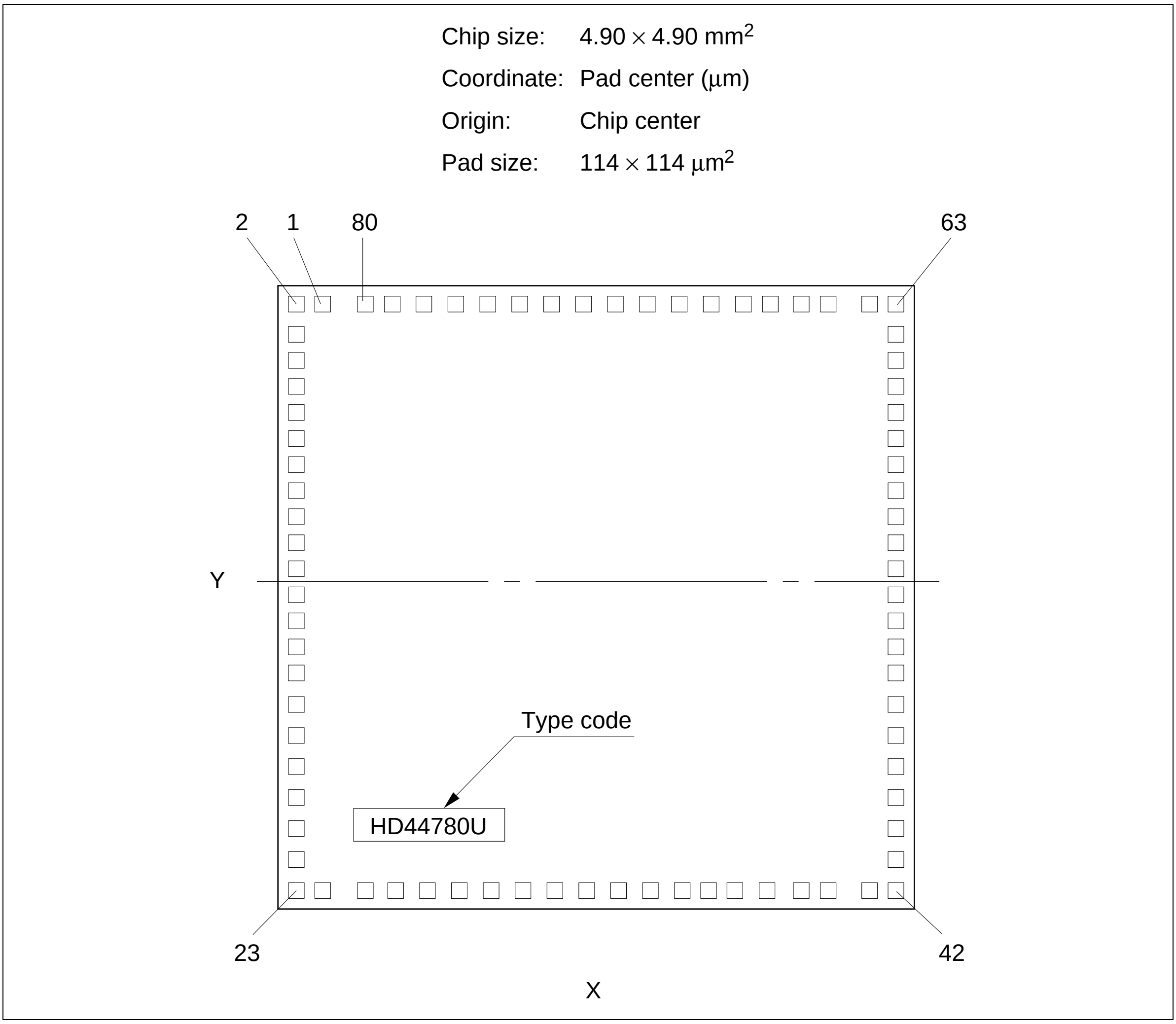
HD44780U Pin Arrangement (FP-80B)



HD44780U Pin Arrangement (TFP-80F)



HD44780U Pad Arrangement



HCD44780U Pad Location Coordinates

		Coordinate				Coordinate	
Pad No.	Function	X (um)	Y (um)	Pad No.	Function	X (um)	Y (um)
1	SEG22	–2100	2313	41	DB2	2070	–2290
2	SEG21	–2280	2313	42	DB3	2260	–2290
3	SEG20	–2313	2089	43	DB4	2290	–2099
4	SEG19	–2313	1833	44	DB5	2290	–1883
5	SEG18	–2313	1617	45	DB6	2290	–1667
6	SEG17	–2313	1401	46	DB7	2290	–1452
7	SEG16	–2313	1186	47	COM1	2313	–1186
8	SEG15	–2313	970	48	COM2	2313	–970
9	SEG14	–2313	755	49	COM3	2313	–755
10	SEG13	–2313	539	50	COM4	2313	–539
11	SEG12	–2313	323	51	COM5	2313	–323
12	SEG11	–2313	108	52	COM6	2313	–108
13	SEG10	–2313	–108	53	COM7	2313	108
14	SEG9	–2313	–323	54	COM8	2313	323
15	SEG8	–2313	–539	55	COM9	2313	539
16	SEG7	–2313	–755	56	COM10	2313	755
17	SEG6	–2313	–970	57	COM11	2313	970
18	SEG5	–2313	–1186	58	COM12	2313	1186
19	SEG4	–2313	–1401	59	COM13	2313	1401
20	SEG3	–2313	–1617	60	COM14	2313	1617
21	SEG2	–2313	–1833	61	COM15	2313	1833
22	SEG1	–2313	–2073	62	COM16	2313	2095
23	GND	–2280	–2290	63	SEG40	2296	2313
24	OSC1	–2080	–2290	64	SEG39	2100	2313
25	OSC2	–1749	–2290	65	SEG38	1617	2313
26	V1	–1550	–2290	66	SEG37	1401	2313
27	V2	–1268	–2290	67	SEG36	1186	2313
28	V3	–941	–2290	68	SEG35	970	2313
29	V4	–623	–2290	69	SEG34	755	2313
30	V5	–304	–2290	70	SEG33	539	2313
31	CL1	–48	–2290	71	SEG32	323	2313
32	CL2	142	–2290	72	SEG31	108	2313
33	V_{CC}	309	–2290	73	SEG30	–108	2313
34	M	475	–2290	74	SEG29	–323	2313
35	D	665	–2290	75	SEG28	–539	2313
36	RS	832	–2290	76	SEG27	–755	2313
37	R/$\overline{W}$	1022	–2290	77	SEG26	–970	2313
38	E	1204	–2290	78	SEG25	–1186	2313
39	DB0	1454	–2290	79	SEG24	–1401	2313
40	DB1	1684	–2290	80	SEG23	–1617	2313

Pin Functions

Signal	No. of Lines	I/O	Device Interfaced with	Function
RS	1	I	MPU	Selects registers. 0: Instruction register (for write) Busy flag: address counter (for read) 1: Data register (for write and read)
R/$\overline{W}$	1	I	MPU	Selects read or write. 0: Write 1: Read
E	1	I	MPU	Starts data read/write.
DB4 to DB7	4	I/O	MPU	Four high order bidirectional tristate data bus pins. Used for data transfer and receive between the MPU and the HD44780U. DB7 can be used as a busy flag.
DB0 to DB3	4	I/O	MPU	Four low order bidirectional tristate data bus pins. Used for data transfer and receive between the MPU and the HD44780U. These pins are not used during 4-bit operation.
CL1	1	O	Extension driver	Clock to latch serial data D sent to the extension driver
CL2	1	O	Extension driver	Clock to shift serial data D
M	1	O	Extension driver	Switch signal for converting the liquid crystal drive waveform to AC
D	1	O	Extension driver	Character pattern data corresponding to each segment signal
COM1 to COM16	16	O	LCD	Common signals that are not used are changed to non-selection waveforms. COM9 to COM16 are non-selection waveforms at 1/8 duty factor and COM12 to COM16 are non-selection waveforms at 1/11 duty factor.
SEG1 to SEG40	40	O	LCD	Segment signals
V1 to V5	5	—	Power supply	Power supply for LCD drive V_{CC} –V5 = 11 V (max)
V_{CC}, GND	2	—	Power supply	V_{CC}: 2.7V to 5.5V, GND: 0V
OSC1, OSC2	2	—	Oscillation resistor clock	When crystal oscillation is performed, a resistor must be connected externally. When the pin input is an external clock, it must be input to OSC1.

Function Description

Registers

The HD44780U has two 8-bit registers, an instruction register (IR) and a data register (DR).

The IR stores instruction codes, such as display clear and cursor shift, and address information for display data RAM (DDRAM) and character generator RAM (CGRAM). The IR can only be written from the MPU.

The DR temporarily stores data to be written into DDRAM or CGRAM and temporarily stores data to be read from DDRAM or CGRAM. Data written into the DR from the MPU is automatically written into DDRAM or CGRAM by an internal operation. The DR is also used for data storage when reading data from DDRAM or CGRAM. When address information is written into the IR, data is read and then stored into the DR from DDRAM or CGRAM by an internal operation. Data transfer between the MPU is then completed when the MPU reads the DR. After the read, data in DDRAM or CGRAM at the next address is sent to the DR for the next read from the MPU. By the register selector (RS) signal, these two registers can be selected (Table 1).

Busy Flag (BF)

When the busy flag is 1, the HD44780U is in the internal operation mode, and the next instruction will not be accepted. When RS = 0 and R/$\overline{W}$ = 1 (Table 1), the busy flag is output to DB7. The next instruction must be written after ensuring that the busy flag is 0.

Address Counter (AC)

The address counter (AC) assigns addresses to both DDRAM and CGRAM. When an address of an instruction is written into the IR, the address information is sent from the IR to the AC. Selection of either DDRAM or CGRAM is also determined concurrently by the instruction.

After writing into (reading from) DDRAM or CGRAM, the AC is automatically incremented by 1 (decremented by 1). The AC contents are then output to DB0 to DB6 when RS = 0 and R/$\overline{W}$ = 1 (Table 1).

Table 1 Register Selection

RS	R/$\overline{W}$	Operation
0	0	IR write as an internal operation (display clear, etc.)
0	1	Read busy flag (DB7) and address counter (DB0 to DB6)
1	0	DR write as an internal operation (DR to DDRAM or CGRAM)
1	1	DR read as an internal operation (DDRAM or CGRAM to DR)

Display Data RAM (DDRAM)

Display data RAM (DDRAM) stores display data represented in 8-bit character codes. Its extended capacity is 80 × 8 bits, or 80 characters. The area in display data RAM (DDRAM) that is not used for display can be used as general data RAM. See Figure 1 for the relationships between DDRAM addresses and positions on the liquid crystal display.

The DDRAM address (A_{DD}) is set in the address counter (AC) as hexadecimal.

- 1-line display (N = 0) (Figure 2)
  — When there are fewer than 80 display characters, the display begins at the head position. For example, if using only the HD44780, 8 characters are displayed. See Figure 3.
  When the display shift operation is performed, the DDRAM address shifts. See Figure 3.

	High order bits			Low order bits			
AC (hexadecimal)	AC6	AC5	AC4	AC3	AC2	AC1	AC0

Example: DDRAM address 4E

1	0	0	1	1	1	0

Figure 1 DDRAM Address

Display position (digit)	1	2	3	4	5		79	80
DDRAM address (hexadecimal)	00	01	02	03	04	. . . .	4E	4F

Figure 2 1-Line Display

Display position	1	2	3	4	5	6	7	8
DDRAM address	00	01	02	03	04	05	06	07
For shift left	01	02	03	04	05	06	07	08
For shift right	4F	00	01	02	03	04	05	06

Figure 3 1-Line by 8-Character Display Example

- 2-line display (N = 1) (Figure 4)
  - Case 1: When the number of display characters is less than 40 × 2 lines, the two lines are displayed from the head. Note that the first line end address and the second line start address are not consecutive. For example, when just the HD44780 is used, 8 characters × 2 lines are displayed. See Figure 5.

    When display shift operation is performed, the DDRAM address shifts. See Figure 5.

Display position	1	2	3	4	5		39	40
DDRAM address (hexadecimal)	00	01	02	03	04	. . . .	26	27
	40	41	42	43	44	. . . .	66	67

Figure 4 2-Line Display

Display position	1	2	3	4	5	6	7	8
DDRAM address	00	01	02	03	04	05	06	07
	40	41	42	43	44	45	46	47
For shift left	01	02	03	04	05	06	07	08
	41	42	43	44	45	46	47	48
For shift right	27	00	01	02	03	04	05	06
	67	40	41	42	43	44	45	46

Figure 5 2-Line by 8-Character Display Example

— Case 2: For a 16-character × 2-line display, the HD44780 can be extended using one 40-output extension driver. See Figure 6.

When display shift operation is performed, the DDRAM address shifts. See Figure 6.

Display position	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
DDRAM address	00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F
	40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F
	HD44780U display								Extension driver display							
For shift left	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F	10
	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F	50
For shift right	27	00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E
	67	40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E

Figure 6 2-Line by 16-Character Display Example

Character Generator ROM (CGROM)

The character generator ROM generates 5×8 dot or 5×10 dot character patterns from 8-bit character codes (Table 4). It can generate 208 5×8 dot character patterns and 32 5×10 dot character patterns. User-defined character patterns are also available by mask-programmed ROM.

Character Generator RAM (CGRAM)

In the character generator RAM, the user can rewrite character patterns by program. For 5×8 dots, eight character patterns can be written, and for 5×10 dots, four character patterns can be written.

Write into DDRAM the character codes at the addresses shown as the left column of Table 4 to show the character patterns stored in CGRAM.

See Table 5 for the relationship between CGRAM addresses and data and display patterns.

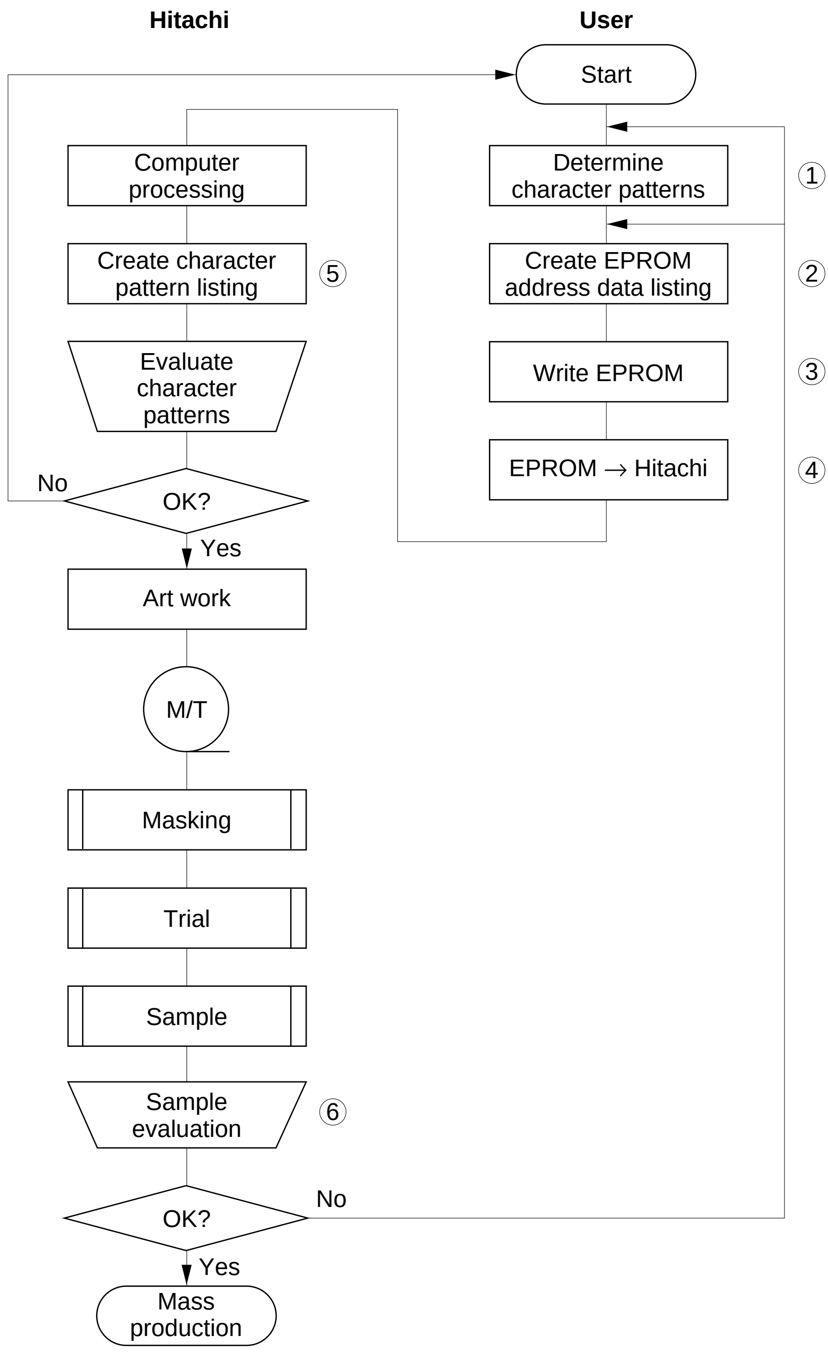
Areas that are not used for display can be used as general data RAM.

Modifying Character Patterns

- Character pattern development procedure

The following operations correspond to the numbers listed in Figure 7:

1. Determine the correspondence between character codes and character patterns.
2. Create a listing indicating the correspondence between EPROM addresses and data.
3. Program the character patterns into the EPROM.
4. Send the EPROM to Hitachi.
5. Computer processing on the EPROM is performed at Hitachi to create a character pattern listing, which is sent to the user.
6. If there are no problems within the character pattern listing, a trial LSI is created at Hitachi and samples are sent to the user for evaluation. When it is confirmed by the user that the character patterns are correctly written, mass production of the LSI proceeds at Hitachi.



Note: For a description of the numbers used in this figure, refer to the preceding page.

Figure 7 Character Pattern Development Procedure

- Programming character patterns

  This section explains the correspondence between addresses and data used to program character patterns in EPROM. The HD44780U character generator ROM can generate 208 5 × 8 dot character patterns and 32 5 × 10 dot character patterns for a total of 240 different character patterns.

  — Character patterns

  EPROM address data and character pattern data correspond with each other to form a 5 × 8 or 5 × 10 dot character pattern (Tables 2 and 3).

Table 2 Example of Correspondence between EPROM Address Data and Character Pattern (5 × 8 Dots)

EPROM Address												Data					
A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1	A0	O4	O3	O2	O1	O0 (LSB)	
								0	0	0	0	1	0	0	0	0	
								0	0	0	1	1	0	0	0	0	
								0	0	1	0	1	0	1	1	0	
								0	0	1	1	1	1	0	0	1	
								0	1	0	0	1	0	0	0	1	
								0	1	0	1	1	0	0	0	1	
								0	1	1	0	1	1	1	1	0	
0	1	1	0	0	0	1	0	0	1	1	1	0	0	0	0	0	← Cursor position
								1	0	0	0	0	0	0	0	0	
								1	0	0	1	0	0	0	0	0	
								1	0	1	0	0	0	0	0	0	
								1	0	1	1	0	0	0	0	0	
								1	1	0	0	0	0	0	0	0	
								1	1	0	1	0	0	0	0	0	
								1	1	1	0	0	0	0	0	0	
								1	1	1	1	0	0	0	0	0	
Character code								Line position									

Notes: 1. EPROM addresses A11 to A4 correspond to a character code.
2. EPROM addresses A3 to A0 specify a line position of the character pattern.
3. EPROM data O4 to O0 correspond to character pattern data.
4. EPROM data O5 to O7 must be specified as 0.
5. A lit display position (black) corresponds to a 1.
6. Line 9 and the following lines must be blanked with 0s for a 5 × 8 dot character fonts.

— Handling unused character patterns

1. EPROM data outside the character pattern area: Always input 0s.
2. EPROM data in CGRAM area: Always input 0s. (Input 0s to EPROM addresses 00H to FFH.)
3. EPROM data used when the user does not use any HD44780U character pattern: According to the user application, handled in one of the two ways listed as follows.
   a. When unused character patterns are not programmed: If an unused character code is written into DDRAM, all its dots are lit. By not programing a character pattern, all of its bits become lit. (This is due to the EPROM being filled with 1s after it is erased.)
   b. When unused character patterns are programmed as 0s: Nothing is displayed even if unused character codes are written into DDRAM. (This is equivalent to a space.)

Table 3 Example of Correspondence between EPROM Address Data and Character Pattern (5 × 10 Dots)

EPROM Address												Data				
A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1	A0	O4	O3	O2	O1	O0 (LSB)
								0	0	0	0	0	0	0	0	0
								0	0	0	1	0	0	0	0	0
								0	0	1	0	0	1	1	0	1
								0	0	1	1	1	0	0	1	1
								0	1	0	0	1	0	0	0	1
								0	1	0	1	1	0	0	0	1
								0	1	1	0	0	1	1	1	1
0	1	0	1	0	0	1	0	0	1	1	1	0	0	0	0	1
								1	0	0	0	0	0	0	0	1
								1	0	0	1	0	0	0	0	1
								1	0	1	0	0	0	0	0	0 ← Cursor position
								1	0	1	1	0	0	0	0	0
								1	1	0	0	0	0	0	0	0
								1	1	0	1	0	0	0	0	0
								1	1	1	0	0	0	0	0	0
								1	1	1	1	0	0	0	0	0

Character code (A11–A4); Line position (A3–A0)

Notes: 1. EPROM addresses A11 to A3 correspond to a character code.
2. EPROM addresses A3 to A0 specify a line position of the character pattern.
3. EPROM data O4 to O0 correspond to character pattern data.
4. EPROM data O5 to O7 must be specified as 0.
5. A lit display position (black) corresponds to a 1.
6. Line 11 and the following lines must be blanked with 0s for a 5 × 10 dot character fonts.

Table 4 Correspondence between Character Codes and Character Patterns (ROM Code: A00)

Lower 4 Bits \ Upper 4 Bits	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
xxxx0000	CG RAM (1)			0	@	P	`	p				ー	タ	ミ	α	p
xxxx0001	(2)		!	1	A	Q	a	q			。	ア	チ	ム	ä	q
xxxx0010	(3)		"	2	B	R	b	r			「	イ	ツ	メ	β	θ
xxxx0011	(4)		#	3	C	S	c	s			」	ウ	テ	モ	ε	∞
xxxx0100	(5)		$	4	D	T	d	t			、	エ	ト	ヤ	μ	Ω
xxxx0101	(6)		%	5	E	U	e	u			・	オ	ナ	ユ	σ	ü
xxxx0110	(7)		&	6	F	V	f	v			ヲ	カ	ニ	ヨ	ρ	Σ
xxxx0111	(8)		'	7	G	W	g	w			ァ	キ	ヌ	ラ	g	π
xxxx1000	(1)		(	8	H	X	h	x			ィ	ク	ネ	リ	√	x̄
xxxx1001	(2)		)	9	I	Y	i	y			ゥ	ケ	ノ	ル	⁻¹	y
xxxx1010	(3)		*	:	J	Z	j	z			ェ	コ	ハ	レ	j	千
xxxx1011	(4)		+	;	K	[	k	{			ォ	サ	ヒ	ロ	ˣ	万
xxxx1100	(5)		,	<	L	¥	l	|			ャ	シ	フ	ワ	¢	円
xxxx1101	(6)		-	=	M	]	m	}			ュ	ス	ヘ	ン	£	÷
xxxx1110	(7)		.	>	N	^	n	→			ョ	セ	ホ	゛	ñ	
xxxx1111	(8)		/	?	O	_	o	←			ッ	ソ	マ	゜	ö	█

Note: The user can specify any pattern for character-generator RAM.

Table 4 Correspondence between Character Codes and Character Patterns (ROM Code: A02)

Upper 4 Bits / Lower 4 Bits	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
xxxx0000	CG RAM (1)			0	@	P	`	p								
xxxx0001	(2)		!	1	A	Q	a	q								
xxxx0010	(3)		"	2	B	R	b	r								
xxxx0011	(4)		#	3	C	S	c	s								
xxxx0100	(5)		$	4	D	T	d	t								
xxxx0101	(6)		%	5	E	U	e	u								
xxxx0110	(7)		&	6	F	V	f	v								
xxxx0111	(8)		'	7	G	W	g	w								
xxxx1000	(1)		(	8	H	X	h	x								
xxxx1001	(2)		)	9	I	Y	i	y								
xxxx1010	(3)		*	:	J	Z	j	z								
xxxx1011	(4)		+	;	K	[	k	{								
xxxx1100	(5)		,	<	L	\	l	|								
xxxx1101	(6)		-	=	M	]	m	}								
xxxx1110	(7)		.	>	N	^	n	~								
xxxx1111	(8)		/	?	O	_	o									

Table 5 Relationship between CGRAM Addresses, Character Codes (DDRAM) and Character Patterns (CGRAM Data)

For 5 × 8 dot character patterns

Character Codes (DDRAM data) 7 6 5 4 3 2 1 0 (High … Low)	CGRAM Address 5 4 3 (High)	CGRAM Address 2 1 0 (Low)	Character Patterns (CGRAM data) 7 6 5 (High)	Character Patterns (CGRAM data) 4 3 2 1 0 (Low)	
		0 0 0	* * *	1 1 1 1 0	
		0 0 1		1 0 0 0 1	
		0 1 0		1 0 0 0 1	
0 0 0 0 * 0 0 0	0 0 0	0 1 1		1 1 1 1 0	Character pattern (1)
		1 0 0		1 0 1 0 0	
		1 0 1		1 0 0 1 0	
		1 1 0		1 0 0 0 1	
		1 1 1	* * *	0 0 0 0 0	Cursor position
		0 0 0	* * *	1 0 0 0 1	
		0 0 1		0 1 0 1 0	
		0 1 0		1 1 1 1 1	
0 0 0 0 * 0 0 1	0 0 1	0 1 1		0 0 1 0 0	Character pattern (2)
		1 0 0		1 1 1 1 1	
		1 0 1		0 0 1 0 0	
		1 1 0		0 0 1 0 0	
		1 1 1	* * *	0 0 0 0 0	Cursor position
		0 0 0	* * *		
		0 0 1			
0 0 0 0 * 1 1 1	1 1 1				
		1 0 0			
		1 0 1			
		1 1 0			
		1 1 1	* * *		

Notes: 1. Character code bits 0 to 2 correspond to CGRAM address bits 3 to 5 (3 bits: 8 types).

2. CGRAM address bits 0 to 2 designate the character pattern line position. The 8th line is the cursor position and its display is formed by a logical OR with the cursor.
Maintain the 8th line data, corresponding to the cursor display position, at 0 as the cursor display.
If the 8th line data is 1, 1 bits will light up the 8th line regardless of the cursor presence.

3. Character pattern row positions correspond to CGRAM data bits 0 to 4 (bit 4 being at the left).

4. As shown Table 5, CGRAM character patterns are selected when character code bits 4 to 7 are all 0. However, since character code bit 3 has no effect, the R display example above can be selected by either character code 00H or 08H.

5. 1 for CGRAM data corresponds to display selection and 0 to non-selection.

* Indicates no effect.

Table 5 Relationship between CGRAM Addresses, Character Codes (DDRAM) and Character Patterns (CGRAM Data) (cont)

For 5 × 10 dot character patterns

Character Codes (DDRAM data)	CGRAM Address		Character Patterns (CGRAM data)		
7 6 5 4 3 2 1 0 High Low	5 4 3 2 1 0 High Low		7 6 5 4 3 2 1 0 High Low		
		0 0 0 0	* * *	0 0 0 0 0	Character pattern
		0 0 0 1		0 0 0 0 0	
		0 0 1 0		1 0 1 1 0	
		0 0 1 1		1 1 0 0 1	
		0 1 0 0		1 0 0 0 1	
0 0 0 0 * 0 0 *	0 0	0 1 0 1		1 0 0 0 1	
		0 1 1 0		1 1 1 1 0	
		0 1 1 1		1 0 0 0 0	
		1 0 0 0		1 0 0 0 0	
		1 0 0 1		1 0 0 0 0	
		1 0 1 0	* * *	0 0 0 0 0	Cursor position
		1 0 1 1	* * *	* * * * *	
		1 1 0 0			
		1 1 0 1			
		1 1 1 0			
		1 1 1 1	* * *	* * * * *	
		0 0 0 0	* * *		
		0 0 0 1			
0 0 0 0 * 1 1 *	1 1	1 0 0 1			
		1 0 1 0	* * *		
		1 0 1 1	* * *	* * * * *	
		1 1 0 0			
		1 1 0 1			
		1 1 1 0			
		1 1 1 1	* * *	* * * * *	

Notes: 1. Character code bits 1 and 2 correspond to CGRAM address bits 4 and 5 (2 bits: 4 types).

2. CGRAM address bits 0 to 3 designate the character pattern line position. The 11th line is the cursor position and its display is formed by a logical OR with the cursor.

Maintain the 11th line data corresponding to the cursor display positon at 0 as the cursor display.

If the 11th line data is “1”, “1” bits will light up the 11th line regardless of the cursor presence.

Since lines 12 to 16 are not used for display, they can be used for general data RAM.

3. Character pattern row positions are the same as 5 × 8 dot character pattern positions.

4. CGRAM character patterns are selected when character code bits 4 to 7 are all 0.

However, since character code bits 0 and 3 have no effect, the P display example above can be selected by character codes 00H, 01H, 08H, and 09H.

5. 1 for CGRAM data corresponds to display selection and 0 to non-selection.

* Indicates no effect.

Timing Generation Circuit

The timing generation circuit generates timing signals for the operation of internal circuits such as DDRAM, CGROM and CGRAM. RAM read timing for display and internal operation timing by MPU access are generated separately to avoid interfering with each other. Therefore, when writing data to DDRAM, for example, there will be no undesirable interferences, such as flickering, in areas other than the display area.

Liquid Crystal Display Driver Circuit

The liquid crystal display driver circuit consists of 16 common signal drivers and 40 segment signal drivers. When the character font and number of lines are selected by a program, the required common signal drivers automatically output drive waveforms, while the other common signal drivers continue to output non-selection waveforms.

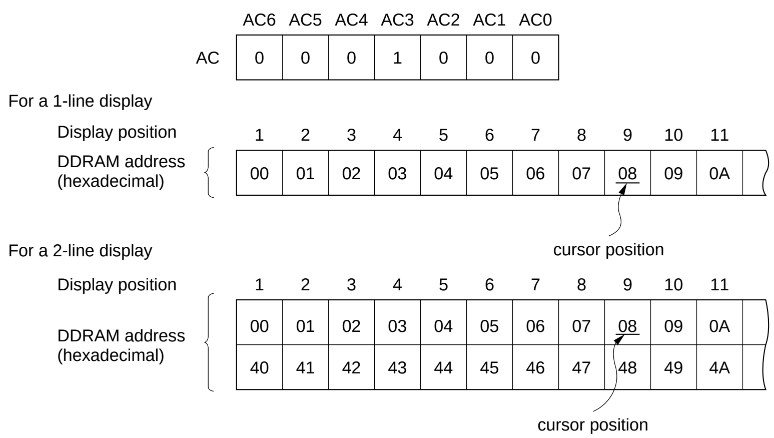
Sending serial data always starts at the display data character pattern corresponding to the last address of the display data RAM (DDRAM).

Since serial data is latched when the display data character pattern corresponding to the starting address enters the internal shift register, the HD44780U drives from the head display.

Cursor/Blink Control Circuit

The cursor/blink control circuit generates the cursor or character blinking. The cursor or the blinking will appear with the digit located at the display data RAM (DDRAM) address set in the address counter (AC).

For example (Figure 8), when the address counter is 08H, the cursor position is displayed at DDRAM address 08H.



Note: The cursor or blinking appears when the address counter (AC) selects the character generator RAM (CGRAM). However, the cursor and blinking become meaningless. The cursor or blinking is displayed in the meaningless position when the AC is a CGRAM address.

Figure 8 Cursor/Blink Display Example

Interfacing to the MPU

The HD44780U can send data in either two 4-bit operations or one 8-bit operation, thus allowing interfacing with 4- or 8-bit MPUs.

- For 4-bit interface data, only four bus lines (DB4 to DB7) are used for transfer. Bus lines DB0 to DB3 are disabled. The data transfer between the HD44780U and the MPU is completed after the 4-bit data has been transferred twice. As for the order of data transfer, the four high order bits (for 8-bit operation, DB4 to DB7) are transferred before the four low order bits (for 8-bit operation, DB0 to DB3).

  The busy flag must be checked (one instruction) after the 4-bit data has been transferred twice. Two more 4-bit operations then transfer the busy flag and address counter data.
- For 8-bit interface data, all eight bus lines (DB0 to DB7) are used.

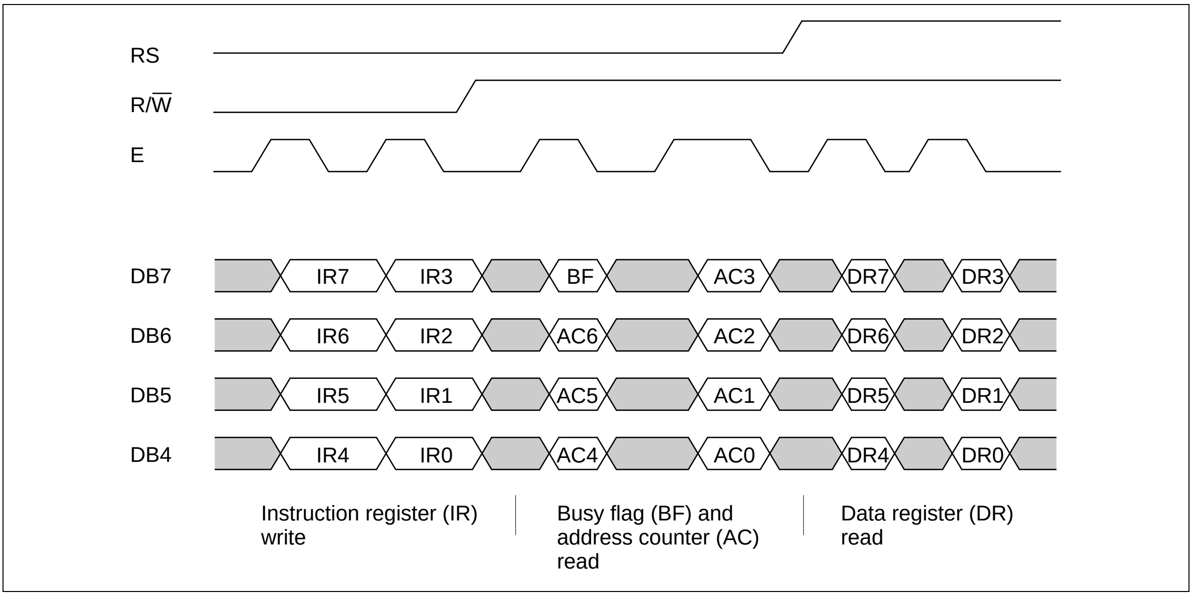


Figure 9 4-Bit Transfer Example

Reset Function

Initializing by Internal Reset Circuit

An internal reset circuit automatically initializes the HD44780U when the power is turned on. The following instructions are executed during the initialization. The busy flag (BF) is kept in the busy state until the initialization ends (BF = 1). The busy state lasts for 10 ms after V_{CC} rises to 4.5 V.

1. Display clear
2. Function set:
   DL = 1; 8-bit interface data
   N = 0; 1-line display
   F = 0; 5 × 8 dot character font
3. Display on/off control:
   D = 0; Display off
   C = 0; Cursor off
   B = 0; Blinking off
4. Entry mode set:
   I/D = 1; Increment by 1
   S = 0; No shift

Note: If the electrical characteristics conditions listed under the table Power Supply Conditions Using Internal Reset Circuit are not met, the internal reset circuit will not operate normally and will fail to initialize the HD44780U. For such a case, initial-ization must be performed by the MPU as explained in the section, Initializing by Instruction.

Instructions

Outline

Only the instruction register (IR) and the data register (DR) of the HD44780U can be controlled by the MPU. Before starting the internal operation of the HD44780U, control information is temporarily stored into these registers to allow interfacing with various MPUs, which operate at different speeds, or various peripheral control devices. The internal operation of the HD44780U is determined by signals sent from the MPU. These signals, which include register selection signal (RS), read/

write signal (R/$\overline{W}$), and the data bus (DB0 to DB7), make up the HD44780U instructions (Table 6). There are four categories of instructions that:

- Designate HD44780U functions, such as display format, data length, etc.
- Set internal RAM addresses
- Perform data transfer with internal RAM
- Perform miscellaneous functions

Normally, instructions that perform data transfer with internal RAM are used the most. However, auto-incrementation by 1 (or auto-decrementation by 1) of internal HD44780U RAM addresses after each data write can lighten the program load of the MPU. Since the display shift instruction (Table 11) can perform concurrently with display data write, the user can minimize system development time with maximum programming efficiency.

When an instruction is being executed for internal operation, no instruction other than the busy flag/address read instruction can be executed.

Because the busy flag is set to 1 while an instruction is being executed, check it to make sure it is 0 before sending another instruction from the MPU.

Note: Be sure the HD44780U is not in the busy state (BF = 0) before sending an instruction from the MPU to the HD44780U. If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself. Refer to Table 6 for the list of each instruc-tion execution time.

Table 6 Instructions

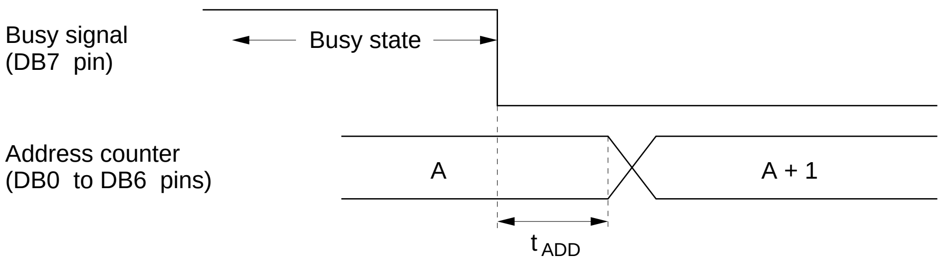
	Code											
Instruction	**RS**	**R/$\overline{W}$**	**DB7**	**DB6**	**DB5**	**DB4**	**DB3**	**DB2**	**DB1**	**DB0**	**Description**	**Execution Time (max) (when f_{cp} or f_{OSC} is 270 kHz)**
Clear display	0	0	0	0	0	0	0	0	0	1	Clears entire display and sets DDRAM address 0 in address counter.	
Return home	0	0	0	0	0	0	0	0	1	—	Sets DDRAM address 0 in address counter. Also returns display from being shifted to original position. DDRAM contents remain unchanged.	1.52 ms
Entry mode set	0	0	0	0	0	0	0	1	I/D	S	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.	37 µs
Display on/off control	0	0	0	0	0	0	1	D	C	B	Sets entire display (D) on/off, cursor on/off (C), and blinking of cursor position character (B).	37 µs
Cursor or display shift	0	0	0	0	0	1	S/C	R/L	—	—	Moves cursor and shifts display without changing DDRAM contents.	37 µs
Function set	0	0	0	0	1	DL	N	F	—	—	Sets interface data length (DL), number of display lines (N), and character font (F).	37 µs
Set CGRAM address	0	0	0	1	ACG	ACG	ACG	ACG	ACG	ACG	Sets CGRAM address. CGRAM data is sent and received after this setting.	37 µs
Set DDRAM address	0	0	1	ADD	ADD	ADD	ADD	ADD	ADD	ADD	Sets DDRAM address. DDRAM data is sent and received after this setting.	37 µs
Read busy flag & address	0	1	BF	AC	AC	AC	AC	AC	AC	AC	Reads busy flag (BF) indicating internal operation is being performed and reads address counter contents.	0 µs

Table 6 Instructions (cont)

Instruction	Code RS	R/$\overline{W}$	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description	Execution Time (max) (when f_{cp} or f_{OSC} is 270 kHz)
Write data to CG or DDRAM	1	0	Write data								Writes data into DDRAM or CGRAM.	37 µs t_{ADD} = 4 µs*
Read data from CG or DDRAM	1	1	Read data								Reads data from DDRAM or CGRAM.	37 µs t_{ADD} = 4 µs*
	I/D = 1: I/D = 0: S = 1: S/C = 1: S/C = 0: R/L = 1: R/L = 0: DL = 1: N = 1: F = 1: BF = 1: BF = 0:		Increment Decrement Accompanies display shift Display shift Cursor move Shift to the right Shift to the left 8 bits, DL = 0: 4 bits 2 lines, N = 0: 1 line 5 × 10 dots, F = 0: 5 × 8 dots Internally operating Instructions acceptable								DDRAM: Display data RAM CGRAM: Character generator RAM ACG: CGRAM address ADD: DDRAM address (corresponds to cursor address) AC: Address counter used for both DD and CGRAM addresses	Execution time changes when frequency changes Example: When f_{cp} or f_{OSC} is 250 kHz, $37\ \mu s \times \frac{270}{250} = 40\ \mu s$

Note: — indicates no effect.

* After execution of the CGRAM/DDRAM data write or read instruction, the RAM address counter is incremented or decremented by 1. The RAM address counter is updated after the busy flag turns off. In Figure 10, t_{ADD} is the time elapsed after the busy flag turns off until the address counter is updated.



Note: t_{ADD} depends on the operation frequency
$t_{ADD} = 1.5/(f_{cp}$ or $f_{OSC})$ seconds

Figure 10 Address Counter Update

Instruction Description

Clear Display

Clear display writes space code 20H (character pattern for character code 20H must be a blank pattern) into all DDRAM addresses. It then sets DDRAM address 0 into the address counter, and returns the display to its original status if it was shifted. In other words, the display disappears and the cursor or blinking goes to the left edge of the display (in the first line if 2 lines are displayed). It also sets I/D to 1 (increment mode) in entry mode. S of entry mode does not change.

Return Home

Return home sets DDRAM address 0 into the address counter, and returns the display to its original status if it was shifted. The DDRAM contents do not change.

The cursor or blinking go to the left edge of the display (in the first line if 2 lines are displayed).

Entry Mode Set

I/D: Increments (I/D = 1) or decrements (I/D = 0) the DDRAM address by 1 when a character code is written into or read from DDRAM.

The cursor or blinking moves to the right when incremented by 1 and to the left when decremented by 1. The same applies to writing and reading of CGRAM.

S: Shifts the entire display either to the right (I/D = 0) or to the left (I/D = 1) when S is 1. The display does not shift if S is 0.

If S is 1, it will seem as if the cursor does not move but the display does. The display does not shift when reading from DDRAM. Also, writing into or reading out from CGRAM does not shift the display.

Display On/Off Control

D: The display is on when D is 1 and off when D is 0. When off, the display data remains in DDRAM, but can be displayed instantly by setting D to 1.

C: The cursor is displayed when C is 1 and not displayed when C is 0. Even if the cursor disappears, the function of I/D or other specifications will not change during display data write. The cursor is displayed using 5 dots in the 8th line for 5 × 8 dot character font selection and in the 11th line for the 5 × 10 dot character font selection (Figure 13).

B: The character indicated by the cursor blinks when B is 1 (Figure 13). The blinking is displayed as switching between all blank dots and displayed characters at a speed of 409.6-ms intervals when f_{cp} or f_{OSC} is 250 kHz. The cursor and blinking can be set to display simultaneously. (The blinking frequency changes according to f_{OSC} or the reciprocal of f_{cp}. For example, when f_{cp} is 270 kHz, 409.6 × 250/270 = 379.2 ms.)

Cursor or Display Shift

Cursor or display shift shifts the cursor position or display to the right or left without writing or reading display data (Table 7). This function is used to correct or search the display. In a 2-line display, the cursor moves to the second line when it passes the 40th digit of the first line. Note that the first and second line displays will shift at the same time.

When the displayed data is shifted repeatedly each line moves only horizontally. The second line display does not shift into the first line position.

The address counter (AC) contents will not change if the only action performed is a display shift.

Function Set

DL: Sets the interface data length. Data is sent or received in 8-bit lengths (DB7 to DB0) when DL is 1, and in 4-bit lengths (DB7 to DB4) when DL is 0.When 4-bit length is selected, data must be sent or received twice.

N: Sets the number of display lines.

F: Sets the character font.

Note: Perform the function at the head of the program before executing any instructions (except for the read busy flag and address instruction). From this point, the function set instruction cannot be executed unless the interface data length is changed.

Set CGRAM Address

Set CGRAM address sets the CGRAM address binary AAAAAA into the address counter.

Data is then written to or read from the MPU for CGRAM.

Instruction		RS	R/$\overline{W}$	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	
Clear display	Code	0	0	0	0	0	0	0	0	0	1	
Return home	Code	0	0	0	0	0	0	0	0	1	*	Note: * Don't care.
Entry mode set	Code	0	0	0	0	0	0	0	1	I/D	S	
Display on/off control	Code	0	0	0	0	0	0	1	D	C	B	
Cursor or display shift	Code	0	0	0	0	0	1	S/C	R/L	*	*	Note: * Don't care.
Function set	Code	0	0	0	0	1	DL	N	F	*	*	
Set CGRAM address	Code	0	0	0	1	A	A	A	A	A	A	

← Higher order bit   Lower order bit →

Figure 11 Instruction (1)

Set DDRAM Address

Set DDRAM address sets the DDRAM address binary AAAAAAA into the address counter.

Data is then written to or read from the MPU for DDRAM.

However, when N is 0 (1-line display), AAAAAAA can be 00H to 4FH. When N is 1 (2-line display), AAAAAAA can be 00H to 27H for the first line, and 40H to 67H for the second line.

Read Busy Flag and Address

Read busy flag and address reads the busy flag (BF) indicating that the system is now internally operating on a previously received instruction. If BF is 1, the internal operation is in progress. The next instruction will not be accepted until BF is reset to 0. Check the BF status before the next write operation. At the same time, the value of the address counter in binary AAAAAAA is read out. This address counter is used by both CG and DDRAM addresses, and its value is determined by the previous instruction. The address contents are the same as for instructions set CGRAM address and set DDRAM address.

Table 7 Shift Function

S/C	R/L	
0	0	Shifts the cursor position to the left. (AC is decremented by one.)
0	1	Shifts the cursor position to the right. (AC is incremented by one.)
1	0	Shifts the entire display to the left. The cursor follows the display shift.
1	1	Shifts the entire display to the right. The cursor follows the display shift.

Table 8 Function Set

N	F	No. of Display Lines	Character Font	Duty Factor	Remarks
0	0	1	5×8 dots	1/8	
0	1	1	5×10 dots	1/11	
1	*	2	5×8 dots	1/16	Cannot display two lines for 5×10 dot character font

Note: * Indicates don't care.

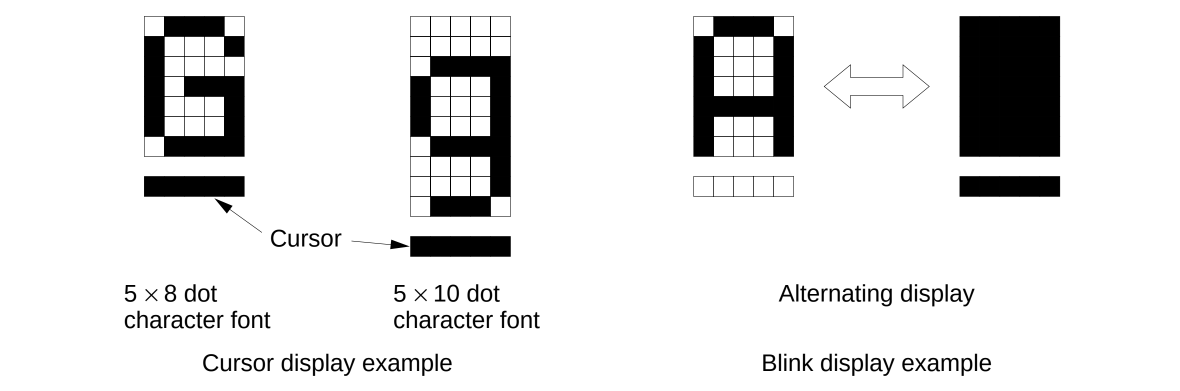


Figure 12 Cursor and Blinking

Set DDRAM address

	RS	R/$\overline{W}$	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Code	0	0	1	A	A	A	A	A	A	A

← Higher order bit Lower order bit →

Read busy flag and address

	RS	R/$\overline{W}$	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Code	0	1	BF	A	A	A	A	A	A	A

← Higher order bit Lower order bit →

Figure 13 Instruction (2)

Write Data to CG or DDRAM

Write data to CG or DDRAM writes 8-bit binary data DDDDDDDD to CG or DDRAM.

To write into CG or DDRAM is determined by the previous specification of the CGRAM or DDRAM address setting. After a write, the address is automatically incremented or decremented by 1 according to the entry mode. The entry mode also determines the display shift.

Read Data from CG or DDRAM

Read data from CG or DDRAM reads 8-bit binary data DDDDDDDD from CG or DDRAM.

The previous designation determines whether CG or DDRAM is to be read. Before entering this read instruction, either CGRAM or DDRAM address set instruction must be executed. If not executed, the first read data will be invalid. When serially executing read instructions, the next address data is normally read from the second read. The address set instructions need not be executed just before this read instruction when shifting the cursor by the cursor shift instruction (when reading out DDRAM). The operation of the cursor shift instruction is the same as the set DDRAM address instruction.

After a read, the entry mode automatically increases or decreases the address by 1. However, display shift is not executed regardless of the entry mode.

Note: The address counter (AC) is automatically incremented or decremented by 1 after the write instructions to CGRAM or DDRAM are executed. The RAM data selected by the AC cannot be read out at this time even if read instructions are executed. Therefore, to correctly read data, execute either the address set instruction or cursor shift instruction (only with DDRAM), then just before reading the desired data, execute the read instruction from the second time the read instruction is sent.

		RS	R/$\overline{W}$	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Write data to CG or DDRAM	Code	1	0	D	D	D	D	D	D	D	D
			← Higher order bits							Lower order bits →	

		RS	R/$\overline{W}$	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Read data from CG or DDRAM	Code	1	1	D	D	D	D	D	D	D	D
			← Higher order bits							Lower order bits →	

Figure 14 Instruction (3)

Interfacing the HD44780U

Interface to MPUs

- Interfacing to an 8-bit MPU

  See Figure 16 for an example of using a I/O port (for a single-chip microcomputer) as an interface device.

  In this example, P30 to P37 are connected to the data bus DB0 to DB7, and P75 to P77 are connected to E, R/$\overline{\text{W}}$, and RS, respectively.

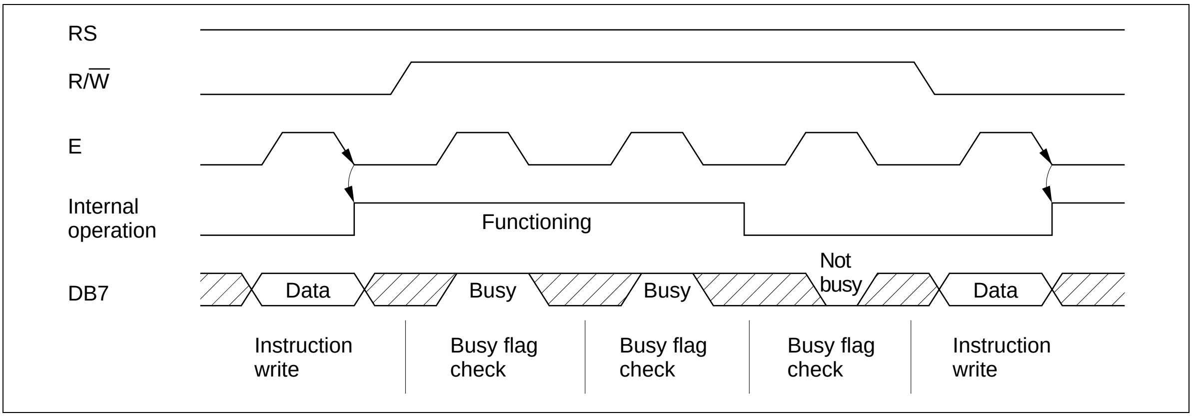


Figure 15 Example of Busy Flag Check Timing Sequence

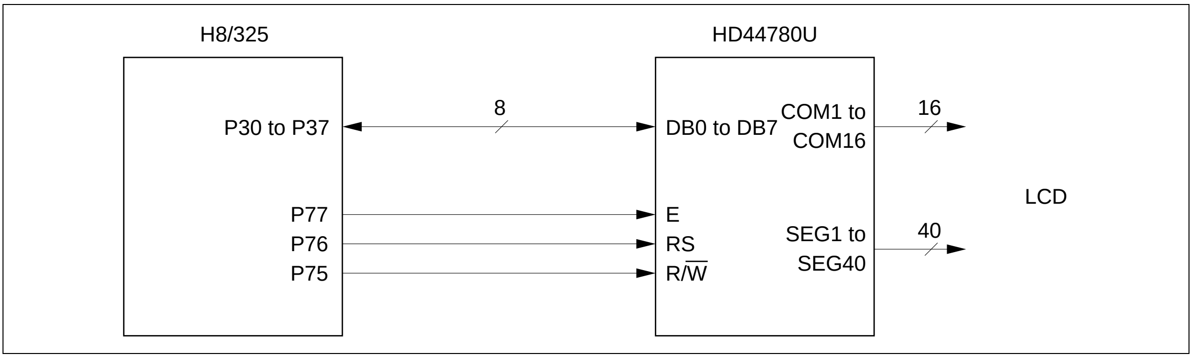


Figure 16 H8/325 Interface (Single-Chip Mode)

- Interfacing to a 4-bit MPU

  The HD44780U can be connected to the I/O port of a 4-bit MPU. If the I/O port has enough bits, 8-bit data can be transferred. Otherwise, one data transfer must be made in two operations for 4-bit data. In this case, the timing sequence becomes somewhat complex. (See Figure 17.)

  See Figure 18 for an interface example to the HMCS4019R.

  Note that two cycles are needed for the busy flag check as well as for the data transfer. The 4-bit operation is selected by the program.

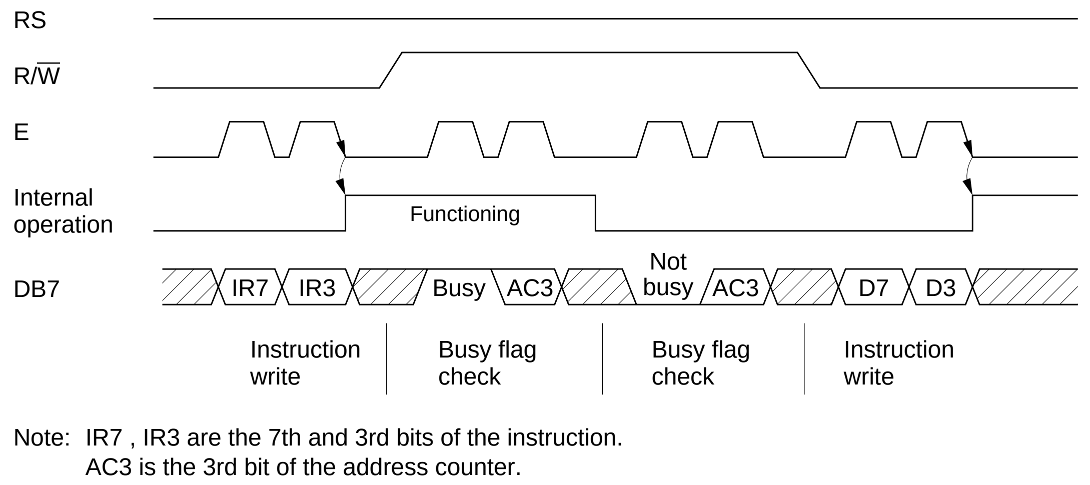


Figure 17 Example of 4-Bit Data Transfer Timing Sequence

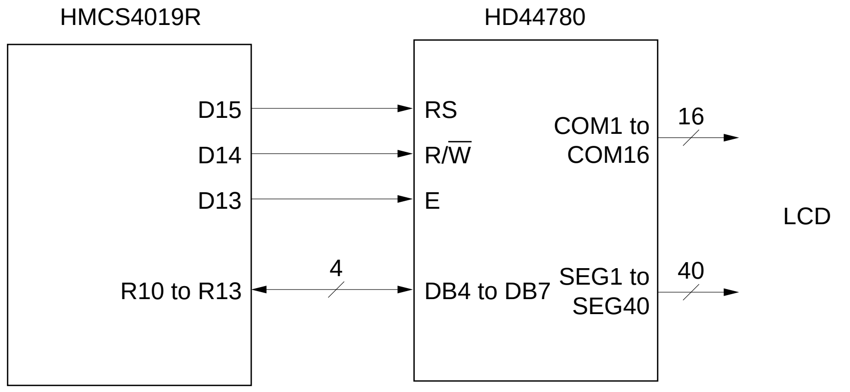


Figure 18 Example of Interface to HMCS4019R

Interface to Liquid Crystal Display

Character Font and Number of Lines: The HD44780U can perform two types of displays, 5 × 8 dot and 5 × 10 dot character fonts, each with a cursor.

Up to two lines are displayed for 5 × 8 dots and one line for 5 × 10 dots. Therefore, a total of three

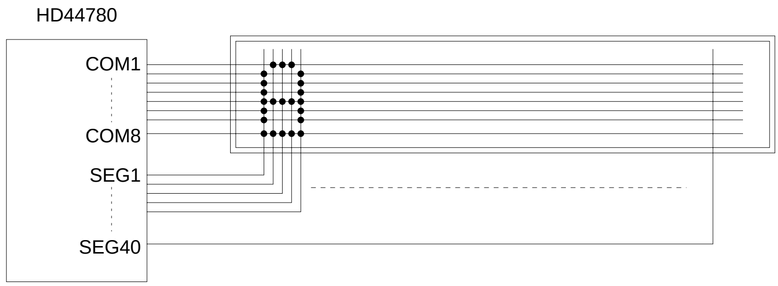
types of common signals are available (Table 9).

The number of lines and font types can be selected by the program. (See Table 6, Instructions.)

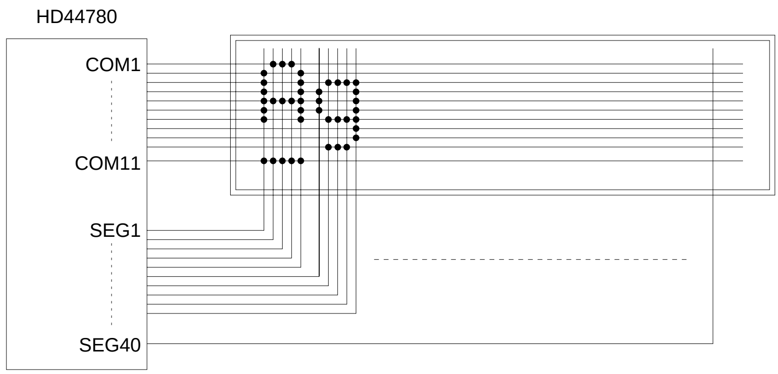
Connection to HD44780 and Liquid Crystal Display: See Figure 19 for the connection examples.

Table 9 Common Signals

Number of Lines	Character Font	Number of Common Signals	Duty Factor
1	5 × 8 dots + cursor	8	1/8
1	5 × 10 dots + cursor	11	1/11
2	5 × 8 dots + cursor	16	1/16



Example of a 5 × 8 dot, 8-character × 1-line display (1/4 bias, 1/8 duty cycle)

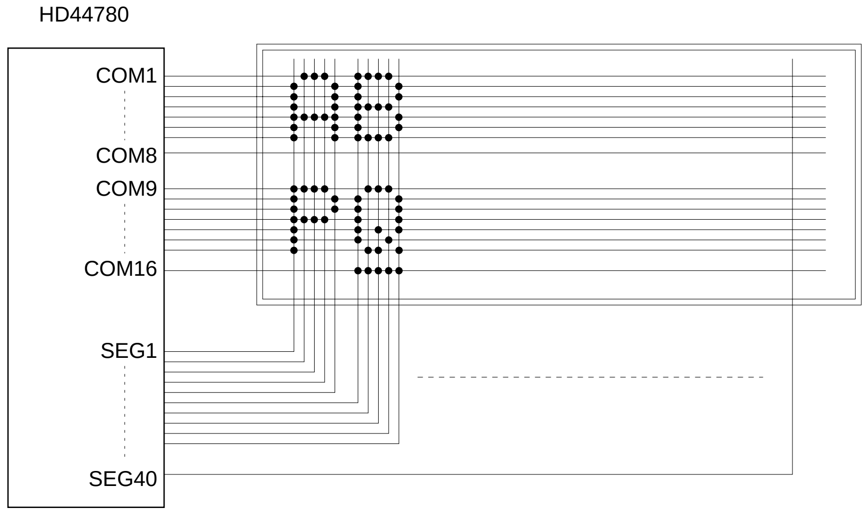


Example of a 5 × 10 dot, 8-character × 1-line display (1/4 bias, 1/11 duty cycle)

Figure 19 Liquid Crystal Display and HD44780 Connections

Since five segment signal lines can display one digit, one HD44780U can display up to 8 digits for a 1-line display and 16 digits for a 2-line display.

The examples in Figure 19 have unused common signal pins, which always output non-selection waveforms. When the liquid crystal display panel has unused extra scanning lines, connect the extra scanning lines to these common signal pins to avoid any undesirable effects due to crosstalk during the floating state.



Example of a 5 × 8 dot, 8-character × 2-line display (1/5 bias, 1/16 duty cycle)

Figure 19 Liquid Crystal Display and HD44780 Connections (cont)

Connection of Changed Matrix Layout: In the preceding examples, the number of lines correspond to the scanning lines. However, the following display examples (Figure 20) are made possible by altering the matrix layout of the liquid crystal display panel. In either case, the only change is the layout. The display characteristics and the number of liquid crystal display characters depend on the number of common signals or on duty factor. Note that the display data RAM (DDRAM) addresses for 4 characters × 2 lines and for 16 characters × 1 line are the same as in Figure 19.

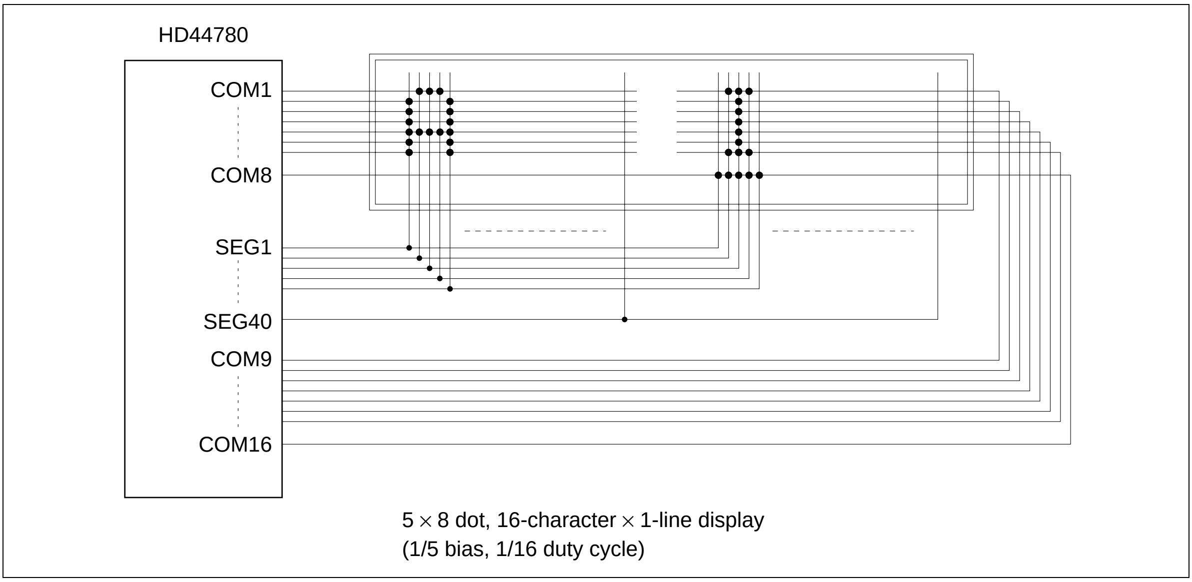


Figure 20 Changed Matrix Layout Displays

Power Supply for Liquid Crystal Display Drive

Various voltage levels must be applied to pins V1 to V5 of the HD44780U to obtain the liquid crystal display drive waveforms. The voltages must be changed according to the duty factor (Table 10).

VLCD is the peak value for the liquid crystal display drive waveforms, and resistance dividing provides voltages V1 to V5 (Figure 21).

Table 10 Duty Factor and Power Supply for Liquid Crystal Display Drive

	Duty Factor	
	1/8, 1/11	**1/16**
	Bias	
Power Supply	**1/4**	**1/5**
V1	V_{CC}–1/4 VLCD	V_{CC}–1/5 VLCD
V2	V_{CC}–1/2 VLCD	V_{CC}–2/5 VLCD
V3	V_{CC}–1/2 VLCD	V_{CC}–3/5 VLCD
V4	V_{CC}–3/4 VLCD	V_{CC}–4/5 VLCD
V5	V_{CC}–VLCD	V_{CC}–VLCD

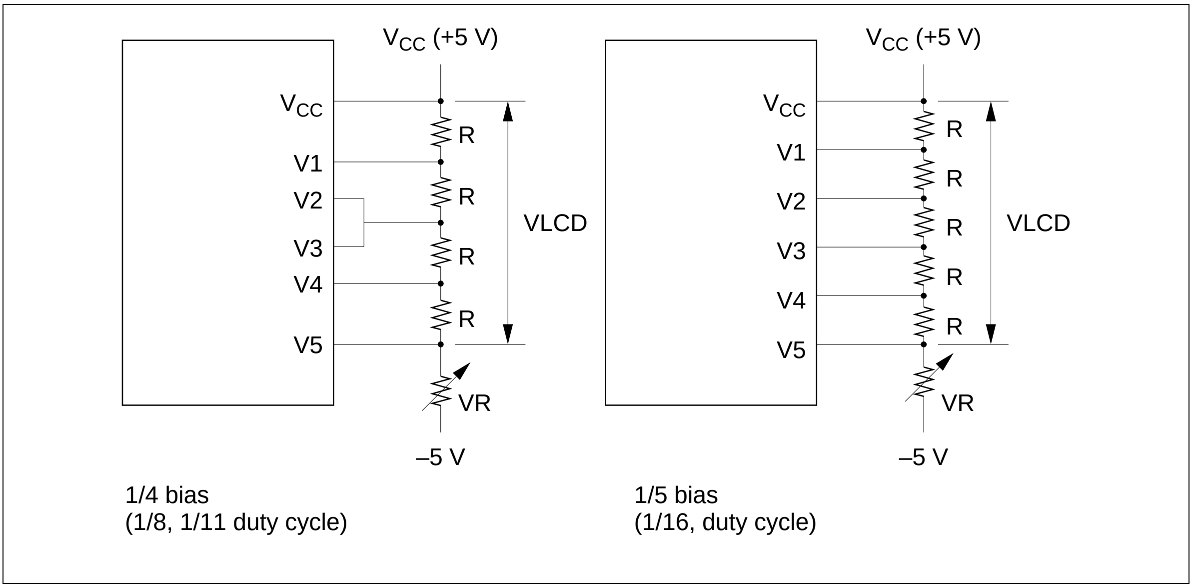
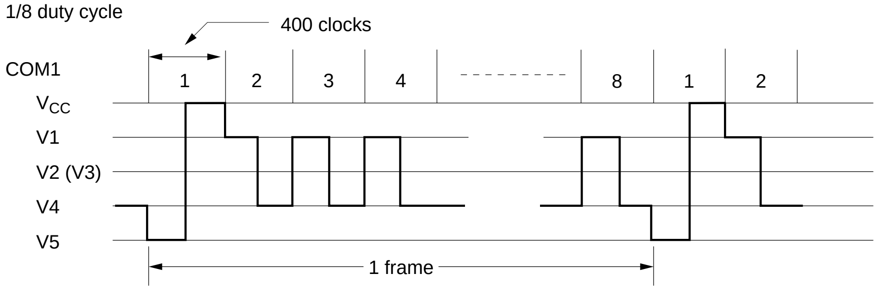


Figure 21 Drive Voltage Supply Example

Relationship between Oscillation Frequency and Liquid Crystal Display Frame Frequency

The liquid crystal display frame frequencies of Figure 22 apply only when the oscillation frequency is 270 kHz (one clock pulse of 3.7 µs).

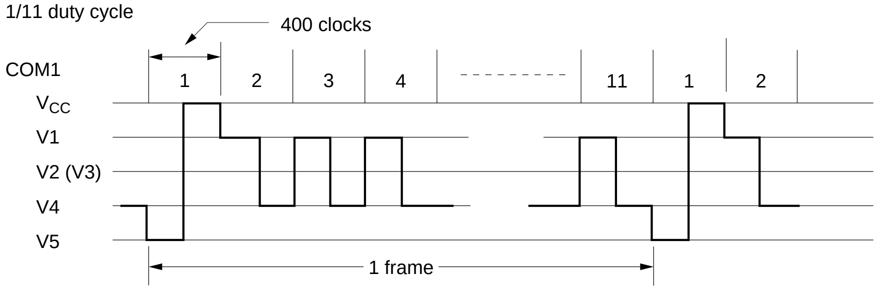
1/8 duty cycle



1 frame = 3.7 µs × 400 × 8 = 11850 µs = 11.9 ms

Frame frequency = $\frac{1}{11.9\text{ ms}}$ = 84.3 Hz

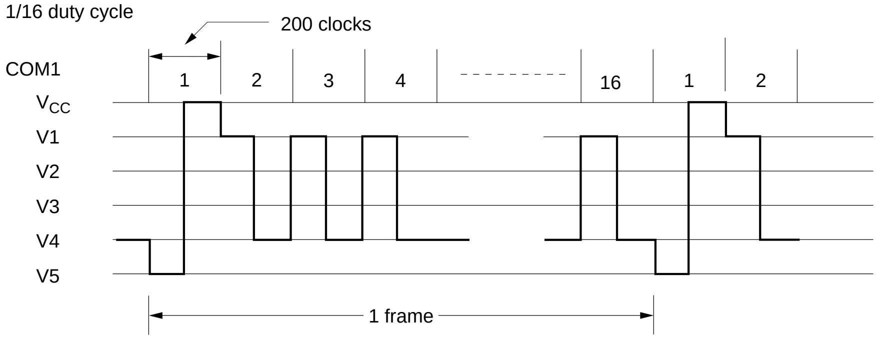
1/11 duty cycle



1 frame = 3.7 µs × 400 × 11 = 16300 µs = 16.3 ms

Frame frequency = $\frac{1}{16.3\text{ ms}}$ = 61.4 Hz

1/16 duty cycle



1 frame = 3.7 µs × 200 × 16 = 11850 µs = 11.9 ms

Frame frequency = $\frac{1}{11.9\text{ ms}}$ = 84.3 Hz

Figure 22 Frame Frequency

Instruction and Display Correspondence

- 8-bit operation, 8-digit × 1-line display with internal reset

  Refer to Table 11 for an example of an 8-digit × 1-line display in 8-bit operation. The HD44780U functions must be set by the function set instruction prior to the display. Since the display data RAM can store data for 80 characters, as explained before, the RAM can be used for displays such as for advertising when combined with the display shift operation.

  Since the display shift operation changes only the display position with DDRAM contents unchanged, the first display data entered into DDRAM can be output when the return home operation is performed.

- 4-bit operation, 8-digit × 1-line display with internal reset

  The program must set all functions prior to the 4-bit operation (Table 12). When the power is turned on, 8-bit operation is automatically selected and the first write is performed as an 8-bit operation. Since DB0 to DB3 are not connected, a rewrite is then required. However, since one operation is completed in two accesses for 4-bit operation, a rewrite is needed to set the functions (see Table 12). Thus, DB4 to DB7 of the function set instruction is written twice.

- 8-bit operation, 8-digit × 2-line display

  For a 2-line display, the cursor automatically moves from the first to the second line after the 40th digit of the first line has been written. Thus, if there are only 8 characters in the first line, the DDRAM address must be again set after the 8th character is completed. (See Table 13.) Note that the display shift operation is performed for the first and second lines. In the example of Table 13, the display shift is performed when the cursor is on the second line. However, if the shift operation is performed when the cursor is on the first line, both the first and second lines move together. If the shift is repeated, the display of the second line will not move to the first line. The same display will only shift within its own line for the number of times the shift is repeated.

Note: When using the internal reset, the electrical characteristics in the Power Supply Conditions Using Internal Reset Circuit table must be satisfied. If not, the HD44780U must be initialized by instructions. See the section, Initializing by Instruction.

Table 11 8-Bit Operation, 8-Digit × 1-Line Display Example with Internal Reset

Step	Instruction											
No.	RS	R/$\overline{W}$	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Display	Operation
1	Power supply on (the HD44780U is initialized by the internal reset circuit)											Initialized. No display.
2	Function set											Sets to 8-bit operation and selects 1-line display and 5 × 8 dot character font. (Number of display lines and character fonts cannot be changed after step #2.)
	0	0	0	0	1	1	0	0	*	*		
3	Display on/off control										_	Turns on display and cursor. Entire display is in space mode because of initialization.
	0	0	0	0	0	0	1	1	1	0		
4	Entry mode set										_	Sets mode to increment the address by one and to shift the cursor to the right at the time of write to the DD/CGRAM. Display is not shifted.
	0	0	0	0	0	0	0	1	1	0		
5	Write data to CGRAM/DDRAM										H_	Writes H. DDRAM has already been selected by initialization when the power was turned on. The cursor is incremented by one and shifted to the right.
	1	0	0	1	0	0	1	0	0	0		
6	Write data to CGRAM/DDRAM										HI_	Writes I.
	1	0	0	1	0	0	1	0	0	1		
7						. . . . .					. . . . .	
8	Write data to CGRAM/DDRAM										HITACHI_	Writes I.
	1	0	0	1	0	0	1	0	0	1		
9	Entry mode set										HITACHI_	Sets mode to shift display at the time of write.
	0	0	0	0	0	0	0	1	1	1		
10	Write data to CGRAM/DDRAM										ITACHI _	Writes a space.
	1	0	0	0	1	0	0	0	0	0		

Table 11 8-Bit Operation, 8-Digit × 1-Line Display Example with Internal Reset (cont)

Step No.	RS	R/$\overline{W}$	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Display	Operation
11	Write data to CGRAM/DDRAM										TACHI M_	Writes M.
	1	0	0	1	0	0	1	1	0	1		
12	. . . . .										. . . . .	
13	Write data to CGRAM/DDRAM										MICROKO_	Writes O.
	1	0	0	1	0	0	1	1	1	1		
14	Cursor or display shift										MICROKO	Shifts only the cursor position to the left.
	0	0	0	0	0	1	0	0	*	*		
15	Cursor or display shift										MICROKO	Shifts only the cursor position to the left.
	0	0	0	0	0	1	0	0	*	*		
16	Write data to CGRAM/DDRAM										ICROCO	Writes C over K. The display moves to the left.
	1	0	0	1	0	0	0	0	1	1		
17	Cursor or display shift										MICROCO	Shifts the display and cursor position to the right.
	0	0	0	0	0	1	1	1	*	*		
18	Cursor or display shift										MICROCO_	Shifts the display and cursor position to the right.
	0	0	0	0	0	1	0	1	*	*		
19	Write data to CGRAM/DDRAM										ICROCOM_	Writes M.
	1	0	0	1	0	0	1	1	0	1		
20	. . . . .										. . . . .	
21	Return home										HITACHI	Returns both display and cursor to the original position (address 0).
	0	0	0	0	0	0	0	0	1	0		

Table 12 4-Bit Operation, 8-Digit × 1-Line Display Example with Internal Reset

Step No.	Instruction RS	R/$\overline{W}$	DB7	DB6	DB5	DB4	Display	Operation
1	Power supply on (the HD44780U is initialized by the internal reset circuit)							Initialized. No display.
2	Function set 0	 0	 0	 0	 1	 0		Sets to 4-bit operation. In this case, operation is handled as 8 bits by initialization, and only this instruction completes with one write.
3	Function set 0 0	 0 0	 0 0	 0 0	 1 *	 0 *		Sets 4-bit operation and selects 1-line display and 5 × 8 dot character font. 4-bit operation starts from this step and resetting is necessary. (Number of display lines and character fonts cannot be changed after step #3.)
4	Display on/off control 0 0	 0 0	 0 1	 0 1	 0 1	 0 0	_	Turns on display and cursor. Entire display is in space mode because of initialization.
5	Entry mode set 0 0	 0 0	 0 0	 0 1	 0 1	 0 0	_	Sets mode to increment the address by one and to shift the cursor to the right at the time of write to the DD/CGRAM. Display is not shifted.
6	Write data to CGRAM/DDRAM 1 1	 0 0	 0 1	 1 0	 0 0	 0 0	H_	Writes H. The cursor is incremented by one and shifts to the right.

Note: The control is the same as for 8-bit operation beyond step #6.

Table 13 8-Bit Operation, 8-Digit × 2-Line Display Example with Internal Reset

Step No.	Instruction RS	R/$\overline{W}$	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Display	Operation
1	Power supply on (the HD44780U is initialized by the internal reset circuit)											Initialized. No display.
2	Function set 0	 0	 0	 0	 1	 1	 1	 0	 *	 *		Sets to 8-bit operation and selects 2-line display and 5 × 8 dot character font.
3	Display on/off control 0	 0	 0	 0	 0	 0	 1	 1	 1	 0	_	Turns on display and cursor. All display is in space mode because of initialization.
4	Entry mode set 0	 0	 0	 0	 0	 0	 0	 1	 1	 0	_	Sets mode to increment the address by one and to shift the cursor to the right at the time of write to the DD/CGRAM. Display is not shifted.
5	Write data to CGRAM/DDRAM 1	 0	 0	 1	 0	 0	 1	 0	 0	 0	H_	Writes H. DDRAM has already been selected by initialization when the power was turned on. The cursor is incremented by one and shifted to the right.
6					. . . . .						. . . . .	
7	Write data to CGRAM/DDRAM 1	 0	 0	 1	 0	 0	 1	 0	 0	 1	HITACHI_	Writes I.
8	Set DDRAM address 0	 0	 1	 1	 0	 0	 0	 0	 0	 0	HITACHI _	Sets DDRAM address so that the cursor is positioned at the head of the second line.

Table 13 8-Bit Operation, 8-Digit × 2-Line Display Example with Internal Reset (cont)

Step No.	RS	R/$\overline{W}$	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Display	Operation
9	Write data to CGRAM/DDRAM										HITACHI M_	Writes M.
	1	0	0	1	0	0	1	1	0	1		
10					. . . . .						. . . . .	
11	Write data to CGRAM/DDRAM										HITACHI MICROCO_	Writes O.
	1	0	0	1	0	0	1	1	1	1		
12	Entry mode set										HITACHI MICROCO_	Sets mode to shift display at the time of write.
	0	0	0	0	0	0	0	1	1	1		
13	Write data to CGRAM/DDRAM										ITACHI ICROCOM_	Writes M. Display is shifted to the left. The first and second lines both shift at the same time.
	1	0	0	1	0	0	1	1	0	1		
14					. . . . .						. . . . .	
15	Return home										HITACHI MICROCOM	Returns both display and cursor to the original position (address 0).
	0	0	0	0	0	0	0	0	1	0		

Initializing by Instruction

If the power supply conditions for correctly operating the internal reset circuit are not met, initialization by instructions becomes necessary.

Refer to Figures 23 and 24 for the procedures on 8-bit and 4-bit initializations, respectively.

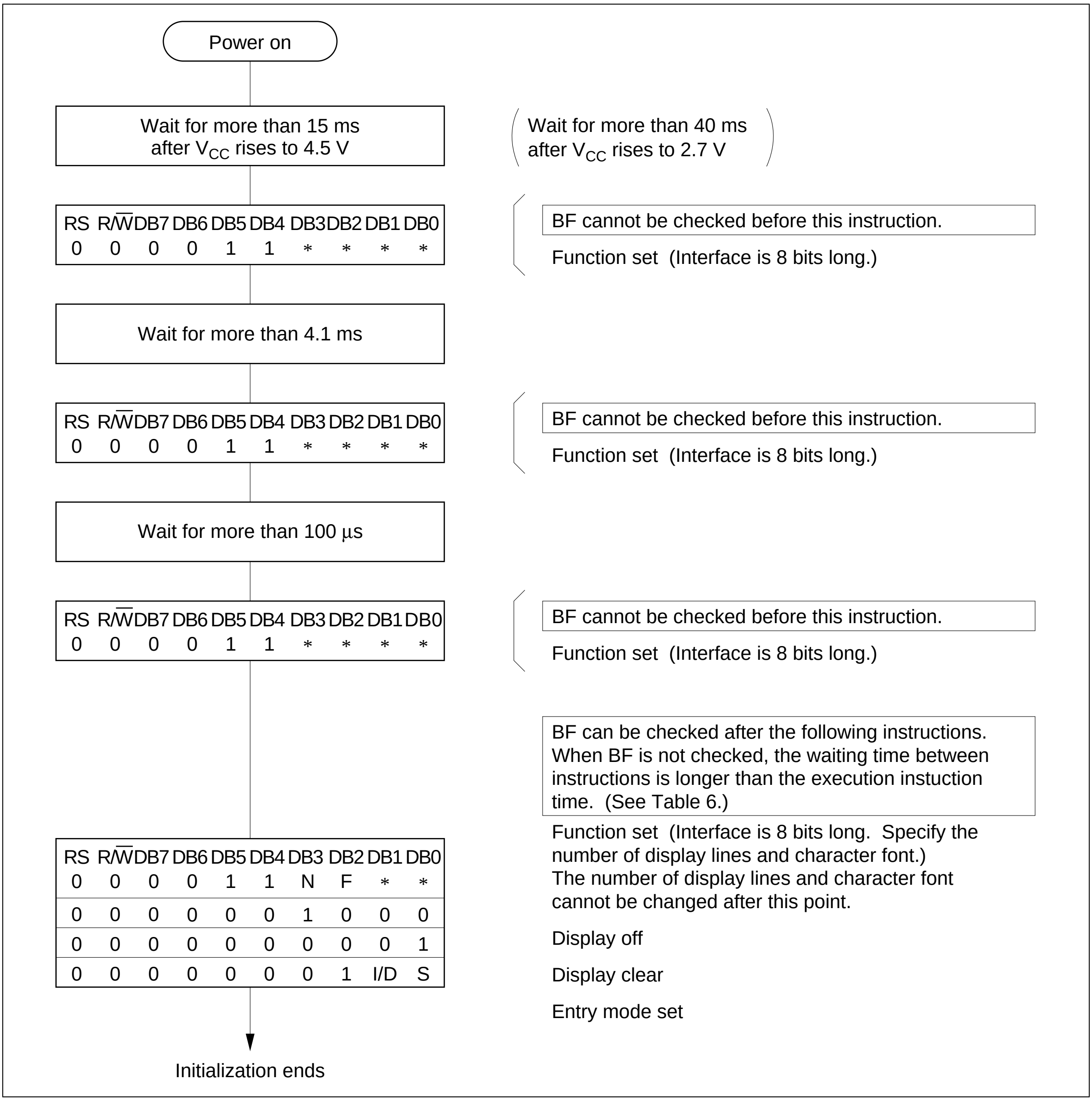


Figure 23 8-Bit Interface

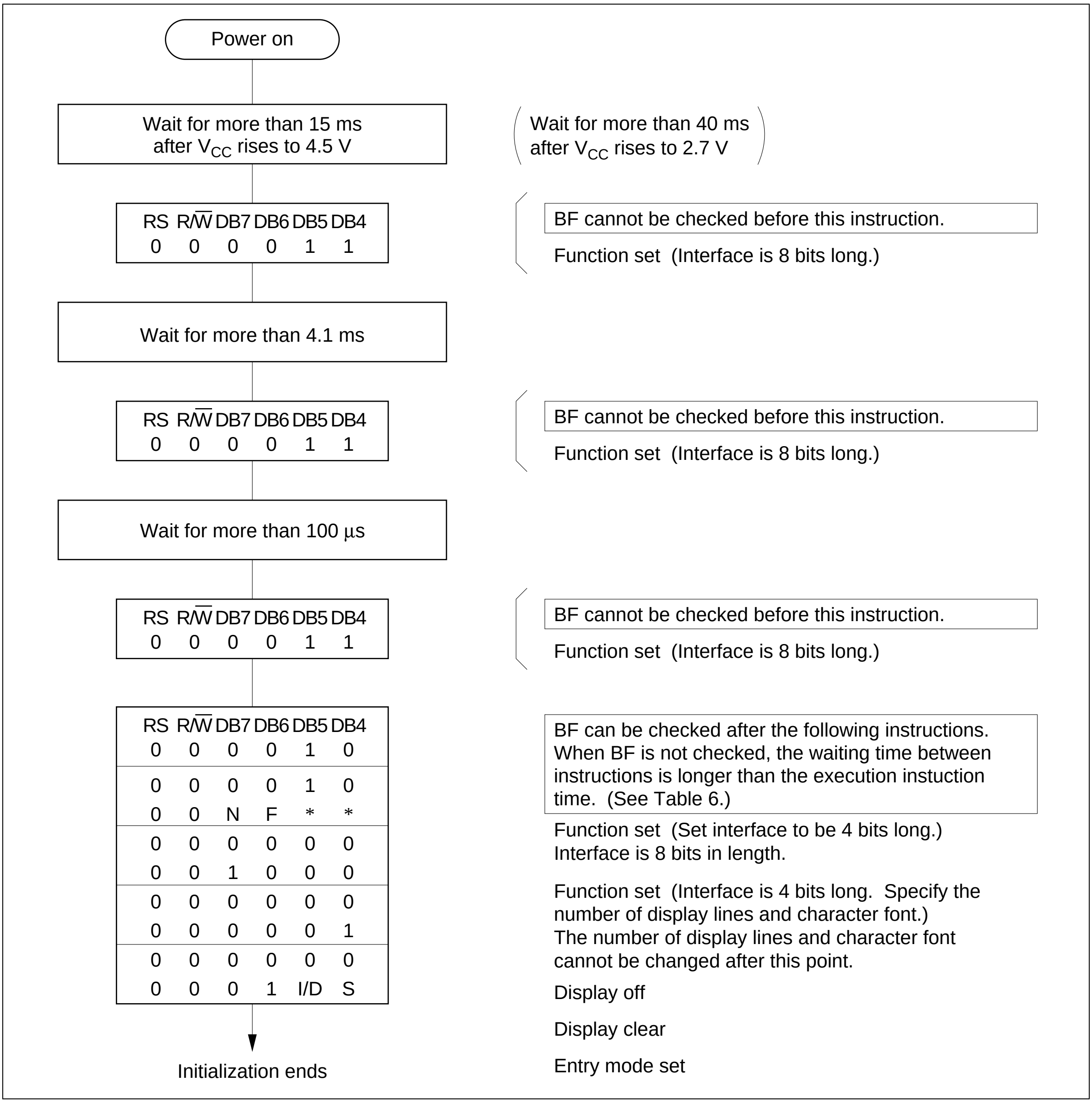


Figure 24 4-Bit Interface

Absolute Maximum Ratings*

Item	Symbol	Value	Unit	Notes
Power supply voltage (1)	V_{CC}–GND	–0.3 to +7.0	V	1
Power supply voltage (2)	V_{CC}–V5	–0.3 to +13.0	V	1, 2
Input voltage	Vt	–0.3 to V_{CC} +0.3	V	1
Operating temperature	T_{opr}	–30 to +75	°C	
Storage temperature	T_{stg}	–55 to +125	°C	4

Note: * If the LSI is used above these absolute maximum ratings, it may become permanently damaged. Using the LSI within the following electrical characteristic limits is strongly recommended for normal operation. If these electrical characteristic conditions are also exceeded, the LSI will malfunction and cause poor reliability.

DC Characteristics (V_{CC} = 2.7 to 4.5 V, T_a = –30 to +75°C*[3])

Item	Symbol	Min	Typ	Max	Unit	Test Condition	Notes*
Input high voltage (1) (except OSC1)	VIH1	$0.7V_{CC}$	—	V_{CC}	V		6
Input low voltage (1) (except OSC1)	VIL1	–0.3	—	0.55	V		6
Input high voltage (2) (OSC1)	VIH2	$0.7V_{CC}$	—	V_{CC}	V		15
Input low voltage (2) (OSC1)	VIL2	—	—	$0.2V_{CC}$	V		15
Output high voltage (1) (DB0–DB7)	VOH1	$0.75V_{CC}$	—	—	V	$-I_{OH}$ = 0.1 mA	7
Output low voltage (1) (DB0–DB7)	VOL1	—	—	$0.2V_{CC}$	V	I_{OL} = 0.1 mA	7
Output high voltage (2) (except DB0–DB7)	VOH2	$0.8V_{CC}$	—	—	V	$-I_{OH}$ = 0.04 mA	8
Output low voltage (2) (except DB0–DB7)	VOL2	—	—	$0.2V_{CC}$	V	I_{OL} = 0.04 mA	8
Driver on resistance (COM)	R_{COM}	—	2	20	kΩ	±Id = 0.05 mA, VLCD = 4 V	13
Driver on resistance (SEG)	R_{SEG}	—	2	30	kΩ	±Id = 0.05 mA, VLCD = 4 V	13
Input leakage current	I_{LI}	–1	—	1	µA	VIN = 0 to V_{CC}	9
Pull-up MOS current (DB0–DB7, RS, R/$\overline{W}$)	$-I_p$	10	50	120	µA	V_{CC} = 3 V	
Power supply current	I_{CC}	—	150	300	µA	R_f oscillation, external clock V_{CC} = 3 V, f_{OSC} = 270 kHz	10, 14
LCD voltage	VLCD1	3.0	—	11.0	V	V_{CC}–V5, 1/5 bias	16
	VLCD2	3.0	—	11.0	V	V_{CC}–V5, 1/4 bias	16

Note: * Refer to the Electrical Characteristics Notes section following these tables.

AC Characteristics (V_{CC} = 2.7 to 4.5 V, T_a = –30 to +75°C*[3])

Clock Characteristics

Item		Symbol	Min	Typ	Max	Unit	Test Condition	Note*
External clock operation	External clock frequency	f_{cp}	125	250	350	kHz		11
	External clock duty	Duty	45	50	55	%		
	External clock rise time	t_{rcp}	—	—	0.2	µs		
	External clock fall time	t_{fcp}	—	—	0.2	µs		
R_f oscillation	Clock oscillation frequency	f_{OSC}	190	270	350	kHz	R_f = 75 kΩ, V_{CC} = 3 V	12

Note: * Refer to the Electrical Characteristics Notes section following these tables.

Bus Timing Characteristics

Write Operation

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Enable cycle time	t_{cycE}	1000	—	—	ns	Figure 25
Enable pulse width (high level)	PW_{EH}	450	—	—		
Enable rise/fall time	t_{Er}, t_{Ef}	—	—	25		
Address set-up time (RS, R/$\overline{W}$ to E)	t_{AS}	60	—	—		
Address hold time	t_{AH}	20	—	—		
Data set-up time	t_{DSW}	195	—	—		
Data hold time	t_H	10	—	—		

Read Operation

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Enable cycle time	t_{cycE}	1000	—	—	ns	Figure 26
Enable pulse width (high level)	PW_{EH}	450	—	—		
Enable rise/fall time	t_{Er}, t_{Ef}	—	—	25		
Address set-up time (RS, R/$\overline{W}$ to E)	t_{AS}	60	—	—		
Address hold time	t_{AH}	20	—	—		
Data delay time	t_{DDR}	—	—	360		
Data hold time	t_{DHR}	5	—	—		

Interface Timing Characteristics with External Driver

Item		Symbol	Min	Typ	Max	Unit	Test Condition
Clock pulse width	High level	t_{CWH}	800	—	—	ns	Figure 27
	Low level	t_{CWL}	800	—	—		
Clock set-up time		t_{CSU}	500	—	—		
Data set-up time		t_{SU}	300	—	—		
Data hold time		t_{DH}	300	—	—		
M delay time		t_{DM}	–1000	—	1000		
Clock rise/fall time		t_{ct}	—	—	200		

Power Supply Conditions Using Internal Reset Circuit

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Power supply rise time	t_{rCC}	0.1	—	10	ms	Figure 28
Power supply off time	t_{OFF}	1	—	—		

DC Characteristics (V_{CC} = 4.5 to 5.5 V, T_a = –30 to +75°C*[3])

Item	Symbol	Min	Typ	Max	Unit	Test Condition	Notes*
Input high voltage (1) (except OSC1)	VIH1	2.2	—	V_{CC}	V		6
Input low voltage (1) (except OSC1)	VIL1	–0.3	—	0.6	V		6
Input high voltage (2) (OSC1)	VIH2	V_{CC}–1.0	—	V_{CC}	V		15
Input low voltage (2) (OSC1)	VIL2	—	—	1.0	V		15
Output high voltage (1) (DB0–DB7)	VOH1	2.4	—	—	V	$–I_{OH}$ = 0.205 mA	7
Output low voltage (1) (DB0–DB7)	VOL1	—	—	0.4	V	I_{OL} = 1.2 mA	7
Output high voltage (2) (except DB0–DB7)	VOH2	0.9 V_{CC}	—	—	V	$–I_{OH}$ = 0.04 mA	8
Output low voltage (2) (except DB0–DB7)	VOL2	—	—	0.1 V_{CC}	V	I_{OL} = 0.04 mA	8
Driver on resistance (COM)	RCOM	—	2	20	kΩ	±Id = 0.05 mA, VLCD = 4 V	13
Driver on resistance (SEG)	RSEG	—	2	30	kΩ	±Id = 0.05 mA, VLCD = 4 V	13
Input leakage current	I_{LI}	–1	—	1	µA	VIN = 0 to V_{CC}	9
Pull-up MOS current (DB0–DB7, RS, R/$\overline{W}$)	$–I_p$	50	125	250	µA	V_{CC} = 5 V	
Power supply current	I_{CC}	—	350	600	µA	R_f oscillation, external clock V_{CC} = 5 V, f_{OSC} = 270 kHz	10, 14
LCD voltage	VLCD1	3.0	—	11.0	V	V_{CC}–V5, 1/5 bias	16
	VLCD2	3.0	—	11.0	V	V_{CC}–V5, 1/4 bias	16

Note: * Refer to the Electrical Characteristics Notes section following these tables.

AC Characteristics (V_{CC} = 4.5 to 5.5 V, T_a = –30 to +75°C*[3])

Clock Characteristics

Item		Symbol	Min	Typ	Max	Unit	Test Condition	Notes*
External clock operation	External clock frequency	f_{cp}	125	250	350	kHz		11
	External clock duty	Duty	45	50	55	%		11
	External clock rise time	t_{rcp}	—	—	0.2	µs		11
	External clock fall time	t_{fcp}	—	—	0.2	µs		11
R_f oscillation	Clock oscillation frequency	f_{OSC}	190	270	350	kHz	R_f = 91 kΩ V_{CC} = 5.0 V	12

Note: * Refer to the Electrical Characteristics Notes section following these tables.

Bus Timing Characteristics

Write Operation

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Enable cycle time	t_{cycE}	500	—	—	ns	Figure 25
Enable pulse width (high level)	PW_{EH}	230	—	—		
Enable rise/fall time	t_{Er}, t_{Ef}	—	—	20		
Address set-up time (RS, R/$\overline{W}$ to E)	t_{AS}	40	—	—		
Address hold time	t_{AH}	10	—	—		
Data set-up time	t_{DSW}	80	—	—		
Data hold time	t_H	10	—	—		

Read Operation

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Enable cycle time	t_{cycE}	500	—	—	ns	Figure 26
Enable pulse width (high level)	PW_{EH}	230	—	—		
Enable rise/fall time	t_{Er}, t_{Ef}	—	—	20		
Address set-up time (RS, R/$\overline{W}$ to E)	t_{AS}	40	—	—		
Address hold time	t_{AH}	10	—	—		
Data delay time	t_{DDR}	—	—	160		
Data hold time	t_{DHR}	5	—	—		

Interface Timing Characteristics with External Driver

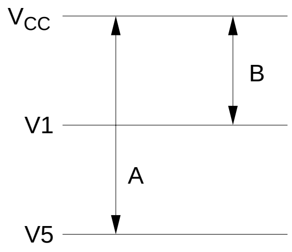
Item		Symbol	Min	Typ	Max	Unit	Test Condition
Clock pulse width	High level	t_{CWH}	800	—	—	ns	Figure 27
	Low level	t_{CWL}	800	—	—		
Clock set-up time		t_{CSU}	500	—	—		
Data set-up time		t_{SU}	300	—	—		
Data hold time		t_{DH}	300	—	—		
M delay time		t_{DM}	–1000	—	1000		
Clock rise/fall time		t_{ct}	—	—	100		

Power Supply Conditions Using Internal Reset Circuit

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Power supply rise time	t_{rCC}	0.1	—	10	ms	Figure 28
Power supply off time	t_{OFF}	1	—	—		

Electrical Characteristics Notes

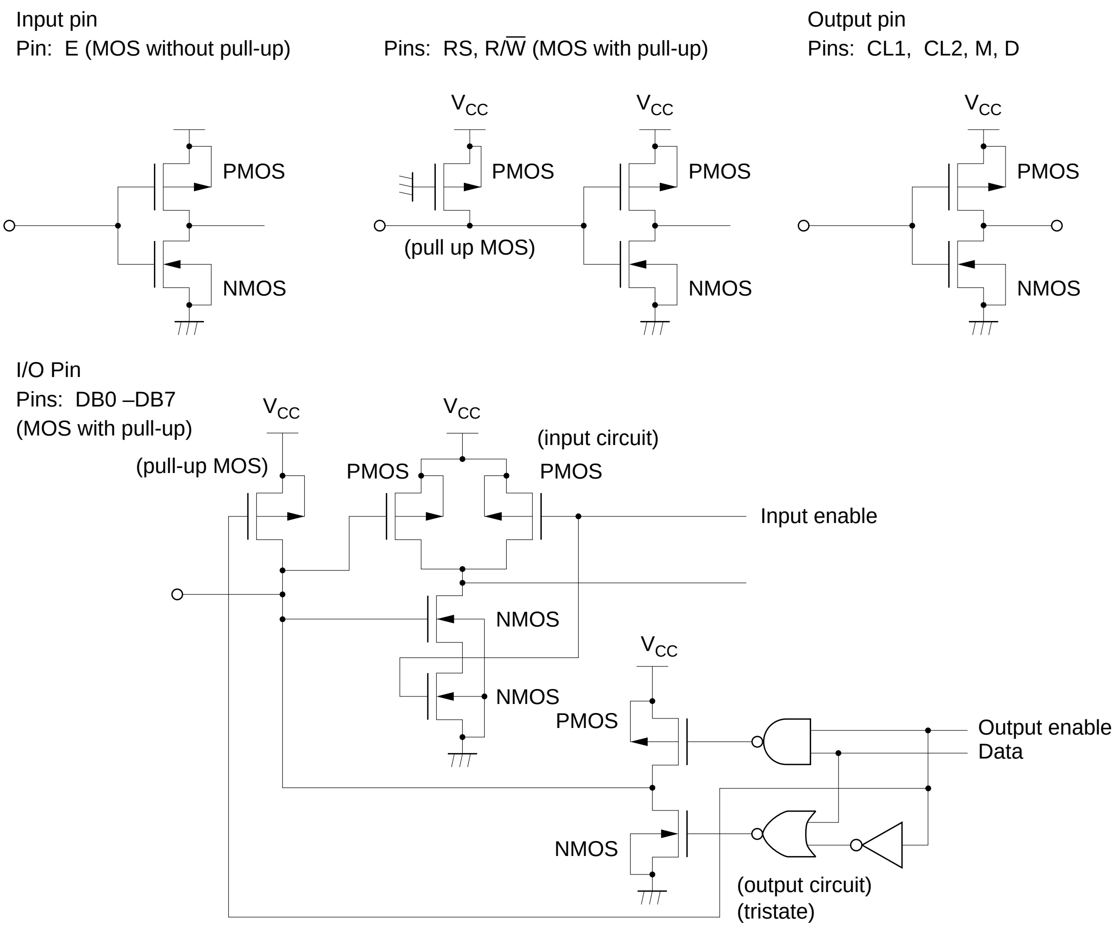
1. All voltage values are referred to GND = 0 V.



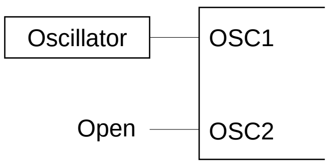
$A = V_{CC} - V5$
$B = V_{CC} - V1$
$A \geq 1.5$ V
$B \leq 0.25 \times A$

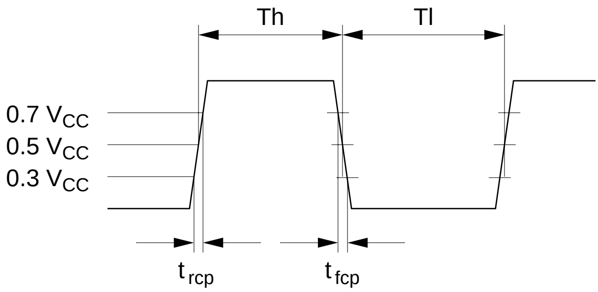
The conditions of V1 and V5 voltages are for proper operation of the LSI and not for the LCD output level. The LCD drive voltage condition for the LCD output level is specified as LCD voltage VLCD.

2. $V_{CC} \geq V1 \geq V2 \geq V3 \geq V4 \geq V5$ must be maintained.
3. For die products, specified at 75°C.
4. For die products, specified by the die shipment specification.
5. The following four circuits are I/O pin configurations except for liquid crystal display output.



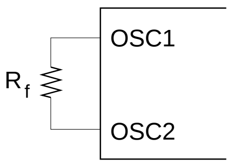
6. Applies to input pins and I/O pins, excluding the OSC1 pin.
7. Applies to I/O pins.
8. Applies to output pins.
9. Current flowing through pull–up MOSs, excluding output drive MOSs.
10. Input/output current is excluded. When input is at an intermediate level with CMOS, the excessive current flows through the input circuit to the power supply. To avoid this from happening, the input level must be fixed high or low.
11. Applies only to external clock operation.



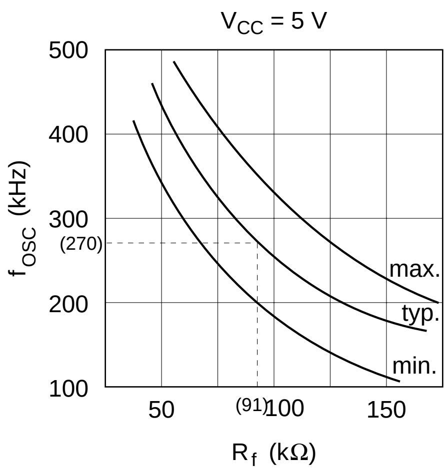


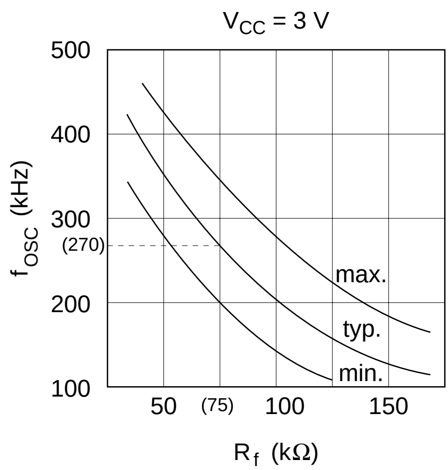
$$\text{Duty} = \frac{\text{Th}}{\text{Th} + \text{Tl}} \times 100\%$$

12. Applies only to the internal oscillator operation using oscillation resistor R_f.



R_f: 75 kΩ ± 2% (when V_{CC} = 3 V)
R_f: 91 kΩ ± 2% (when V_{CC} = 5 V)
Since the oscillation frequency varies depending on the OSC1 and OSC2 pin capacitance, the wiring length to these pins should be minimized.

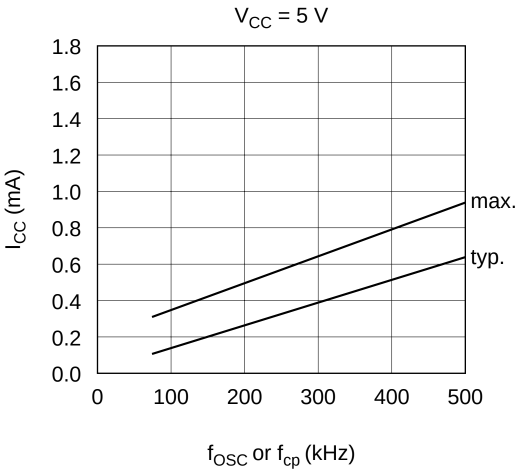


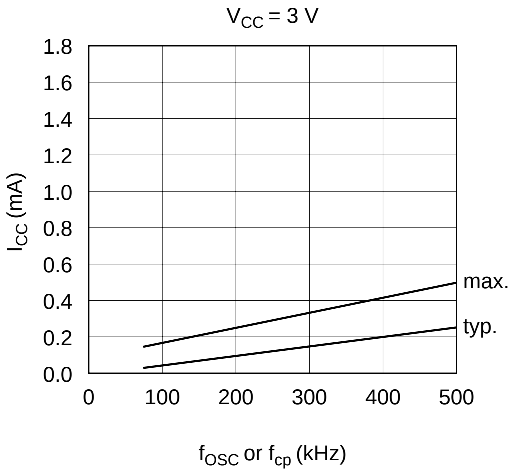


13. RCOM is the resistance between the power supply pins (V_{CC}, V1, V4, V5) and each common signal pin (COM1 to COM16).

    RSEG is the resistance between the power supply pins (V_{CC}, V2, V3, V5) and each segment signal pin (SEG1 to SEG40).

14. The following graphs show the relationship between operation frequency and current consumption.

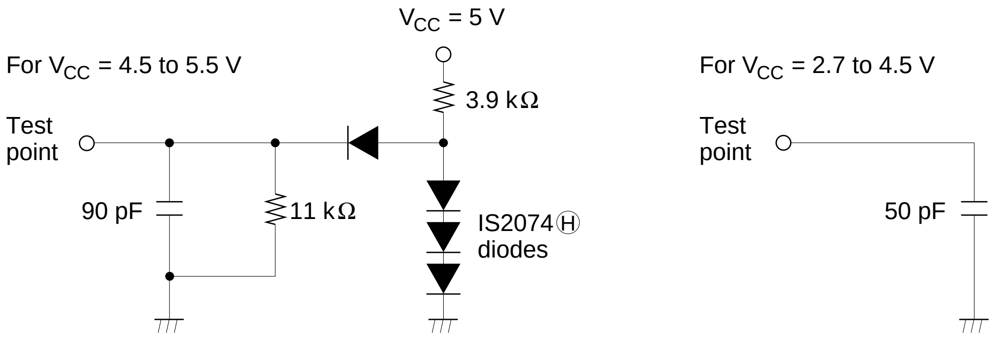




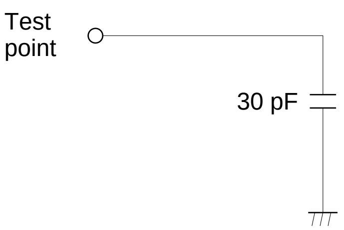
15. Applies to the OSC1 pin.
16. Each COM and SEG output voltage is within ±0.15 V of the LCD voltage (V_{CC}, V1, V2, V3, V4, V5) when there is no load.

Load Circuits

Data Bus DB0 to DB7



External Driver Control Signals: CL1, CL2, D, M



Timing Characteristics

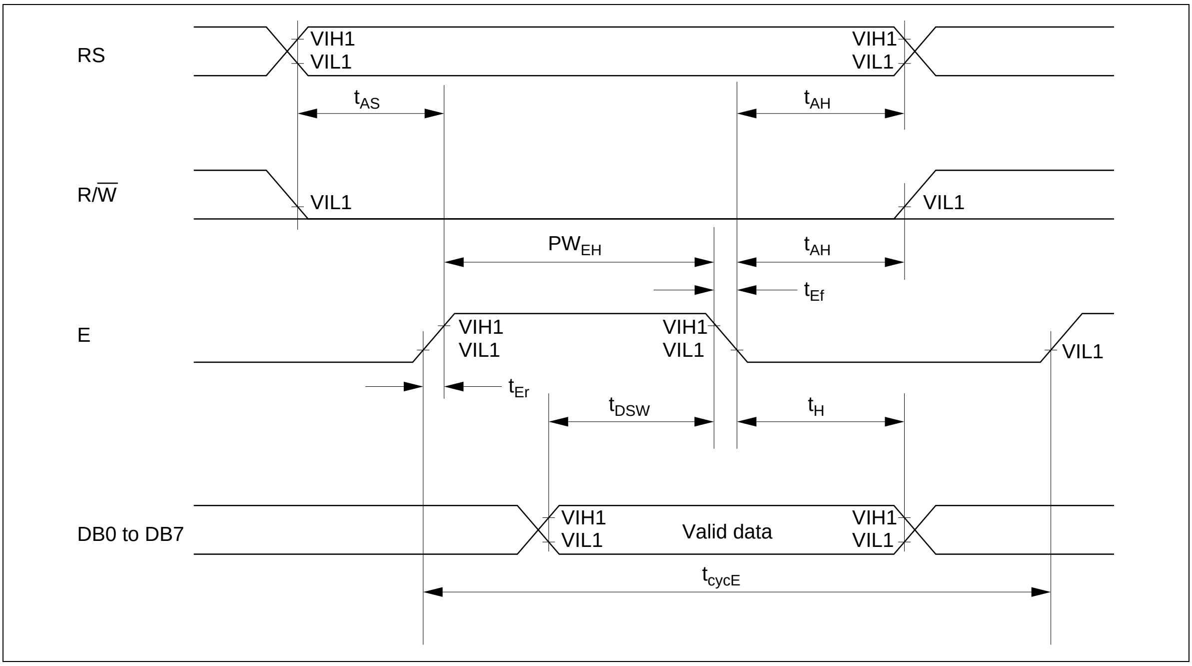


Figure 25 Write Operation

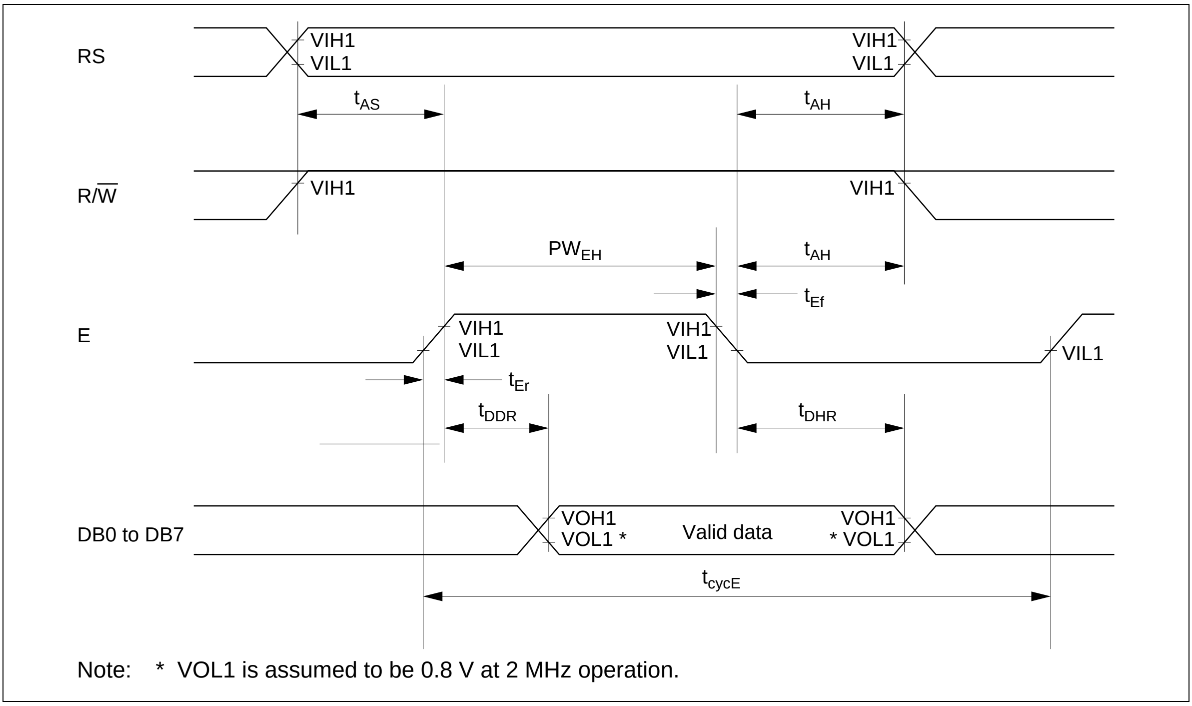


Figure 26 Read Operation

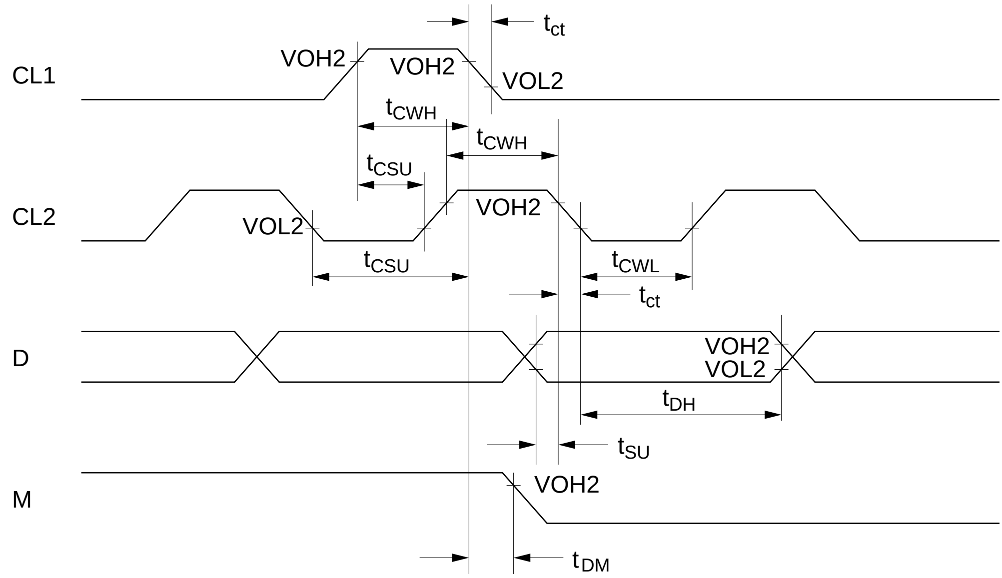
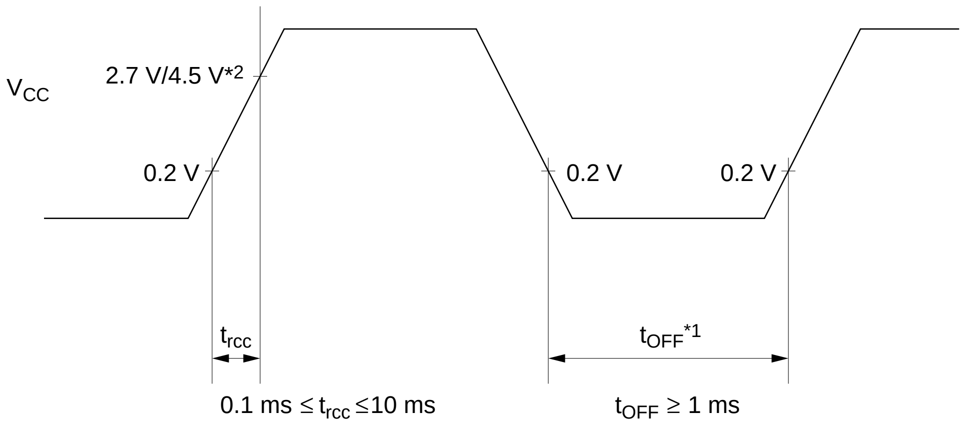


Figure 27 Interface Timing with External Driver



Notes:
1. t_{OFF} compensates for the power oscillation period caused by momentary power supply oscillations.
2. Specified at 4.5 V for 5-V operation, and at 2.7 V for 3-V operation.
3. For if 4.5 V is not reached during 5-V operation, the internal reset circuit will not operate normally.
   In this case, the LSI must be initialized by software. (Refer to the Initializing by Instruction section.)

Figure 28 Internal Power Supply Reset

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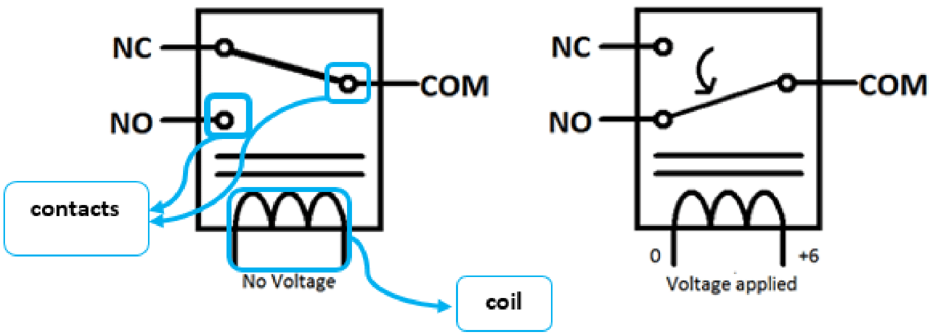
RELAY MODULES

RELAY WORKING IDEA

Relays consist of three pins normaly open pin , normaly closed pin, common pin and coil. When coil powerd on magntic field is generated the contacts connected to each other.

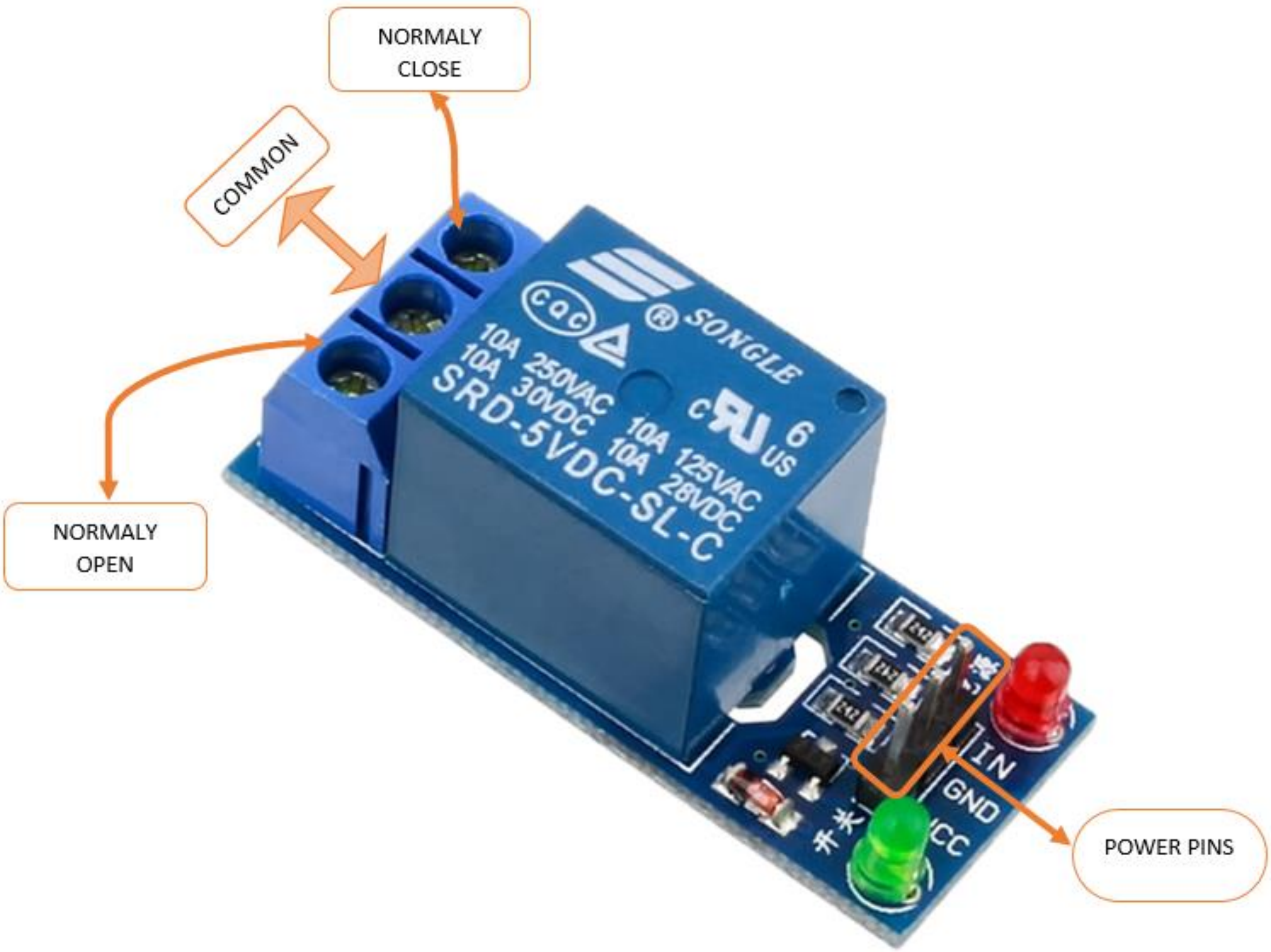


Relay modules 1-channel features

- Contact current 10A and 250V AC or 30V DC.
- Each channel has indication LED.
- Coil voltage 12V per channel.
- Kit operating voltage 5-12 V
- Input signal 3-5 V for each channel.
- Three pins for normally open and closed for each channel.

How to connect relay module with Arduino

As shown in relay working idea it depends on magnetic field generated from the coil so there is power isolation between the coil and the switching pins so coils can be easily powered from Arduino by connecting VCC and GND bins from Arduino kit to the relay module kit after that we choose Arduino output pins depending on the number of relays needed in project designed and set these pins to output and make it out high (5 V) to control the coil that allow controlling of switching process.

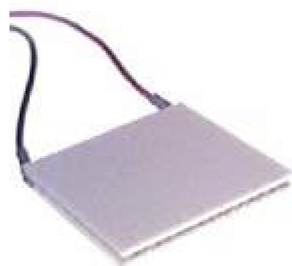


NOTE : whatever was the relay channels number the pinconfiguration is the same for every channel except the power pins (VCC and GND) are for the board itself. The input signal (IN) pin for every relay.

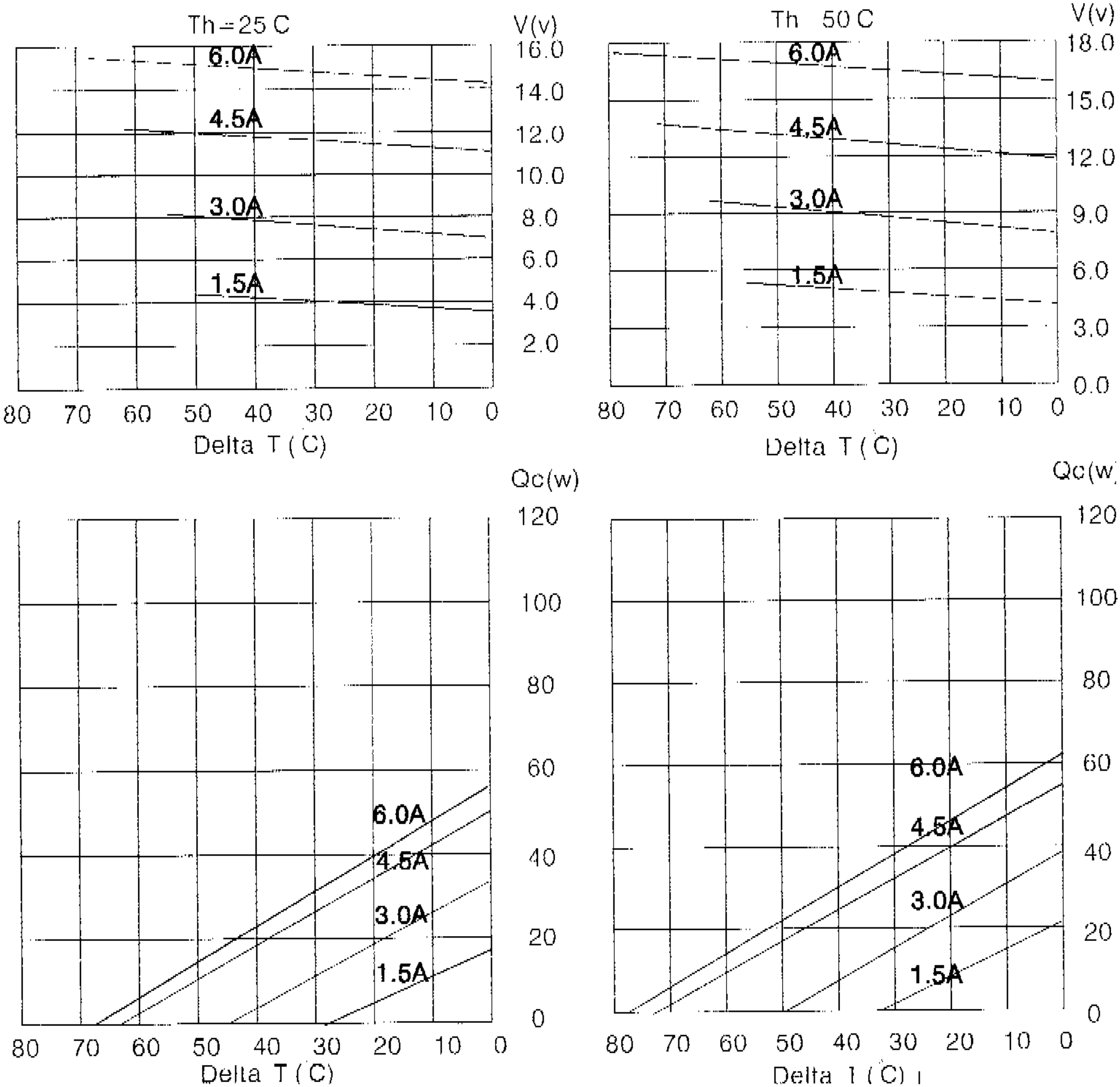
TEC1-12706

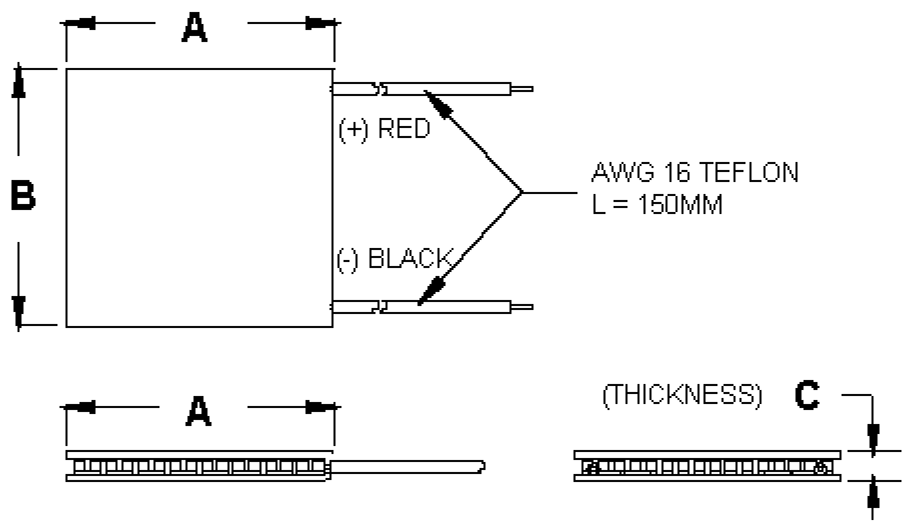
Performance Specifications

Hot Side Temperature (° C)	25° C	50° C
Qmax (Watts)	50	57
Delta Tmax (° C)	66	75
Imax (Amps)	6.4	6.4
Vmax (Volts)	14.4	16.4
Module Resistance (Ohms)	1.98	2.30



Performance curves:





Ceramic Material: Alumina (Al_2O_3)
Solder Construction: 138°C, Bismuth Tin (BiSn)

Size table:

A	B	C			
40	40	3.9			

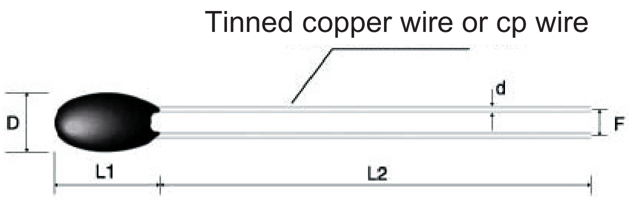
Operating Tips

- Max. Operating Temperature: 138°C
- Do not exceed Imax or Vmax when operating module.
- Life expectancy: 200,000 hours
- Please consult HB for moisture protection options (seeling).
- Failure rate based on long time testings: 0.2%.

MF52

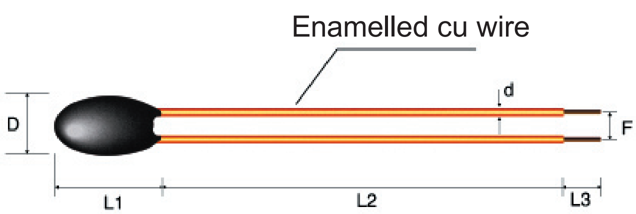
Pearl-Shaped Precision NTC Thermistor for Temperature Measurement. The MF52 series is ethoxyline resin coated. The small size is made possible by new materials and manufacturing methods which provide the benefit of close tolerances and fast response. MF52 thermistors are available with 5 lead styles in standard or custom lengths.

Dimensions (mm)



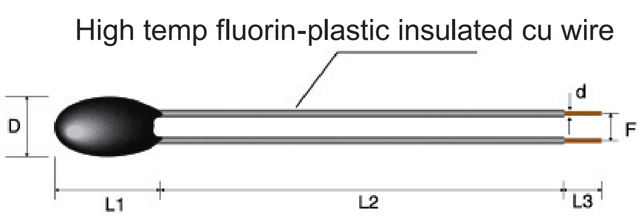
A: Tin. Ag. nickel plated cu wire

Code	D max	L_1 max	L_2 min	d +/- 0.05	F +/- 0.5
A1	2.5	4.0	25	0.3	1.7
A2	3	4.5	25	0.45	2.2



B: Enamelled cu wire

Code	D max	L_1 max	L_2 min	L_3 +/- 1	d +/- 0.05
B1	2	3.5	Customer Specified	3	0.2
B2	3	4	Customer Specified	3	0.3



C: High temp fluorin-plastic wire

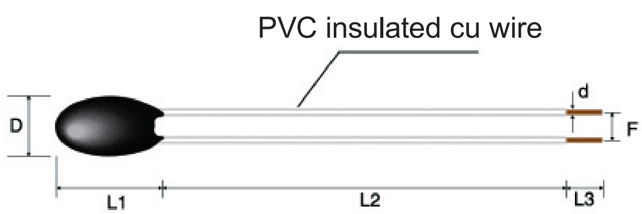
Code	D max	L_1 max	L_2 min	L_3 +/- 1	d +/- 0.05
C1	3	7.5	Customer Specified	5	0.26
C2	4	7.5	Customer Specified	5	0.32

Application

- Heating, Ventilation & Air Conditioning
- Temperature Regulation and Measurement
- Electronic Thermometers
- Liquid Level Sensing
- Automotive Electronics
- Medical Equipment and Apparatus
- Battery Packs and Portable Electronics

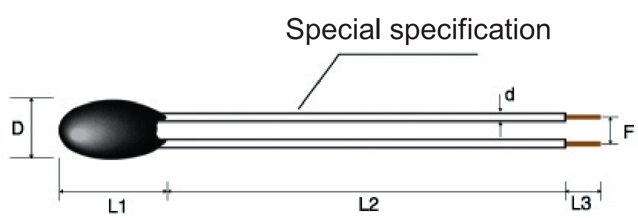
Characteristics

- Small Size and fast response
- Available tolerances: ±1%, ±2%, ±3%, ±5% and ±10%
- Long-term Stability and Reliability
- Excellent Tolerance and Interchangeability
- Available in all popular resistance values
- Dissipation Constant ≥2.0mW/°C
- Time Constant of ≤7 seconds in still air
- Available in custom probes



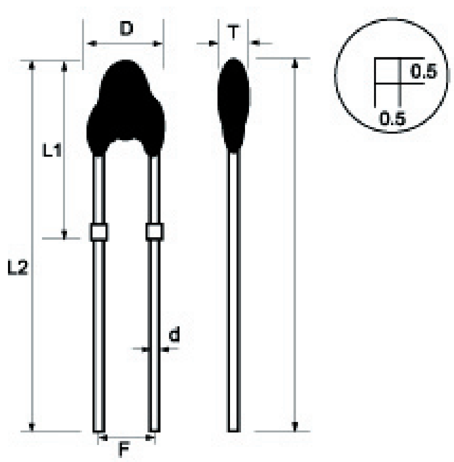
D: PVC wire

Code	D max	L_1 max	L_2 min	L_3 +/- 1	d +/- 0.05
D1	3	7.5	Customer Specified	5	0.26
D2	4	7.5	Customer Specified	5	0.32



E: Lead and head according to specification

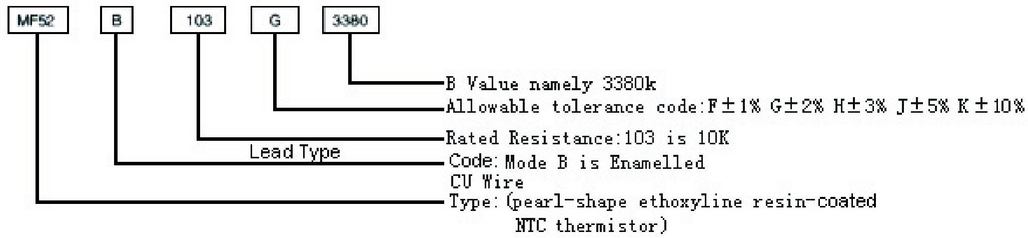
Code	D max	L_1 max	L_2 min	L_3 +/- 1	d +/- 0.05
E1	Customer Specified	Customer Specified	Customer Specified	5	Customer Specified
E2	Customer Specified	Customer Specified	Customer Specified	5	Customer Specified



F: Tinned lead-frame style

Code	D max	L_1 max	L_2 +/- 1.5	d max	F +/- 0.5	T max
F	3.8	9.5	17	0.5	2.5	3.5

Specification



Main Techno-Parameter

Part No.	Rated Resistance R_{25} (KΩ)	B Value (25/50°C) (K)	Rated Power(mw)	Dissi. Coef. (mW/ °C)	Thermal time Constant(S)	Operating Temp.(°C)
MF52□□□3100	0.1-20	3100	≤ 50	≥ 2.0 In Still Air	≤ 7 In Still Air	-55° - +125°C
MF52□□□3270	0.2-20	3270				
MF52□□□3380	0.5-50	3380				
MF52□□□3470	0.5-50	3470				
MF52□□□3600	1-100	3600				
MF52□□□3950	5-100	3950				
MF52□□□4000	5-100	4000				
MF52□□□4050	5-200	4050				
MF52□□□4150	10-250	4150				
MF52□□□4300	20-1000	4300				
MF52□□□4500	20-1000	4500				

Remark:
* B Value (25/50C) error is ±1% for components with rated resistance tolerance of ±1% and ±2% for all others.

Notice:
* The two ends of the lead wire cannot endure too big pull because of the small size and soldered spot in series of MF52.
* Solder at least 5mm from the bottom of wire.

UL 1434
(File E240991)

CQC
(File 07001019009)

* Specifications are subject to change without notice.

CANTHERM
Supplying high-quality bimetal and thermal sensor products.

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Website: www.cantherm.com | Division of Microtherm

National Semiconductor

LM35
Precision Centigrade Temperature Sensors

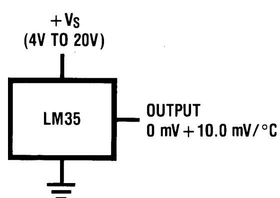
General Description

The LM35 series are precision integrated-circuit temperature sensors, whose output voltage is linearly proportional to the Celsius (Centigrade) temperature. The LM35 thus has an advantage over linear temperature sensors calibrated in ˚ Kelvin, as the user is not required to subtract a large constant voltage from its output to obtain convenient Centigrade scaling. The LM35 does not require any external calibration or trimming to provide typical accuracies of ±¼˚C at room temperature and ±¾˚C over a full −55 to +150˚C temperature range. Low cost is assured by trimming and calibration at the wafer level. The LM35's low output impedance, linear output, and precise inherent calibration make interfacing to readout or control circuitry especially easy. It can be used with single power supplies, or with plus and minus supplies. As it draws only 60 µA from its supply, it has very low self-heating, less than 0.1˚C in still air. The LM35 is rated to operate over a −55˚ to +150˚C temperature range, while the LM35C is rated for a −40˚ to +110˚C range (−10˚ with improved accuracy). The LM35 series is available packaged in hermetic TO-46 transistor packages, while the LM35C, LM35CA, and LM35D are also available in the plastic TO-92 transistor package. The LM35D is also available in an 8-lead surface mount small outline package and a plastic TO-220 package.

Features

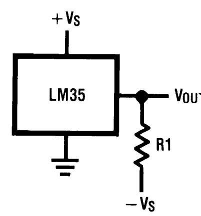
- Calibrated directly in ˚ Celsius (Centigrade)
- Linear + 10.0 mV/˚C scale factor
- 0.5˚C accuracy guaranteeable (at +25˚C)
- Rated for full −55˚ to +150˚C range
- Suitable for remote applications
- Low cost due to wafer-level trimming
- Operates from 4 to 30 volts
- Less than 60 µA current drain
- Low self-heating, 0.08˚C in still air
- Nonlinearity only ±¼˚C typical
- Low impedance output, 0.1 Ω for 1 mA load

Typical Applications



DS005516-3

FIGURE 1. Basic Centigrade Temperature Sensor (+2˚C to +150˚C)



DS005516-4

Choose $R_1 = -V_S/50\ \mu A$

V_{OUT}=+1,500 mV at +150˚C

= +250 mV at +25˚C

= −550 mV at −55˚C

FIGURE 2. Full-Range Centigrade Temperature Sensor

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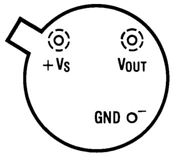
Connection Diagrams

TO-46
Metal Can Package*

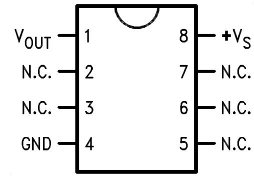


BOTTOM VIEW
DS005516-1

*Case is connected to negative pin (GND)

Order Number LM35H, LM35AH, LM35CH, LM35CAH or LM35DH
See NS Package Number H03H

SO-8
Small Outline Molded Package

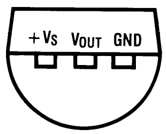


DS005516-21

N.C. = No Connection

Top View
Order Number LM35DM
See NS Package Number M08A

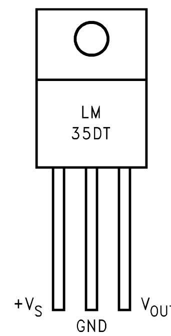
TO-92
Plastic Package



BOTTOM VIEW
DS005516-2

Order Number LM35CZ, LM35CAZ or LM35DZ
See NS Package Number Z03A

TO-220
Plastic Package*



DS005516-24

*Tab is connected to the negative pin (GND).

Note: The LM35DT pinout is different than the discontinued LM35DP.

Order Number LM35DT
See NS Package Number TA03F

Absolute Maximum Ratings (Note 10)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage	+35V to −0.2V
Output Voltage	+6V to −1.0V
Output Current	10 mA
Storage Temp.;	
TO-46 Package,	−60°C to +180°C
TO-92 Package,	−60°C to +150°C
SO-8 Package,	−65°C to +150°C
TO-220 Package,	−65°C to +150°C
Lead Temp.:	
TO-46 Package, (Soldering, 10 seconds)	300°C
TO-92 and TO-220 Package, (Soldering, 10 seconds)	260°C
SO Package (Note 12)	
Vapor Phase (60 seconds)	215°C
Infrared (15 seconds)	220°C
ESD Susceptibility (Note 11)	2500V
Specified Operating Temperature Range: T_{MIN} to T_{MAX} (Note 2)	
LM35, LM35A	−55°C to +150°C
LM35C, LM35CA	−40°C to +110°C
LM35D	0°C to +100°C

Electrical Characteristics

(Notes 1, 6)

Parameter	Conditions	LM35A			LM35CA			Units (Max.)
		Typical	Tested Limit (Note 4)	Design Limit (Note 5)	Typical	Tested Limit (Note 4)	Design Limit (Note 5)	
Accuracy (Note 7)	T_A=+25°C	±0.2	±0.5		±0.2	±0.5		°C
	T_A=−10°C	±0.3			±0.3		±1.0	°C
	$T_A=T_{MAX}$	±0.4	±1.0		±0.4	±1.0		°C
	$T_A=T_{MIN}$	±0.4	±1.0		±0.4		±1.5	°C
Nonlinearity (Note 8)	$T_{MIN}≤T_A≤T_{MAX}$	**±0.18**		**±0.35**	**±0.15**		**±0.3**	°C
Sensor Gain (Average Slope)	$T_{MIN}≤T_A≤T_{MAX}$	**+10.0**	**+9.9, +10.1**		**+10.0**		**+9.9, +10.1**	mV/°C
Load Regulation (Note 3) 0≤I_L≤1 mA	T_A=+25°C	±0.4	±1.0		±0.4	±1.0		mV/mA
	$T_{MIN}≤T_A≤T_{MAX}$	**±0.5**		**±3.0**	**±0.5**		**±3.0**	mV/mA
Line Regulation (Note 3)	T_A=+25°C	±0.01	±0.05		±0.01	±0.05		mV/V
	4V≤V_S≤30V	**±0.02**		**±0.1**	**±0.02**		**±0.1**	mV/V
Quiescent Current (Note 9)	V_S=+5V, +25°C	56	67		56	67		µA
	V_S=+5V	**105**		**131**	**91**		**114**	µA
	V_S=+30V, +25°C	56.2	68		56.2	68		µA
	V_S=+30V	**105.5**		**133**	**91.5**		**116**	µA
Change of Quiescent Current (Note 3)	4V≤V_S≤30V, +25°C	0.2	1.0		0.2	1.0		µA
	4V≤V_S≤30V	**0.5**		**2.0**	**0.5**		**2.0**	µA
Temperature Coefficient of Quiescent Current		**+0.39**		**+0.5**	**+0.39**		**+0.5**	µA/°C
Minimum Temperature for Rated Accuracy	In circuit of *Figure 1*, I_L=0	+1.5		+2.0	+1.5		+2.0	°C
Long Term Stability	$T_J=T_{MAX}$, for 1000 hours	±0.08			±0.08			°C

Electrical Characteristics

(Notes 1, 6)

Parameter	Conditions	LM35			LM35C, LM35D			Units (Max.)
		Typical	Tested Limit (Note 4)	Design Limit (Note 5)	Typical	Tested Limit (Note 4)	Design Limit (Note 5)	
Accuracy, LM35, LM35C (Note 7)	T_A=+25˚C	±0.4	±1.0		±0.4	±1.0		˚C
	T_A=−10˚C	±0.5			±0.5		±1.5	˚C
	$T_A=T_{MAX}$	±0.8	±1.5		±0.8		±1.5	˚C
	$T_A=T_{MIN}$	±0.8		±1.5	±0.8		±2.0	˚C
Accuracy, LM35D (Note 7)	T_A=+25˚C				±0.6	±1.5		˚C
	$T_A=T_{MAX}$				±0.9		±2.0	˚C
	$T_A=T_{MIN}$				±0.9		±2.0	˚C
Nonlinearity (Note 8)	$T_{MIN}\leq T_A\leq T_{MAX}$	**±0.3**		**±0.5**	**±0.2**		**±0.5**	˚C
Sensor Gain (Average Slope)	$T_{MIN}\leq T_A\leq T_{MAX}$	**+10.0**	**+9.8, +10.2**		**+10.0**		**+9.8, +10.2**	mV/˚C
Load Regulation (Note 3) $0\leq I_L\leq 1$ mA	T_A=+25˚C	±0.4	±2.0		±0.4	±2.0		mV/mA
	$T_{MIN}\leq T_A\leq T_{MAX}$	**±0.5**		**±5.0**	**±0.5**		**±5.0**	mV/mA
Line Regulation (Note 3)	T_A=+25˚C	±0.01	±0.1		±0.01	±0.1		mV/V
	$4V\leq V_S\leq 30V$	**±0.02**		**±0.2**	**±0.02**		**±0.2**	mV/V
Quiescent Current (Note 9)	V_S=+5V, +25˚C	56	80		56	80		µA
	V_S=+5V	**105**		**158**	**91**		**138**	µA
	V_S=+30V, +25˚C	56.2	82		56.2	82		µA
	V_S=+30V	**105.5**		**161**	**91.5**		**141**	µA
Change of Quiescent Current (Note 3)	$4V\leq V_S\leq 30V$, +25˚C	0.2	2.0		0.2	2.0		µA
	$4V\leq V_S\leq 30V$	**0.5**		**3.0**	**0.5**		**3.0**	µA
Temperature Coefficient of Quiescent Current		**+0.39**		**+0.7**	**+0.39**		**+0.7**	µA/˚C
Minimum Temperature for Rated Accuracy	In circuit of *Figure 1*, I_L=0	+1.5		+2.0	+1.5		+2.0	˚C
Long Term Stability	$T_J=T_{MAX}$, for 1000 hours	±0.08			±0.08			˚C

Note 1: Unless otherwise noted, these specifications apply: $-55˚C\leq T_J\leq +150˚C$ for the LM35 and LM35A; $-40˚C\leq T_J\leq +110˚C$ for the LM35C and LM35CA; and $0˚C\leq T_J\leq +100˚C$ for the LM35D. V_S=+5Vdc and I_{LOAD}=50 µA, in the circuit of *Figure 2*. These specifications also apply from +2˚C to T_{MAX} in the circuit of *Figure 1*. Specifications in **boldface** apply over the full rated temperature range.

Note 2: Thermal resistance of the TO-46 package is 400˚C/W, junction to ambient, and 24˚C/W junction to case. Thermal resistance of the TO-92 package is 180˚C/W junction to ambient. Thermal resistance of the small outline molded package is 220˚C/W junction to ambient. Thermal resistance of the TO-220 package is 90˚C/W junction to ambient. For additional thermal resistance information see table in the Applications section.

Note 3: Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating effects can be computed by multiplying the internal dissipation by the thermal resistance.

Note 4: Tested Limits are guaranteed and 100% tested in production.

Note 5: Design Limits are guaranteed (but not 100% production tested) over the indicated temperature and supply voltage ranges. These limits are not used to calculate outgoing quality levels.

Note 6: Specifications in **boldface** apply over the full rated temperature range.

Note 7: Accuracy is defined as the error between the output voltage and 10mv/˚C times the device's case temperature, at specified conditions of voltage, current, and temperature (expressed in ˚C).

Note 8: Nonlinearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the device's rated temperature range.

Note 9: Quiescent current is defined in the circuit of *Figure 1*.

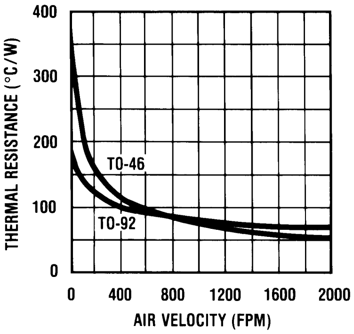
Note 10: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its rated operating conditions. See Note 1.

Note 11: Human body model, 100 pF discharged through a 1.5 kΩ resistor.

Note 12: See AN-450 "Surface Mounting Methods and Their Effect on Product Reliability" or the section titled "Surface Mount" found in a current National Semiconductor Linear Data Book for other methods of soldering surface mount devices.

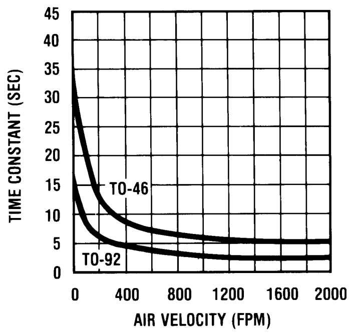
Typical Performance Characteristics

Thermal Resistance Junction to Air



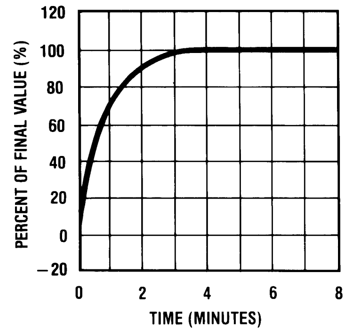
DS005516-25

Thermal Time Constant



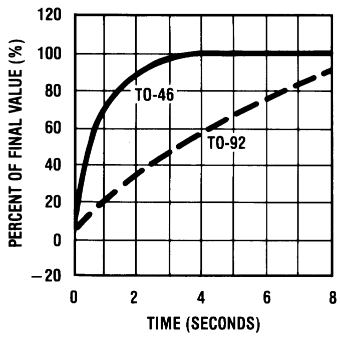
DS005516-26

Thermal Response in Still Air



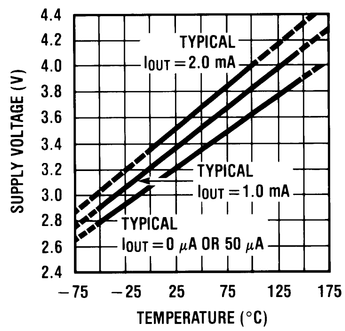
DS005516-27

Thermal Response in Stirred Oil Bath



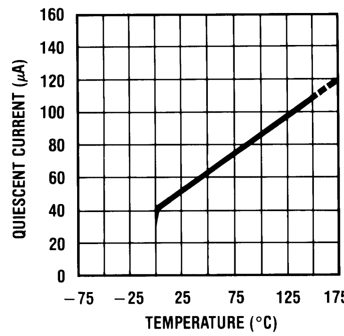
DS005516-28

Minimum Supply Voltage vs. Temperature



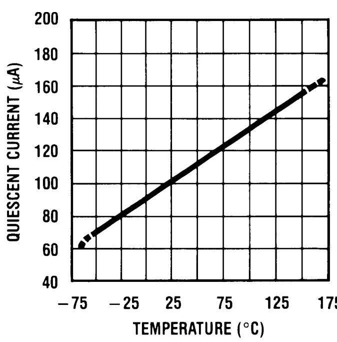
DS005516-29

Quiescent Current vs. Temperature (In Circuit of ***Figure 1*****.)**



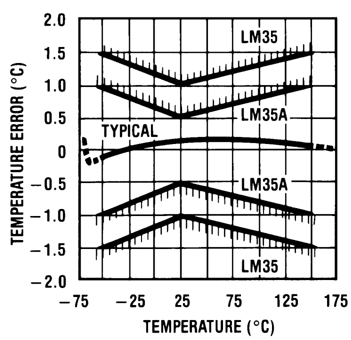
DS005516-30

Quiescent Current vs. Temperature (In Circuit of ***Figure 2*****.)**



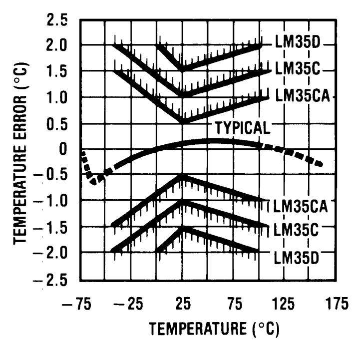
DS005516-31

Accuracy vs. Temperature (Guaranteed)



DS005516-32

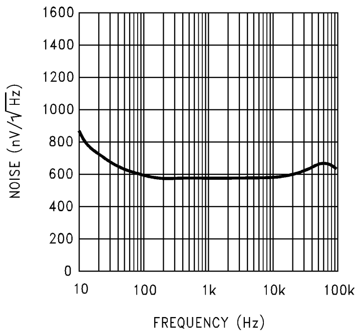
Accuracy vs. Temperature (Guaranteed)



DS005516-33

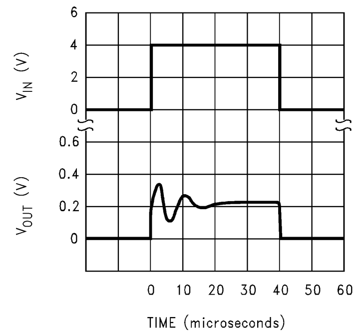
Typical Performance Characteristics (Continued)

Noise Voltage



DS005516-34

Start-Up Response



DS005516-35

Applications

The LM35 can be applied easily in the same way as other integrated-circuit temperature sensors. It can be glued or cemented to a surface and its temperature will be within about 0.01˚C of the surface temperature.

This presumes that the ambient air temperature is almost the same as the surface temperature; if the air temperature were much higher or lower than the surface temperature, the actual temperature of the LM35 die would be at an intermediate temperature between the surface temperature and the air temperature. This is expecially true for the TO-92 plastic package, where the copper leads are the principal thermal path to carry heat into the device, so its temperature might be closer to the air temperature than to the surface temperature.

To minimize this problem, be sure that the wiring to the LM35, as it leaves the device, is held at the same temperature as the surface of interest. The easiest way to do this is to cover up these wires with a bead of epoxy which will insure that the leads and wires are all at the same temperature as the surface, and that the LM35 die's temperature will not be affected by the air temperature.

The TO-46 metal package can also be soldered to a metal surface or pipe without damage. Of course, in that case the V− terminal of the circuit will be grounded to that metal. Alternatively, the LM35 can be mounted inside a sealed-end metal tube, and can then be dipped into a bath or screwed into a threaded hole in a tank. As with any IC, the LM35 and accompanying wiring and circuits must be kept insulated and dry, to avoid leakage and corrosion. This is especially true if the circuit may operate at cold temperatures where condensation can occur. Printed-circuit coatings and varnishes such as Humiseal and epoxy paints or dips are often used to insure that moisture cannot corrode the LM35 or its connections.

These devices are sometimes soldered to a small light-weight heat fin, to decrease the thermal time constant and speed up the response in slowly-moving air. On the other hand, a small thermal mass may be added to the sensor, to give the steadiest reading despite small deviations in the air temperature.

Temperature Rise of LM35 Due To Self-heating (Thermal Resistance, θ_{JA})

	TO-46, no heat sink	TO-46*, small heat fin	TO-92, no heat sink	TO-92**, small heat fin	SO-8 no heat sink	SO-8** small heat fin	TO-220 no heat sink
Still air	400˚C/W	100˚C/W	180˚C/W	140˚C/W	220˚C/W	110˚C/W	90˚C/W
Moving air	100˚C/W	40˚C/W	90˚C/W	70˚C/W	105˚C/W	90˚C/W	26˚C/W
Still oil	100˚C/W	40˚C/W	90˚C/W	70˚C/W			
Stirred oil	50˚C/W	30˚C/W	45˚C/W	40˚C/W			
(Clamped to metal, Infinite heat sink)		(24˚C/W)				(55˚C/W)	

*Wakefield type 201, or 1" disc of 0.020" sheet brass, soldered to case, or similar.
**TO-92 and SO-8 packages glued and leads soldered to 1" square of 1/16" printed circuit board with 2 oz. foil or similar.

Typical Applications

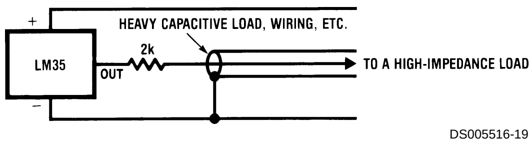


FIGURE 3. LM35 with Decoupling from Capacitive Load

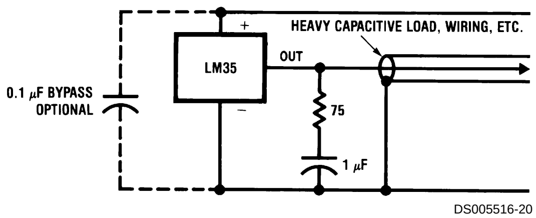


FIGURE 4. LM35 with R-C Damper

CAPACITIVE LOADS

Like most micropower circuits, the LM35 has a limited ability to drive heavy capacitive loads. The LM35 by itself is able to drive 50 pf without special precautions. If heavier loads are anticipated, it is easy to isolate or decouple the load with a resistor; see *Figure 3*. Or you can improve the tolerance of capacitance with a series R-C damper from output to ground; see *Figure 4*.

When the LM35 is applied with a 200Ω load resistor as shown in *Figure 5*, *Figure 6* or *Figure 8* it is relatively immune to wiring capacitance because the capacitance forms a bypass from ground to input, not on the output. However, as with any linear circuit connected to wires in a hostile environment, its performance can be affected adversely by intense electromagnetic sources such as relays, radio transmitters, motors with arcing brushes, SCR transients, etc, as its wiring can act as a receiving antenna and its internal junctions can act as rectifiers. For best results in such cases, a bypass capacitor from V_{IN} to ground and a series R-C damper such as 75Ω in series with 0.2 or 1 µF from output to ground are often useful. These are shown in *Figure 13*, *Figure 14*, and *Figure 16*.

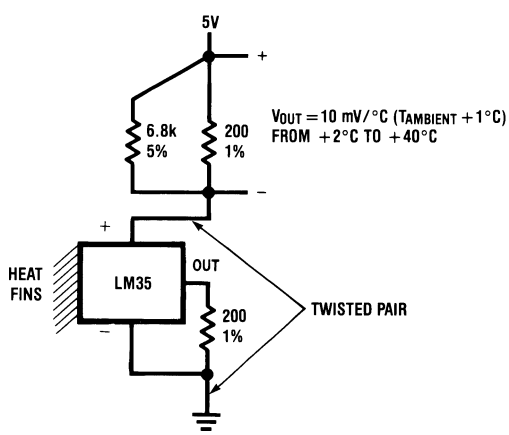


FIGURE 5. Two-Wire Remote Temperature Sensor (Grounded Sensor)

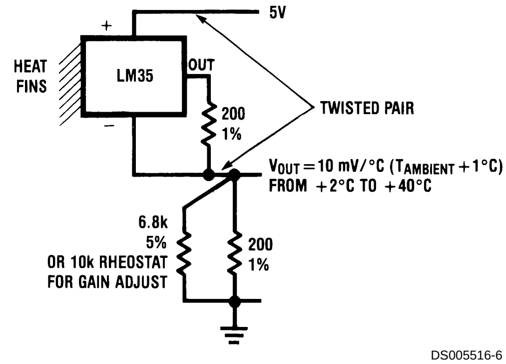


FIGURE 6. Two-Wire Remote Temperature Sensor (Output Referred to Ground)

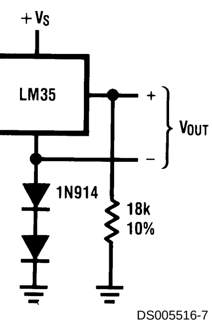


FIGURE 7. Temperature Sensor, Single Supply, −55˚ to +150˚C

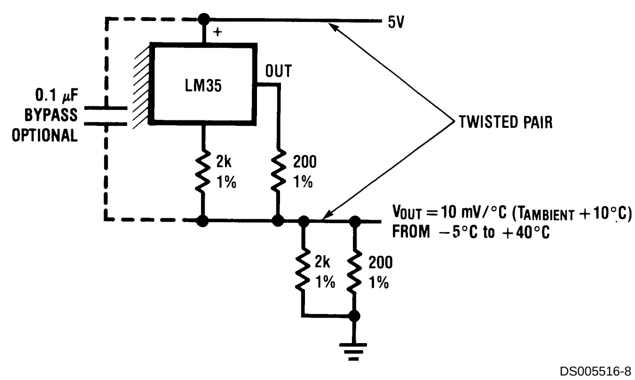


FIGURE 8. Two-Wire Remote Temperature Sensor (Output Referred to Ground)

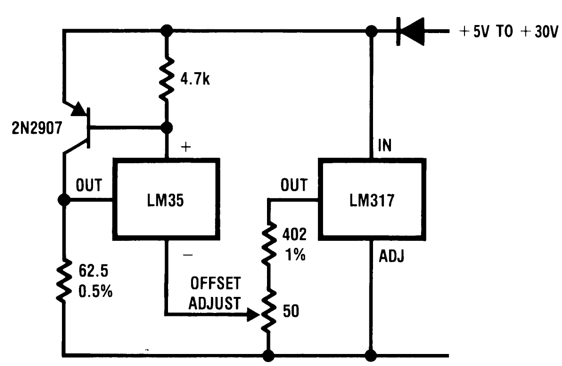


FIGURE 9. 4-To-20 mA Current Source (0˚C to +100˚C)

Typical Applications (Continued)

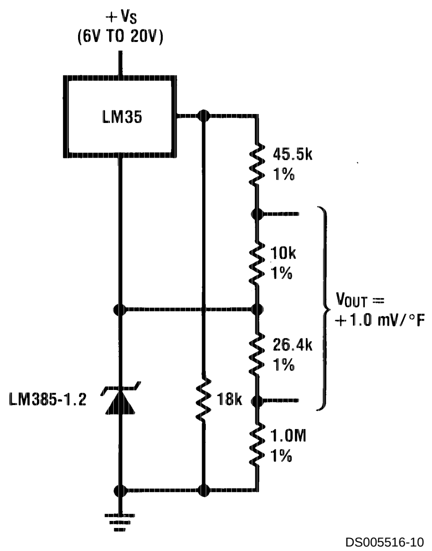


FIGURE 10. Fahrenheit Thermometer

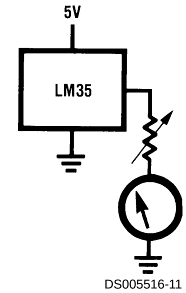


FIGURE 11. Centigrade Thermometer (Analog Meter)

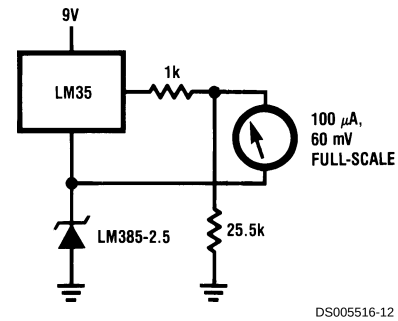


FIGURE 12. Fahrenheit ThermometerExpanded Scale Thermometer
(50˚ to 80˚ Fahrenheit, for Example Shown)

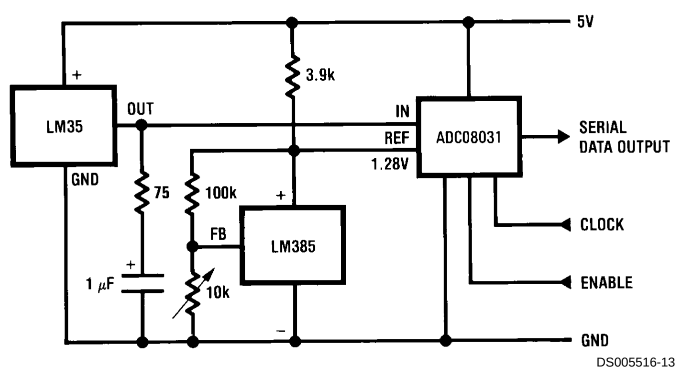


FIGURE 13. Temperature To Digital Converter (Serial Output) (+128˚C Full Scale)

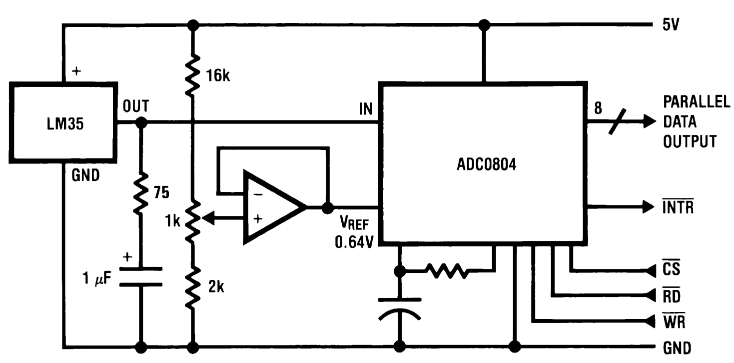
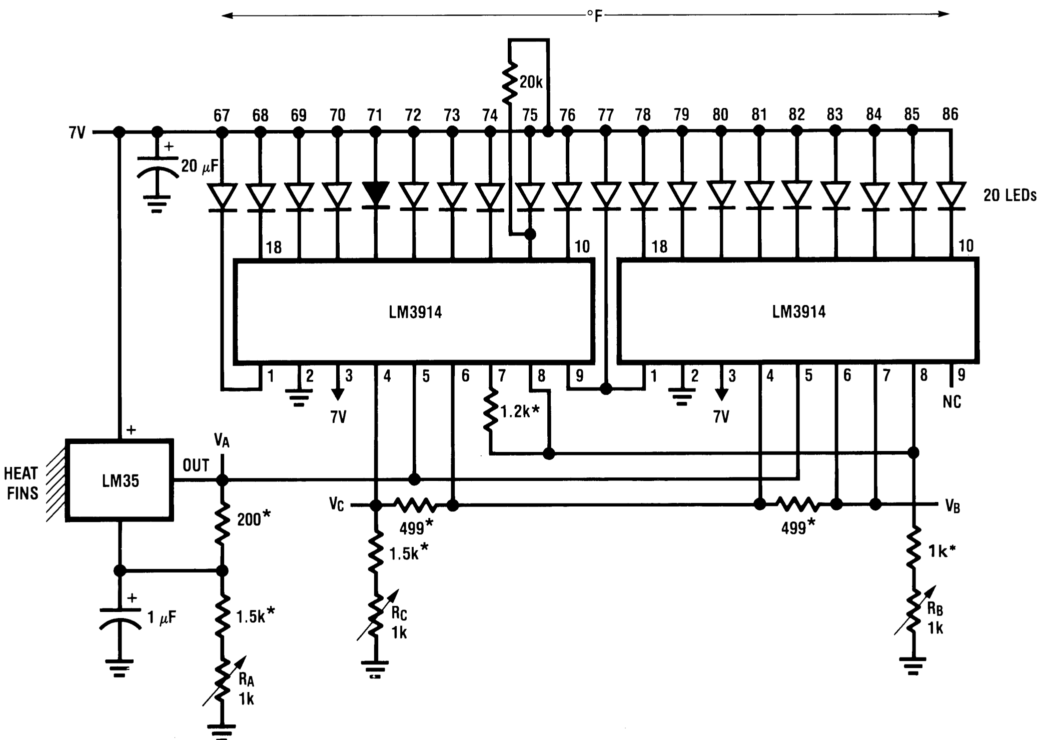


FIGURE 14. Temperature To Digital Converter (Parallel TRI-STATE™ Outputs for Standard Data Bus to µP Interface) (128˚C Full Scale)

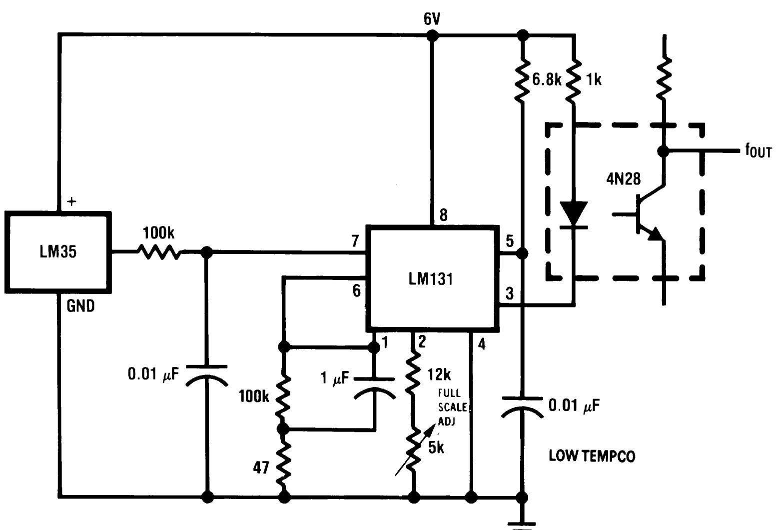
Typical Applications (Continued)



DS005516-16

*=1% or 2% film resistor
Trim R_B for V_B=3.075V
Trim R_C for V_C=1.955V
Trim R_A for V_A=0.075V + 100mV/˚C x $T_{ambient}$
Example, V_A=2.275V at 22˚C

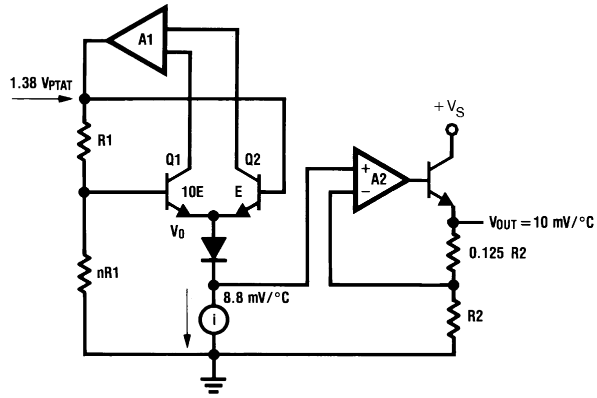
FIGURE 15. Bar-Graph Temperature Display (Dot Mode)



DS005516-15

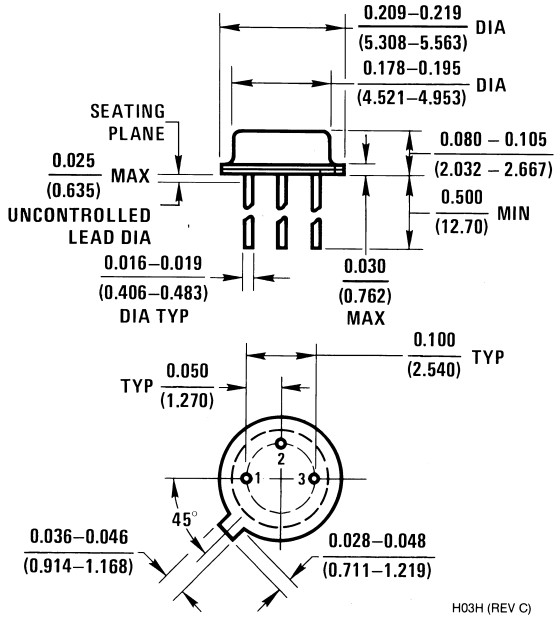
FIGURE 16. LM35 With Voltage-To-Frequency Converter And Isolated Output (2˚C to +150˚C; 20 Hz to 1500 Hz)

Block Diagram

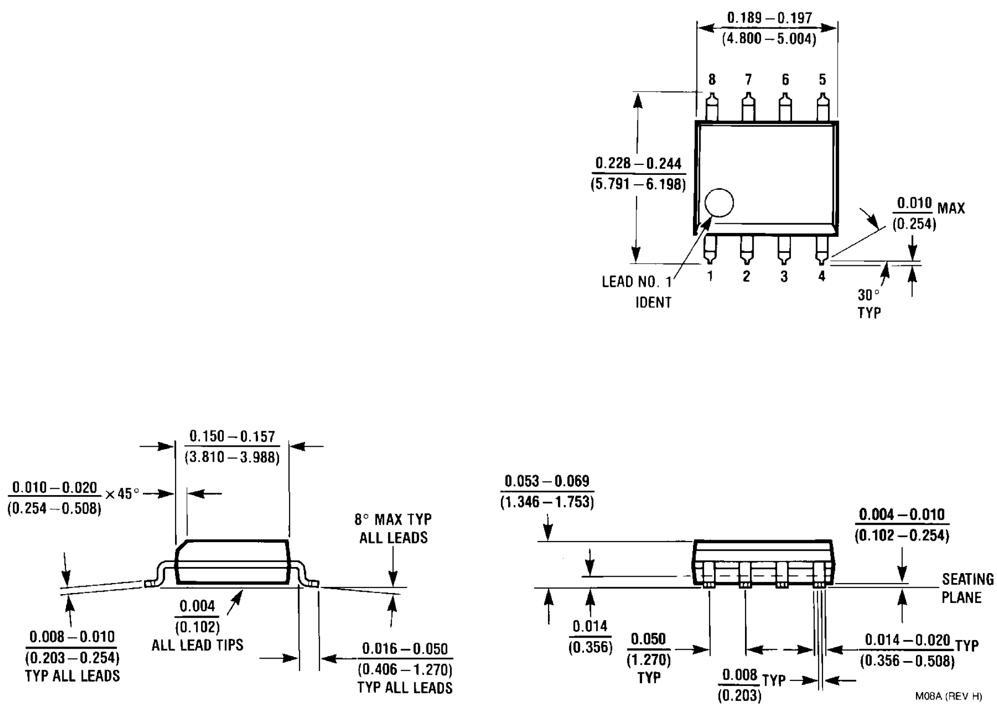


DS005516-23

Physical Dimensions inches (millimeters) unless otherwise noted

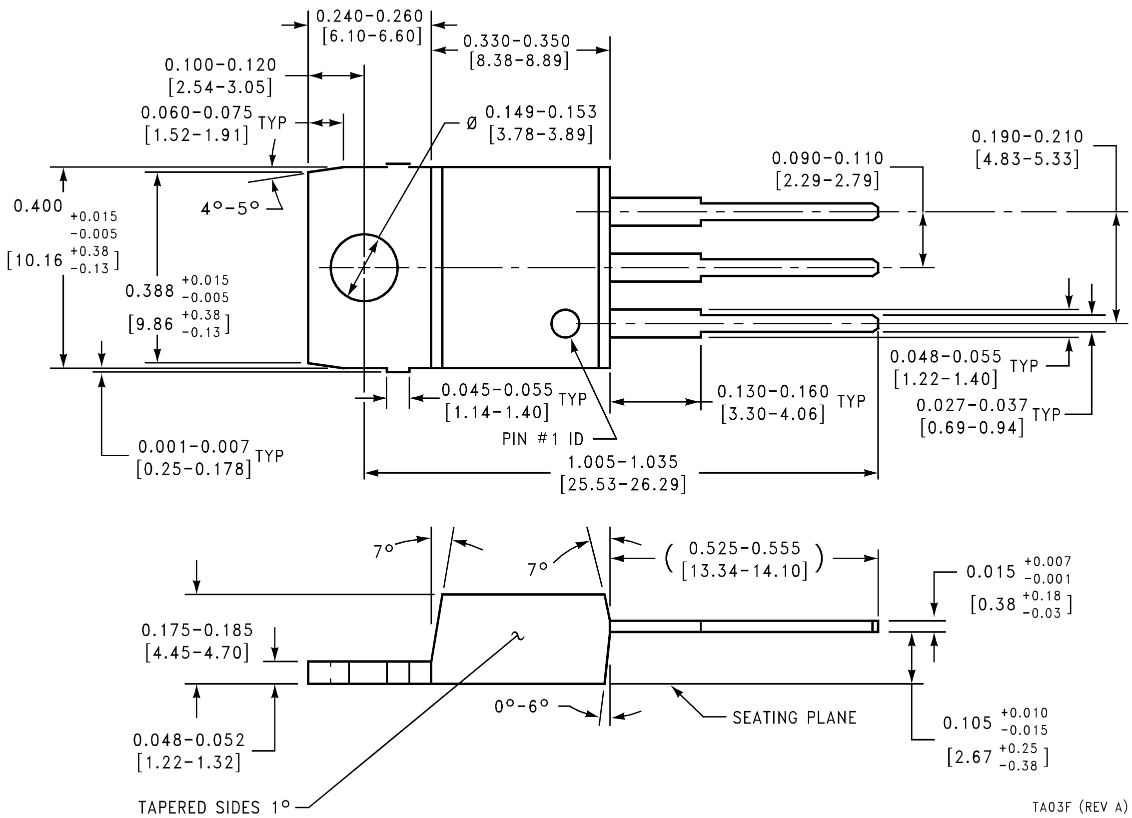


TO-46 Metal Can Package (H)
Order Number LM35H, LM35AH, LM35CH, LM35CAH, or LM35DH
NS Package Number H03H



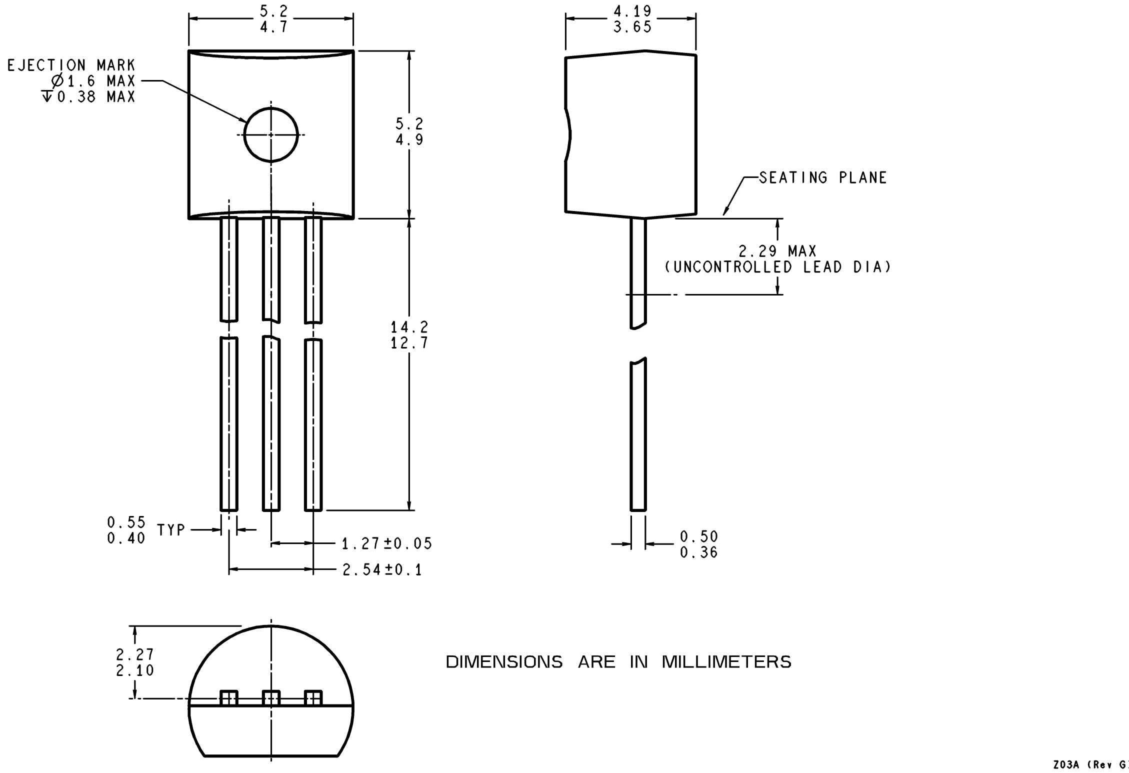
SO-8 Molded Small Outline Package (M)
Order Number LM35DM
NS Package Number M08A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



Power Package TO-220 (T)
Order Number LM35DT
NS Package Number TA03F

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



TO-92 Plastic Package (Z)
Order Number LM35CZ, LM35CAZ or LM35DZ
NS Package Number Z03A

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80×80×25 mm

San Cooler 80 9A type

General Specifications

- Material .... Frame: Plastic (Flammability: UL 94V-0), Impeller: Plastic (Flammability: UL 94V-0)
- Expected life .... See the table below. (L10 life: 90% survival rate for continuous operation in free air at 60˚C, rated voltage)
- Motor protection function .... Locked rotor burnout protection, Reverse polarity protection
For details, please refer to p. 547.
- Dielectric strength .... 50/60 Hz, 500 VAC, for 1 minute (between lead wire conductors and frame)
- Insulation resistance .... 10 MΩ or more with a 500 VDC megger (between lead wire conductors and frame)
- Sound pressure level (SPL) .... At 1 m away from the air inlet
- Storage temperature .... -30 to +70˚C (Non-condensing)
- Lead wire .... ⊕Red ⊖Black or Blue Sensor Yellow
- Mass .... 90 g

Specifications

The models listed below **have ribs and pulse sensors.** For models without ribs, append "1" to the end of model numbers.

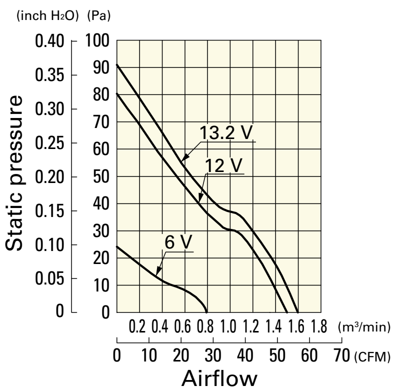
Model no.	Rated voltage [V]	Operating voltage range [V]	Rated current [A]	Rated input [W]	Rated speed [min⁻¹]	Max. airflow [m³/min]	Max. airflow [CFM]	Max. static pressure [Pa]	Max. static pressure [inchH₂O]	SPL [dB (A)]	Operating temperature [˚C]	Expected life [h]
9A0812G401	12	6 to 13.2	0.38	4.56	4500	1.5	53.0	80.3	0.323	40	-20 to +60	30000/60˚C
9A0812S401		6 to 13.8	0.18	2.16	3400	1.2	42.4	48	0.193	34	-20 to +70	40000/60˚C
9A0812H401			0.13	1.56	2900	1.03	36.4	35.3	0.142	29		
9A0812F401			0.11	1.32	2600	0.92	32.5	28.4	0.114	26		
9A0812M401			0.09	1.08	2350	0.83	29.3	22.5	0.09	23		
9A0812L401		7 to 13.8	0.06	0.72	1850	0.65	23.0	14.7	0.059	20		
9A0824G401	24	12 to 26.4	0.21	5.04	4500	1.5	53.0	80.3	0.323	40	-20 to +60	30000/60˚C
9A0824S401		12 to 27.6	0.1	2.4	3400	1.2	42.4	48	0.193	34	-20 to +70	40000/60˚C
9A0824H401			0.07	1.68	2900	1.03	36.4	35.3	0.142	29		
9A0824F401			0.06	1.44	2600	0.92	32.5	28.4	0.114	26		
9A0824M401			0.05	1.2	2350	0.83	29.3	22.5	0.09	23		
9A0824L401		14 to 27.6	0.04	0.96	1850	0.65	23.0	14.7	0.059	20		

The following sensor and control options are available for selection.
Available for all models. **Without sensor** **Lock sensor**
Differs according to the model. Refer to the table on pp. 565 to 566. **PWM control**

Airflow - Static Pressure Characteristics

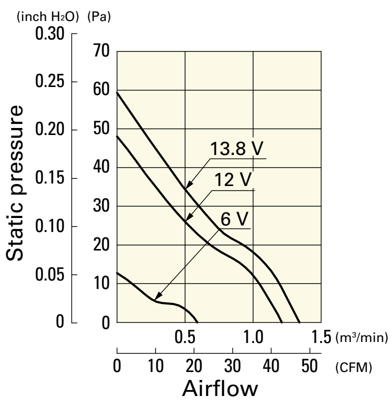
9A0812G401 With pulse sensor

Operating voltage range



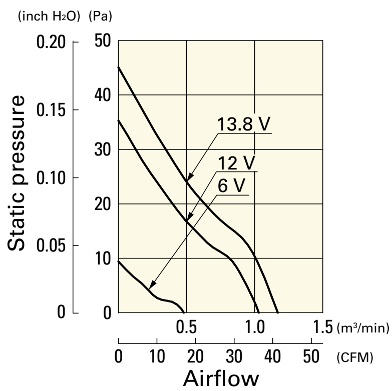
9A0812S401 With pulse sensor

Operating voltage range



9A0812H401 With pulse sensor

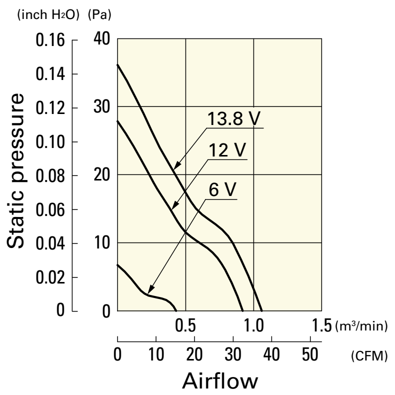
Operating voltage range



Airflow - Static Pressure Characteristics

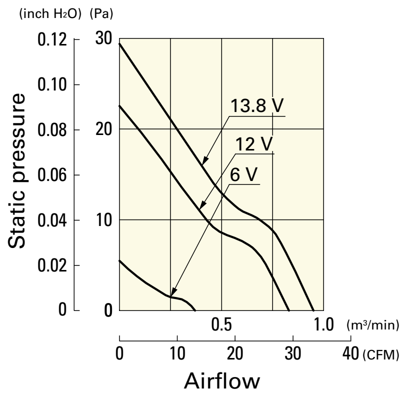
9A0812F401 With pulse sensor

Operating voltage range



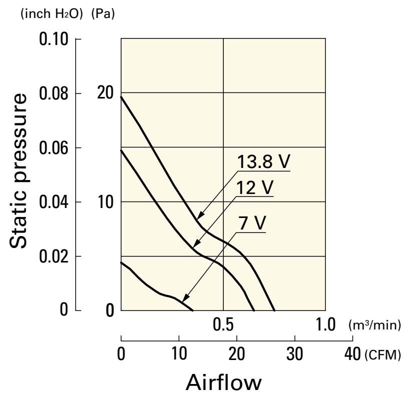
9A0812M401 With pulse sensor

Operating voltage range



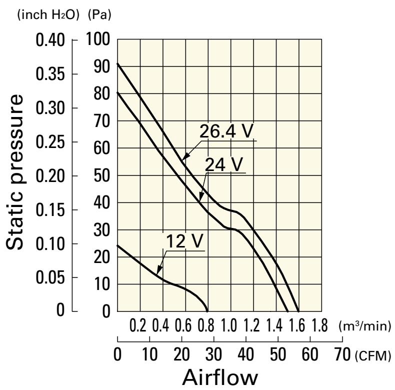
9A0812L401 With pulse sensor

Operating voltage range



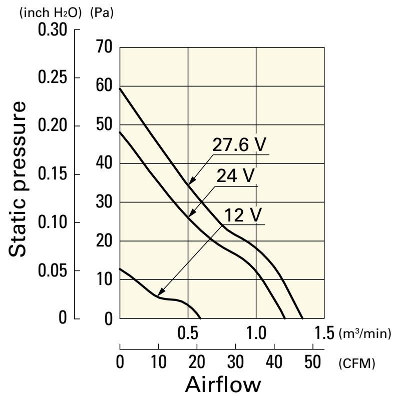
9A0824G401 With pulse sensor

Operating voltage range



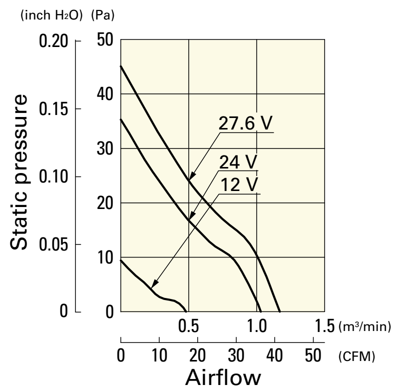
9A0824S401 With pulse sensor

Operating voltage range



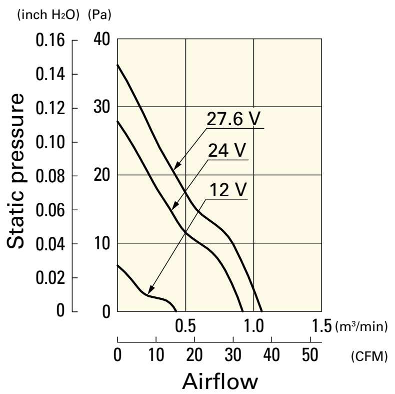
9A0824H401 With pulse sensor

Operating voltage range



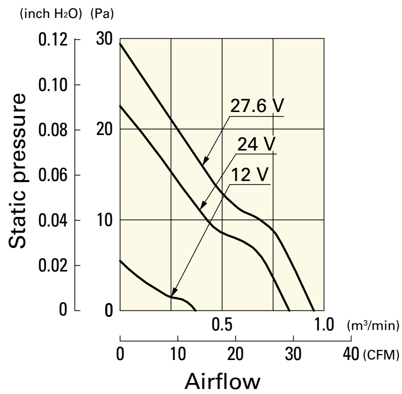
9A0824F401 With pulse sensor

Operating voltage range



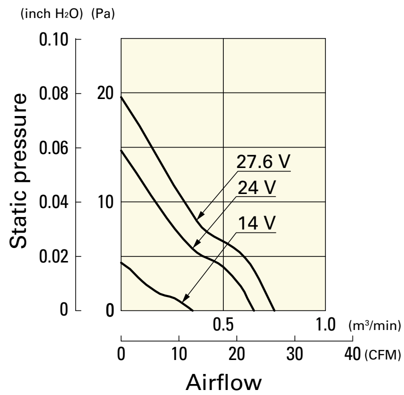
9A0824M401 With pulse sensor

Operating voltage range

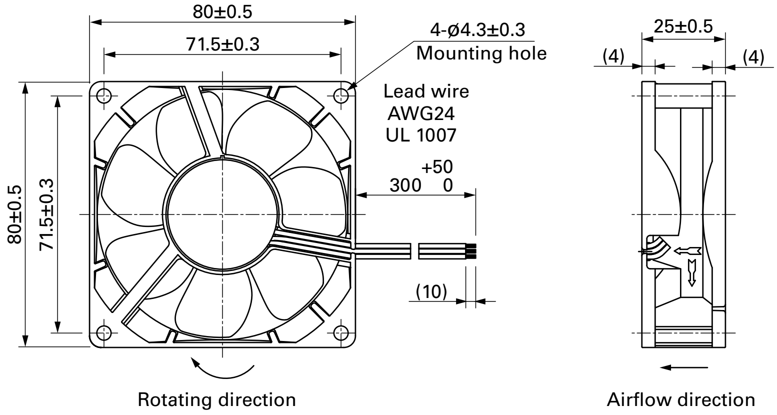


9A0824L401 With pulse sensor

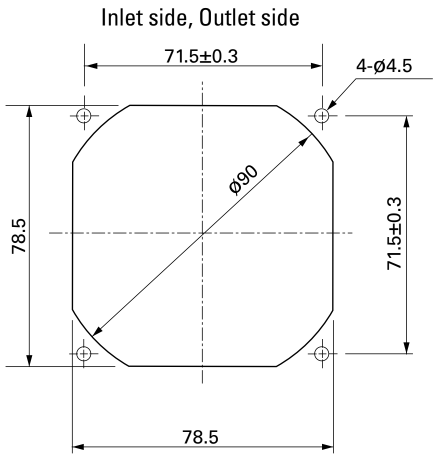
Operating voltage range



Dimensions (unit: mm) (With ribs)



Reference Dimensions of Mounting Holes and Vent Opening (unit: mm)



Options

Finger guards	page: p. 532

Model no.: 109-049E, 109-049H, 109-049C

Resin finger guards	page: p. 539

Model no.: 109-1002G

Resin filter kits	page: p. 540

Model no.: 109-1002F13 (13PPI), 109-1002F20 (20PPI), 109-1002F30 (30PPI), 109-1002F40 (40PPI)

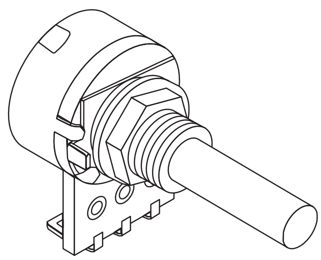
Date: 08-21-09 **Ref.#:** TW-700213

ALPHA

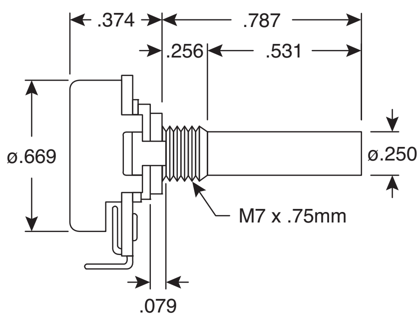
Potentiometers

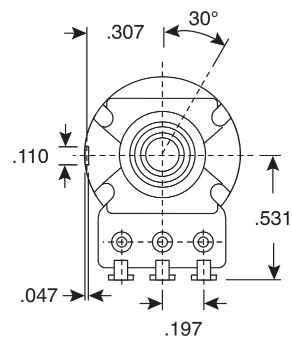
31JA301-F, 31JA302-F, 31JA305-F, 31JA401-F, 31JA405-F, 31JA501-F, 31JA505-F, 31JA601-F

Dimensions: in.
(except where noted)



RoHS Compliant





Specifications:

- Type: miniature carbon composition
- Taper: audio
- Rated wattage: .125W
- Rated voltage: 200V
- Insulation resistance: > 100MΩ @ 500VDC
- Dielectric strength: 500VAC for 1 minute
- Rotation life: 15,000 cycles
- Rotational noise: 47mV
- Total rotational angle: 300°±5°
- Rotation torque: 20 ~ 200gf. cm
- Shaft stop strength: 6Kgf. cm min.
- Tolerance: < 1MΩ±20%, ≥ 1MΩ±30%
- Shaft: zinc alloy
- Case: zinc plated steel
- RoHS Compliant

Mouser Stock No.	Value (Ω)
31JA301-F	1K
31JA302-F	2K
31JA305-F	5K
31JA401-F	10K
31JA405-F	50K
31JA501-F	100K
31JA505-F	500K
31JA601-F	1 Meg

Specifications are subject to change without notice. No liability or warranty implied by this information. Environmental compliance based on producer documentation.

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